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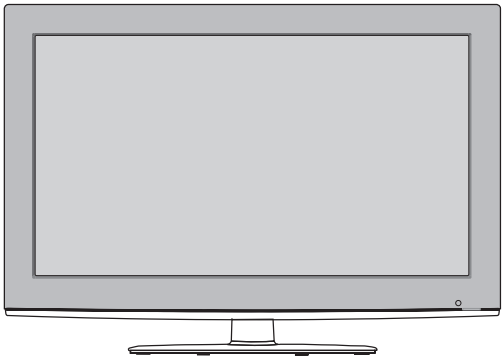
LED LCD TV
SERVICE MANUAL

CHASSIS : LB01U

MODEL : 32LV3300 32LV3300-TA

CAUTION
BEFORE SERVICING THE CHASSIS,
READ THE SAFETY PRECAUTIONS IN THIS MANUAL.



P/NO : MFL62461539 (1111-REV00)

Printed in Korea

CONTENTS

SAFETY PRECAUTIONS

IMPORTANT SAFETY NOTICE

Many electrical and mechanical parts in this chassis have special safety-related characteristics. These parts are identified by ⚠ in the Schematic Diagram and Exploded View.
It is essential that these special safety parts should be replaced with the same components as recommended in this manual to prevent Shock, Fire, or other Hazards.
Do not modify the original design without permission of manufacturer.

General Guidance

An **isolation Transformer should always be used** during the servicing of a receiver whose chassis is not isolated from the AC power line. Use a transformer of adequate power rating as this protects the technician from accidents resulting in personal injury from electrical shocks.

It will also protect the receiver and it's components from being damaged by accidental shorts of the circuitry that may be inadvertently introduced during the service operation.

If any fuse (or Fusible Resistor) in this TV receiver is blown, replace it with the specified.

When replacing a high wattage resistor (Oxide Metal Film Resistor, over 1 W), keep the resistor 10 mm away from PCB.

Keep wires away from high voltage or high temperature parts.

Before returning the receiver to the customer,

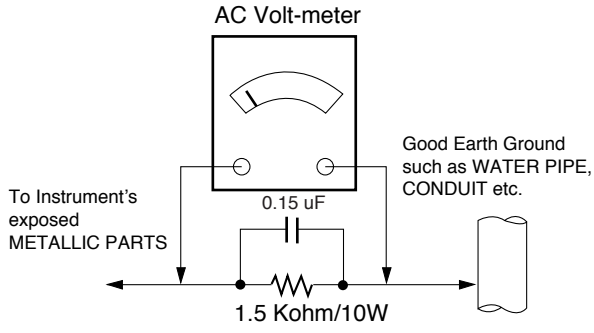
always perform an **AC leakage current check** on the exposed metallic parts of the cabinet, such as antennas, terminals, etc., to be sure the set is safe to operate without damage of electrical shock.

Leakage Current Cold Check(Antenna Cold Check)
With the instrument AC plug removed from AC source, connect an electrical jumper across the two AC plug prongs. Place the AC switch in the on position, connect one lead of ohm-meter to the AC plug prongs tied together and touch other ohm-meter lead in turn to each exposed metallic parts such as antenna terminals, phone jacks, etc.
If the exposed metallic part has a return path to the chassis, the measured resistance should be between 1 MΩ and 5.2 MΩ.
When the exposed metal has no return path to the chassis the reading must be infinite.
An other abnormality exists that must be corrected before the receiver is returned to the customer.

Leakage Current Hot Check (See below Figure)
Plug the AC cord directly into the AC outlet.

Do not use a line Isolation Transformer during this check.
Connect 1.5 K / 10 watt resistor in parallel with a 0.15 uF capacitor between a known good earth ground (Water Pipe, Conduit, etc.) and the exposed metallic parts.
Measure the AC voltage across the resistor using AC voltmeter with 1000 ohms/volt or more sensitivity.
Reverse plug the AC cord into the AC outlet and repeat AC voltage measurements for each exposed metallic part. Any voltage measured must not exceed 0.75 volt RMS which is corresponds to 0.5 mA.
In case any measurement is out of the limits specified, there is possibility of shock hazard and the set must be checked and repaired before it is returned to the customer.

Leakage Current Hot Check circuit



When 25A is impressed between Earth and 2nd Ground for 1 second, Resistance must be less than 0.1 Ω
*Base on Adjustment standard

SERVICING PRECAUTIONS

CAUTION: Before servicing receivers covered by this service manual and its supplements and addenda, read and follow the *SAFETY PRECAUTIONS* on page 3 of this publication.
NOTE: If unforeseen circumstances create conflict between the following servicing precautions and any of the safety precautions on page 3 of this publication, always follow the safety precautions. Remember: Safety First.

General Servicing Precautions

1. Always unplug the receiver AC power cord from the AC power source before;
   a. Removing or reinstalling any component, circuit board module or any other receiver assembly.
   b. Disconnecting or reconnecting any receiver electrical plug or other electrical connection.
   c. Connecting a test substitute in parallel with an electrolytic capacitor in the receiver.
   CAUTION: A wrong part substitution or incorrect polarity installation of electrolytic capacitors may result in an explosion hazard.

2. Test high voltage only by measuring it with an appropriate high voltage meter or other voltage measuring device (DVM, FETVOM, etc) equipped with a suitable high voltage probe.
   Do not test high voltage by "drawing an arc".
3. Do not spray chemicals on or near this receiver or any of its assemblies.
4. Unless specified otherwise in this service manual, clean electrical contacts only by applying the following mixture to the contacts with a pipe cleaner, cotton-tipped stick or comparable non-abrasive applicator; 10 % (by volume) Acetone and 90 % (by volume) isopropyl alcohol (90 % - 99 % strength)
   CAUTION: This is a flammable mixture.
   Unless specified otherwise in this service manual, lubrication of contacts in not required.
5. Do not defeat any plug/socket B+ voltage interlocks with which receivers covered by this service manual might be equipped.
6. Do not apply AC power to this instrument and/or any of its electrical assemblies unless all solid-state device heat sinks are correctly installed.
7. Always connect the test receiver ground lead to the receiver chassis ground before connecting the test receiver positive lead.
   Always remove the test receiver ground lead last.
8. *Use with this receiver only the test fixtures specified in this service manual.*
   CAUTION: Do not connect the test fixture ground strap to any heat sink in this receiver.

Electrostatically Sensitive (ES) Devices

Some semiconductor (solid-state) devices can be damaged easily by static electricity. Such components commonly are called *Electrostatically Sensitive (ES) Devices*. Examples of typical ES devices are integrated circuits and some field-effect transistors and semiconductor "chip" components. The following techniques should be used to help reduce the incidence of component damage caused by static by static electricity.

1. Immediately before handling any semiconductor component or semiconductor-equipped assembly, drain off any electrostatic charge on your body by touching a known earth ground. Alternatively, obtain and wear a commercially available discharging wrist strap device, which should be removed to prevent potential shock reasons prior to applying power to the unit under test.
2. After removing an electrical assembly equipped with ES devices, place the assembly on a conductive surface such as aluminum foil, to prevent electrostatic charge buildup or exposure of the assembly.
3. Use only a grounded-tip soldering iron to solder or unsolder ES devices.
4. Use only an anti-static type solder removal device. Some solder removal devices not classified as "anti-static" can generate electrical charges sufficient to damage ES devices.
5. Do not use freon-propelled chemicals. These can generate electrical charges sufficient to damage ES devices.
6. Do not remove a replacement ES device from its protective package until immediately before you are ready to install it. (Most replacement ES devices are packaged with leads electrically shorted together by conductive foam, aluminum foil or comparable conductive material).
7. Immediately before removing the protective material from the leads of a replacement ES device, touch the protective material to the chassis or circuit assembly into which the device will be installed.
   CAUTION: Be sure no power is applied to the chassis or circuit, and observe all other safety precautions.
8. Minimize bodily motions when handling unpackaged replacement ES devices. (Otherwise harmless motion such as the brushing together of your clothes fabric or the lifting of your foot from a carpeted floor can generate static electricity sufficient to damage an ES device.)

General Soldering Guidelines

1. Use a grounded-tip, low-wattage soldering iron and appropriate tip size and shape that will maintain tip temperature within the range or 500 °F to 600 °F.
2. Use an appropriate gauge of RMA resin-core solder composed of 60 parts tin/40 parts lead.
3. Keep the soldering iron tip clean and well tinned.
4. Thoroughly clean the surfaces to be soldered. Use a mall wire-bristle (0.5 inch, or 1.25 cm) brush with a metal handle.
   Do not use freon-propelled spray-on cleaners.
5. Use the following unsoldering technique
   a. Allow the soldering iron tip to reach normal temperature. (500 °F to 600 °F)
   b. Heat the component lead until the solder melts.
   c. Quickly draw the melted solder with an anti-static, suction-type solder removal device or with solder braid.
   CAUTION: Work quickly to avoid overheating the circuit board printed foil.
6. Use the following soldering technique.
   a. Allow the soldering iron tip to reach a normal temperature (500 °F to 600 °F)
   b. First, hold the soldering iron tip and solder the strand against the component lead until the solder melts.
   c. Quickly move the soldering iron tip to the junction of the component lead and the printed circuit foil, and hold it there only until the solder flows onto and around both the component lead and the foil.
   CAUTION: Work quickly to avoid overheating the circuit board printed foil.
   d. Closely inspect the solder area and remove any excess or splashed solder with a small wire-bristle brush.

IC Remove/Replacement

Some chassis circuit boards have slotted holes (oblong) through which the IC leads are inserted and then bent flat against the circuit foil. When holes are the slotted type, the following technique should be used to remove and replace the IC. When working with boards using the familiar round hole, use the standard technique as outlined in paragraphs 5 and 6 above.

Removal

1. Desolder and straighten each IC lead in one operation by gently prying up on the lead with the soldering iron tip as the solder melts.
2. Draw away the melted solder with an anti-static suction-type solder removal device (or with solder braid) before removing the IC.

Replacement

1. Carefully insert the replacement IC in the circuit board.
2. Carefully bend each IC lead against the circuit foil pad and solder it.
3. Clean the soldered areas with a small wire-bristle brush. (It is not necessary to reapply acrylic coating to the areas).

"Small-Signal" Discrete Transistor Removal/Replacement

1. Remove the defective transistor by clipping its leads as close as possible to the component body.
2. Bend into a "U" shape the end of each of three leads remaining on the circuit board.
3. Bend into a "U" shape the replacement transistor leads.
4. Connect the replacement transistor leads to the corresponding leads extending from the circuit board and crimp the "U" with long nose pliers to insure metal to metal contact then solder each connection.

Power Output, Transistor Device Removal/Replacement

1. Heat and remove all solder from around the transistor leads.
2. Remove the heat sink mounting screw (if so equipped).
3. Carefully remove the transistor from the heat sink of the circuit board.
4. Insert new transistor in the circuit board.
5. Solder each transistor lead, and clip off excess lead.
6. Replace heat sink.

Diode Removal/Replacement

1. Remove defective diode by clipping its leads as close as possible to diode body.
2. Bend the two remaining leads perpendicular y to the circuit board.
3. Observing diode polarity, wrap each lead of the new diode around the corresponding lead on the circuit board.
4. Securely crimp each connection and solder it.
5. Inspect (on the circuit board copper side) the solder joints of the two "original" leads. If they are not shiny, reheat them and if necessary, apply additional solder.

Fuse and Conventional Resistor

Removal/Replacement

1. Clip each fuse or resistor lead at top of the circuit board hollow stake.
2. Securely crimp the leads of replacement component around notch at stake top.
3. Solder the connections.
   CAUTION: Maintain original spacing between the replaced component and adjacent components and the circuit board to prevent excessive component temperatures.

Circuit Board Foil Repair

Excessive heat applied to the copper foil of any printed circuit board will weaken the adhesive that bonds the foil to the circuit board causing the foil to separate from or "lift-off" the board. The following guidelines and procedures should be followed whenever this condition is encountered.

At IC Connections

To repair a defective copper pattern at IC connections use the following procedure to install a jumper wire on the copper pattern side of the circuit board. (Use this technique only on IC connections).

1. Carefully remove the damaged copper pattern with a sharp knife. (Remove only as much copper as absolutely necessary).
2. carefully scratch away the solder resist and acrylic coating (if used) from the end of the remaining copper pattern.
3. Bend a small "U" in one end of a small gauge jumper wire and carefully crimp it around the IC pin. Solder the IC connection.
4. Route the jumper wire along the path of the out-away copper pattern and let it overlap the previously scraped end of the good copper pattern. Solder the overlapped area and clip off any excess jumper wire.

At Other Connections

Use the following technique to repair the defective copper pattern at connections other than IC Pins. This technique involves the installation of a jumper wire on the component side of the circuit board.

1. Remove the defective copper pattern with a sharp knife. Remove at least 1/4 inch of copper, to ensure that a hazardous condition will not exist if the jumper wire opens.
2. Trace along the copper pattern from both sides of the pattern break and locate the nearest component that is directly connected to the affected copper pattern.
3. Connect insulated 20-gauge jumper wire from the lead of the nearest component on one side of the pattern break to the lead of the nearest component on the other side. Carefully crimp and solder the connections.
   CAUTION: Be sure the insulated jumper wire is dressed so the it does not touch components or sharp edges.

SPECIFICATION

NOTE : Specifications and others are subject to change without notice for improvement.

1. Application range

This specification is applied to the LCD TV used LB01U chassis.

2. Requirement for Test

Each part is tested as below without special appointment.

1) Temperature: 25 ºC ± 5 ºC(77 ºF ± 9 ºF), CST: 40 ºC ± 5 ºC
2) Relative Humidity : 65 % ± 10 %
3) Power Voltage
   : Standard input voltage (AC 100-240 V~, 50 / 60 Hz)
   * Standard Voltage of each products is marked by models.
4) Specification and performance of each parts are followed each drawing and specification by part number in accordance with BOM.
5) The receiver must be operated for about 5 minutes prior to the adjustment.

3. Test method

1) Performance: LGE TV test method followed
2) Demanded other specification
   - Safety: CE, IEC specification
   - EMC:CE, IEC

4. Model General Specification

No.	Item	Specification	Remarks
1.	Market	Australia, NewZealand, Singapore, Malaysia, Vietnam,Indonesia,South Africa, Israel, A-ASIA	only Analog for A-ASIA
2.	Broadcasting system	1) PAL/SECAM-B/G/D/K 2) PAL-I/II 3) NTSC-M 4) DVB-T	PAL for NZ/SG
3.	Receiving system	Analog : Upper Heterodyne Digital : COFDM(DVB-T)	► DVB-T - Guard Interval(Bitrate_Mbit/s) 1/4, 1/8, 1/16, 1/32 - Modulation : Code Rate QPSK : 1/2, 2/3, 3/4, 5/6, 7/8 16-QAM : 1/2, 2/3, 3/4, 5/6, 7/8 64-QAM : 1/2, 2/3, 3/4, 5/6, 7/8
4.	Video Input RCA	PAL, SECAM, NTSC	4 System : PAL, SECAM, NTSC, PAL60
5.	Component Input	Y/Cb/Cr, Y/Pb/Pr	
6.	RGB Input (1EA)	RGB-PC	Analog(D-SUB 15PIN)
7.	HDMI Input	HDMI1-DTV/DVI HDMI2-DTV/DVI HDMI3-DTV/DVI	PC - HD Model : HDMI version 1.3 - FHD Model : HDMI version 1.4 Support HDCP
8.	Audio Input	RGB/DVI Audio Component AV	
9.	SDPIF out	SPDIF out	
10.	USB	For My Media(Movie/Photo/Music List) or For SVC	

5. Component Video Input (Y, P_B, P_R)

No.	Specification				Remark
	Resolution	H-freq(kHz)	V-freq(Hz)		
1.	720x480	15.73	60.00	SDTV,DVD 480i	
2.	720x480	15.63	59.94	SDTV,DVD 480i	
3.	720x480	31.47	59.94	480p	
4.	720x480	31.50	60.00	480p	
5.	720x576	15.625	50.00	SDTV,DVD 625 Line	
6.	720x576	31.25	50.00	HDTV 576p	
7.	1280x720	45.00	50.00	HDTV 720p	
8.	1280x720	44.96	59.94	HDTV 720p	
9.	1280x720	45.00	60.00	HDTV 720p	
10.	1920x1080	31.25	50.00	HDTV 1080i	
11.	1920x1080	33.75	60.00	HDTV 1080i	
12.	1920x1080	33.72	59.94	HDTV 1080i	
13.	1920x1080	56.250	50	HDTV 1080p	
14.	1920x1080	67.5	60	HDTV 1080p	

6. RGB Input (PC)

No.	Specification				Proposed	Remark
	Resolution	H-freq(kHz)	V-freq(Hz)	Pixel Clock(MHz)		
1.	720*400	31.468	70.08	28.321		For only DOS mode
2.	640*480	31.469	59.94	25.17	VESA	Input 848*480 60 Hz, 852*480 60 Hz -> 640*480 60 Hz Display
3.	800*600	37.879	60.31	40.00	VESA	
4.	1024*768	48.363	60.00	65.00	VESA(XGA)	
5.	1280*768	47.78	59.87	79.5	WXGA	
6.	1360*768	47.72	59.8	84.75	WXGA	
7.	1280*1024	63.981	60.02	108.875	SXGA	FHD Model
8.	1920*1080	66.587	59.93	138.625	WUXGA	FHD model

7. HDMI Input

(1) DTV Mode

No.	Resolution	H-freq(kHz)	V-freq.(Hz)	Pixel clock(MHz)	Proposed	Remark
1.	720*480	31.469/31.5	59.94/60	27.00/27.03	SDTV 480P	
2.	720*576	31.25	50	54	SDTV 576P	
3.	1280*720	37.500	50	74.25	HDTV 720P	
4.	1280*720	44.96/45	59.94/60	74.17/74.25	HDTV 720P	
5.	1920*1080	33.72/33.75	59.94/60	74.17/74.25	HDTV 1080I	
6.	1920*1080	28.125	50.00	74.25	HDTV 1080I	
7.	1920*1080	26.97/27	23.97/24	74.17/74.25	HDTV 1080P	
8.	1920*1080	33.716/33.75	29.976/30.00	74.25	HDTV 1080P	
9.	1920*1080	56.250	50	148.5	HDTV 1080P	
10.	1920*1080	67.43/67.5	59.94 /60	148.35/148.50	HDTV 1080P	

(2) PC Mode

No.	Resolution	H-freq(kHz)	V-freq.(Hz)	Pixel clock(MHz)	Proposed	Remark
1.	720*400	31.468	70.08	28.321		HDCP
2.	640*480	31.469	59.94	25.17	VESA	HDCP
3.	800*600	37.879	60.31	40.00	VESA	HDCP
4.	1024*768	48.363	60.00	65.00	VESA(XGA)	HDCP
5.	1360*768	47.72	59.8	84.75	WXGA	HDCP
6.	1280*1024	63.981	60.02	108.875	SXGA	HDCP/FHD model
7.	1920*1080	67.5	60	138.5	WUXGA	HDCP/FHD model

ADJUSTMENT INSTRUCTION

1. Application Range

This specification sheet is applied to all of the LCD TV with LB01U chassis.

2. Designation

1) The adjustment is according to the order which is designated and which must be followed, according to the plan which can be changed only on agreeing.
2) Power Adjustment: Free Voltage
3) Magnetic Field Condition: Nil.
4) Input signal Unit: Product Specification Standard
5) Reserve after operation: Above 5 Minutes (Heat Run)
   Temperature : at 25 ºC ± 5 ºC
   Relative humidity : 65 % ± 10 %
   Input voltage : 220 V, 60 Hz
6) Adjustment equipments: Color Analyzer(CA-210 or CA-110), DDC Adjustment Jig equipment, Service remote control.
7) Push the “IN STOP” key - For memory initialization.

Case1 : Software version up
1. After downloading S/W by USB, TV set will reboot automatically
2. Push “In-stop” key
3. Push “Power on” key
4. Function inspection
5. After function inspection, Push “In-stop” key.

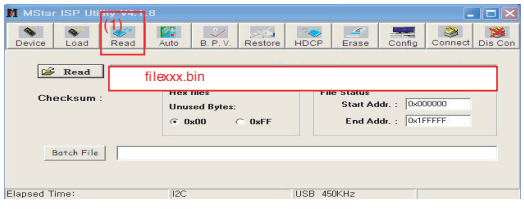
Case2 : Function check at the assembly line
1. When TV set is entering on the assembly line, Push “In-stop” key at first.
2. Push “Power on” key for turning it on.
   -> If you push “Power on” key, TV set will recover channel information by itself.
3. After function inspection, Push “In-stop” key.

3. Main PCB check process

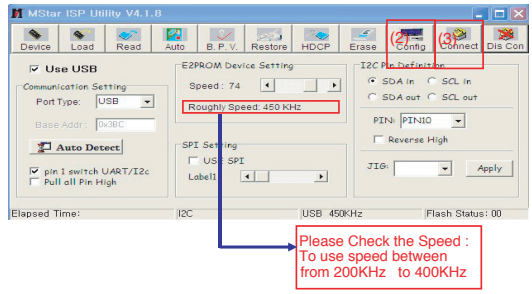
* APC - After Manual-Insert, executing APC

* Boot file Download

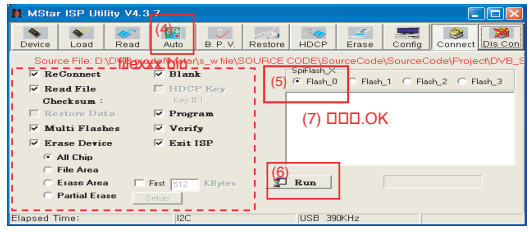
1) Execute ISP program “Mstar ISP Utility” and then click “Config” tab.



2) Set as below, and then click “Auto Detect” and check “OK” message.
   If “Error” is displayed, Check connection between computer, jig, and set.
3) Click “Read” tab, and then load download file(XXXX.bin) by clicking “Read”.
4) Click “Connect” tab. If “Can’t” is displayed, check connection between computer, jig, and set.

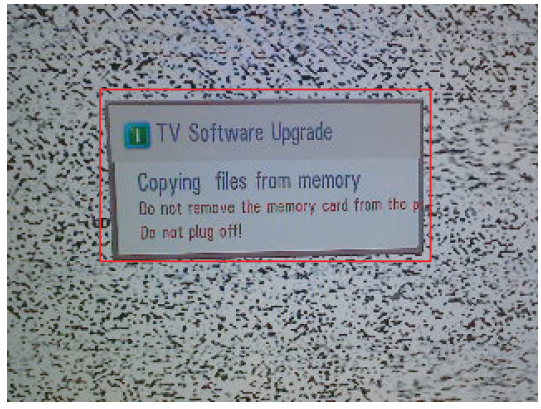


5) Click “Auto” tab and set as below.
6) Click “Run”.
7) After downloading, check “OK” message.

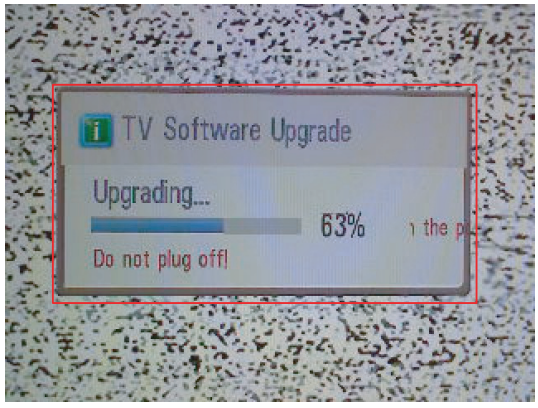


* USB DOWNLOAD

1) Put the USB Stick to the USB socket.
2) Automatically detecting update file in USB Stick.
   - If your downloaded program version in USB Stick is Low, it didn’t work. But your downloaded version is High, USB data is automatically detecting.
3) Show the message “Copying files from memory”.



4) Updating is starting.



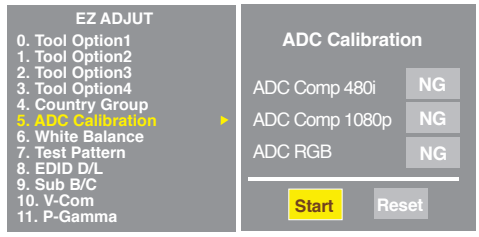
5) Uploading completed, the TV will restart automatically.
6) If your TV is turned on, check your updated version and Tool option.(explain the Tool option, next stage)
   * If downloading version is more high than your TV have, TV can lost all channel data. In this case, you have to channel recover. if all channel data is cleared, you didn't have a DTV/ATV test on production line.

*** After downloading, have to adjust Tool Option again.**

1) Push "IN-START" key in service remote control.
2) Select "Tool Option 1" and Push "OK" ok.
3) Punch in the number. (Each model has their number)

3.1. ADC Process

(1) ADC
- Enter Service Mode by pushing "ADJ" key,
- Enter Internal ADC mode by pushing "▶" key at "5. ADC Calibration".



<Caution> Using 'power on' key of the Adjustment remote control, power on TV.

* ADC Calibration Protocol (RS232)

No	Item	CMD1	CMD2	Data0		
Enter Adjust Mode	Adjust 'Mode In'	A	A	0	0	When transfer the 'Mode In', Carry the command.
ADC adjust	ADC Adjust	A	D	1	0	Automatically adjustment (The use of a internal pattern)

Adjust Sequence
- aa 00 00 [Enter Adjust Mode]
- xb 00 40 [Component1 Input (480i)]
- ad 00 10 [Adjust 480i Comp1]
- xb 00 60 [RGB Input (1024*768)]
- ad 00 10 [Adjust 1024*768 RGB]
- aa 00 90 End Adjust mode

* Required equipment : Adjustment remote control.

3.2. Function Check

* Check display and sound
- Check Input and Signal items. (cf. work instructions)
  1) TV
  2) AV (SCART1/SCART2/ CVBS)
  3) COMPONENT (480i)
  4) RGB (PC : 1024 x 768 @ 60hz)
  5) HDMI
  6) PC Audio In
  * Display and Sound check is executed by Remote control.

4. Total Assembly line process

4.1. Adjustment Preparation

· W/B Equipment condition
CA210
: CCFL/EEFL -> CH9, Test signal: Inner pattern(80IRE)
LED -> CH14, Test signal: Inner pattern(80IRE)

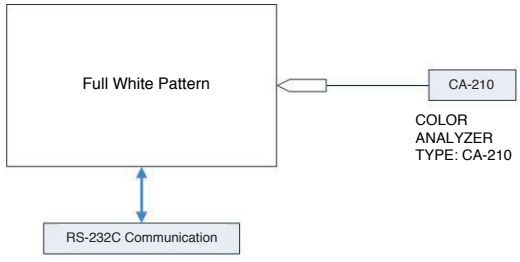
· Above 5 minutes H/run in the inner pattern. (“power on” key of adjustment remote control)

Cool	13,000	K	X=0.269(±0.002)	<Test Signal> Inner pattern (204gray,80IRE)
			Y=0.273(±0.002)	
Medium	9,300	K	X=0.285(±0.002)	
			Y=0.293(±0.002)	
Warm	6,500	K	X=0.313(±0.002)	
			Y=0.329(±0.002)	

· Edge LED W/B Table is process of aging time (Only LGD Edge LED Module except AUO, CMI, IPS Module)

GP2R	Aging Time (Min.)	Cool		Medium		Warm	
		X	Y	X	Y	X	Y
		269	273	285	293	313	329
1	0-2	279	288	295	308	319	338
2	3-5	278	286	294	306	318	336
3	6-9	277	285	293	305	317	335
4	10-19	276	283	292	303	316	333
5	20-35	274	280	290	300	314	330
6	36-49	272	277	288	297	312	327
7	50-79	271	275	287	295	311	325
8	80-149	270	274	286	294	310	324
9	Over 150	269	273	285	293	309	323

* Connecting picture of the measuring instrument
(On Automatic control)
Inside PATTERN is used when W/B is controlled. Connect to auto controller or push Adjustment remote control POWER ON -> Enter the mode of White-Balance, the pattern will come out.



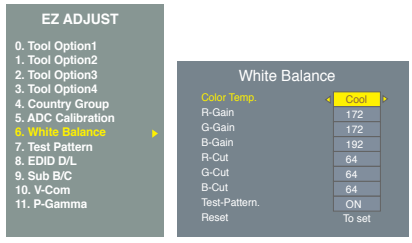
* Auto-control interface and directions
1) Adjust in the place where the influx of light like floodlight around is blocked. (illumination is less than 10 lux).
2) Adhere closely the Color Analyzer (CA210) to the module less than 10 cm distance, keep it with the surface of the Module and Color Analyzer’s prove vertically.(80° ~ 100°).
3) Aging time
- After aging start, keep the power on (no suspension of power supply) and heat-run over 5 minutes.
- Using ‘no signal’ or ‘full white pattern’ or the others, check the back light on.

· Auto adjustment Map(RS-232C)
RS-232C COMMAND
[CMD ID DATA]
Wb 00 00 White Balance Start
Wb 00 ff White Balance End

	RS-232C COMMAND [CMD ID DATA]			MIN	CENTER (DEFAULT)			MAX
	Cool	Mid	Warm		Cool	Mid	Warm	
R Gain	jg	Ja	jd	00	172	192	192	192
G Gain	jh	Jb	je	00	172	192	192	192
B Gain	ji	Jc	jf	00	192	192	172	192
R Cut					64	64	64	128
G Cut					64	64	64	128
B Cut					64	64	64	128

<Caution>
Color Temperature : COOL, Medium, Warm.
One of R Gain/G Gain/ B Gain should be kept on 0xC0, and adjust other two lower than C0.
(when R/G/B Gain are all C0, it is the FULL Dynamic Range of Module.)

* Manual W/B process using adjusts Remote control.
• After enter Service Mode by pushing “ADJ” key,
• Enter White Balance by pushing “►” key at “6. White Balance”.



* After you finished all adjustments, Press “In-start” key and compare Tool option and Area option value with its BOM, if it is correctly same then unplug the AC cable. If it is not same, then correct it same with BOM and unplug AC cable. For correct it to the model’s module from factory Jig model.
* Push the “IN STOP” key after completing the function inspection. And Mechanical Power Switch must be set “ON”.

4.2. DDC EDID Write (RGB 128Byte)

• Connect D-sub Signal Cable to D-sub Jack.
• Write EDID Data to EEPROM(24C02) by using DDC2B protocol.
• Check whether written EDID data is correct or not.
* For Service main Assembly, EDID have to be downloaded to Insert Process in advance.

4.3. DDC EDID Write (HDMI 256Byte)

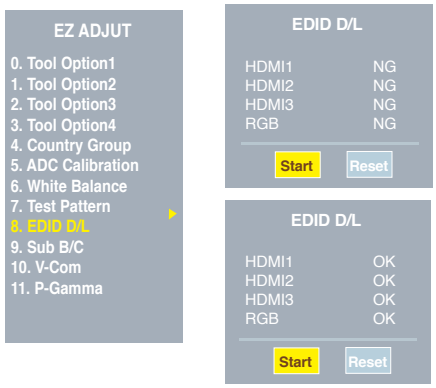
• Connect HDMI Signal Cable to HDMI Jack.
• Write EDID Data to EEPROM(24C02) by using DDC2B protocol.
• Check whether written EDID data is correct or not.
* For Service main Assembly, EDID have to be downloaded to Insert Process in advance.

4.4. EDID DATA

1) All Data : HEXA Value
2) Changeable Data :
*: Serial No : Controlled / Data:01
**: Month : Controlled / Data:00
***: Year : Controlled
****: Check sum

- Auto Download

1) After enter Service Mode by pushing “ADJ” key.
2) Enter EDID D/L menu.
3) Enter “START” by pushing “OK” key.



<Caution> Never connect HDMI && D-sub cable when EDID downloaded.

* EDID data and Model option download (RS232)

NO	Item	CMD1	CMD2	Data0		
Enter download Mode	Download ‘Mode In’	A	A	0	0	When transfer the ‘Mode In’, Carry the command.
EDID data and Model option download	Download	A	E	00	10	Automatically Download (The use of a internal pattern)

- Manual Download

* Caution
1) Use the proper signal cable for EDID Download.
- Analog EDID : Pin3 exists
- Digital EDID : Pin3 exists
2) Never connect HDMI & D-sub Cable at the same time.
3) Use the proper cables below for EDID Writing.
4) Download HDMI1, HDMI2, separately because HDMI1 is different from HDMI2.

For Analog EDID	For HDMI EDID
D-sub to D-sub	DVI-D to HDMI or HDMI to HDMI
	 

Item	Condition	Data(Hex)
Manufacturer ID	GSM	1E6D
Version	Digital : 1	01
Revision	Digital : 3	03

1) HD RGB EDID data

	0	1	2	3	4	5	6	7	8	9	A	B	C	D	E	F
0	0	FF	FF	FF	FF	FF	FF	0	1E	6D	**A**			**B**		
10	**C**		1	3	68	10	9	78	0A	EE	91	A3	54	4C	99	26
20	0F	50	54	A1	8	0	81	C0	61	40	45	40	31	40	1	1
30	1	1	1	1	1	1	1B	21	50	A0	51	0	1E	30	48	88
40	35	0	A0	5A	0	0	0	1E	1	1D	0	72	51	D0	1E	20
50	6E	28	55	0	A0	5A	0	0	0	1E	0	0	0	FD	0	3A
60	3E	1F	46	10	0	0A	20	20	20	20	20	20	**D**			
70	**D**														0	E

2) HD HDMI EDID data

	0	1	2	3	4	5	6	7	8	9	A	B	C	D	E	F
0	0	FF	FF	FF	FF	FF	FF	0	1E	6D	**A**			**B**		
10	**C**		1	3	80	10	9	78	0A	EE	91	A3	54	4C	99	26
20	0F	50	54	A1	8	0	81	C0	61	40	45	40	31	40	1	1
30	1	1	1	1	1	1	1B	21	50	A0	51	0	1E	30	48	88
40	35	0	A0	5A	0	0	0	1C	1	1D	0	72	51	D0	1E	20
50	6E	28	55	0	A0	5A	0	0	0	1E	0	0	0	FD	0	3A
60	3E	1F	46	10	0	0A	20	20	20	20	20	20	**D**			
70	**D**														0	E
80	2	3	20	F1	4E	10	1F	84	13	5	14	3	2	12	20	21
90	22	15	1	26	15	7	50	9	57	7	**F**					
A0	1	1D	80	18	71	1C	16	20	58	2C	25	0	A0	5A	0	0
B0	0	9E	1	1D	0	80	51	D0	0C	20	40	80	35	0	A0	5A
C0	0	0	0	1E	8C	0A	D0	8A	20	E0	2D	10	10	3E	96	0
D0	A0	5A	0	0	0	18	2	3A	80	18	71	38	2D	40	58	2C
E0	45	0	A0	5A	0	0	0	1E	1	1D	80	D0	72	1C	16	20
F0	10	2C	25	80	A0	5A	0	0	0	9E	0	0	0	0	0	E

* Detail EDID Options are below

ⓐ Product ID

Model Name	HEX	EDID Table	DDC Function
HD/FHD Model	0001	01 00	Analog/Digital

ⓑ Serial No: Controlled on production line.

ⓒ Month, Year: Controlled on production line:
ex) Week : ‘01’ -> ‘01’
Year : ‘2011’ -> ‘15’ fix

ⓓ Model Name(Hex):

MODEL	MODEL NAME(HEX)
all	00 00 00 FC 00 4C 47 20 54 56 0A 20 20 20 20 20 20 20

ⓔ Checksum: Changeable by total EDID data.

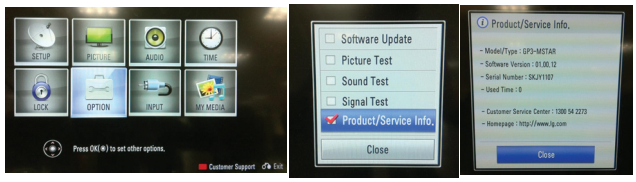
EDID C/S data		HD	
		HDMI	RGB
Check sum (Hex)	Block 0	B4	CD
	Block 1	65(HDMI1)	-
		55(HDMI2)	
		45(HDMI3)	

ⓕ Vendor Specific(HDMI)

INPUT	MODEL NAME(HEX)
HDMI1	65030C001000
HDMI2	65030C002000
HDMI3	65030C003000

5. Model name & Serial number D/L

- Press “Power on” key of service remote control. (Baud rate : 115200 bps)
- Connect RS232 Signal Cable to RS-232 Jack.
- Write Serial number by use RS-232.
- Must check the serial number at the Product/Service info.. (menu key -> red key -> select product/Service info)



5.1. Signal TABLE

CMD	LENGTH	ADH	ADL	DATA_1	. . .	Data_n	CS	DELAY

CMD : A0h
LENGTH : 85~94h (1~16 bytes)
ADH : EEPROM Sub Address high (00~1F)
ADL : EEPROM Sub Address low (00~FF)
Data : Write data
CS : CMD + LENGTH + ADH + ADL + Data_1 +…+ Data_n
Delay : 20ms

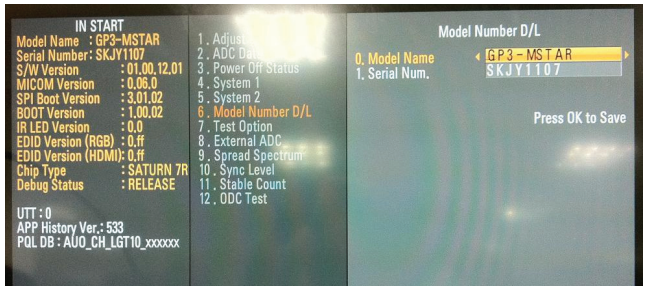
5.2. Command Set

No.	Adjust mode	CMD(hex)	LENGTH(hex)	Description
1	EEPROM WRITE	A0h	84h+n	n-bytes Write (n = 1~16)

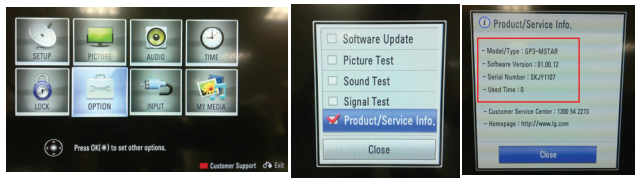
* Description
  FOS Default write : <7mode data> write
  Vtotal, V_Frequency, Sync_Polarity, Htotal, Hstart, Vstart, 0, Phase
  Data write : Model Name and Serial Number write in EEPROM,.

5.3. Method & notice

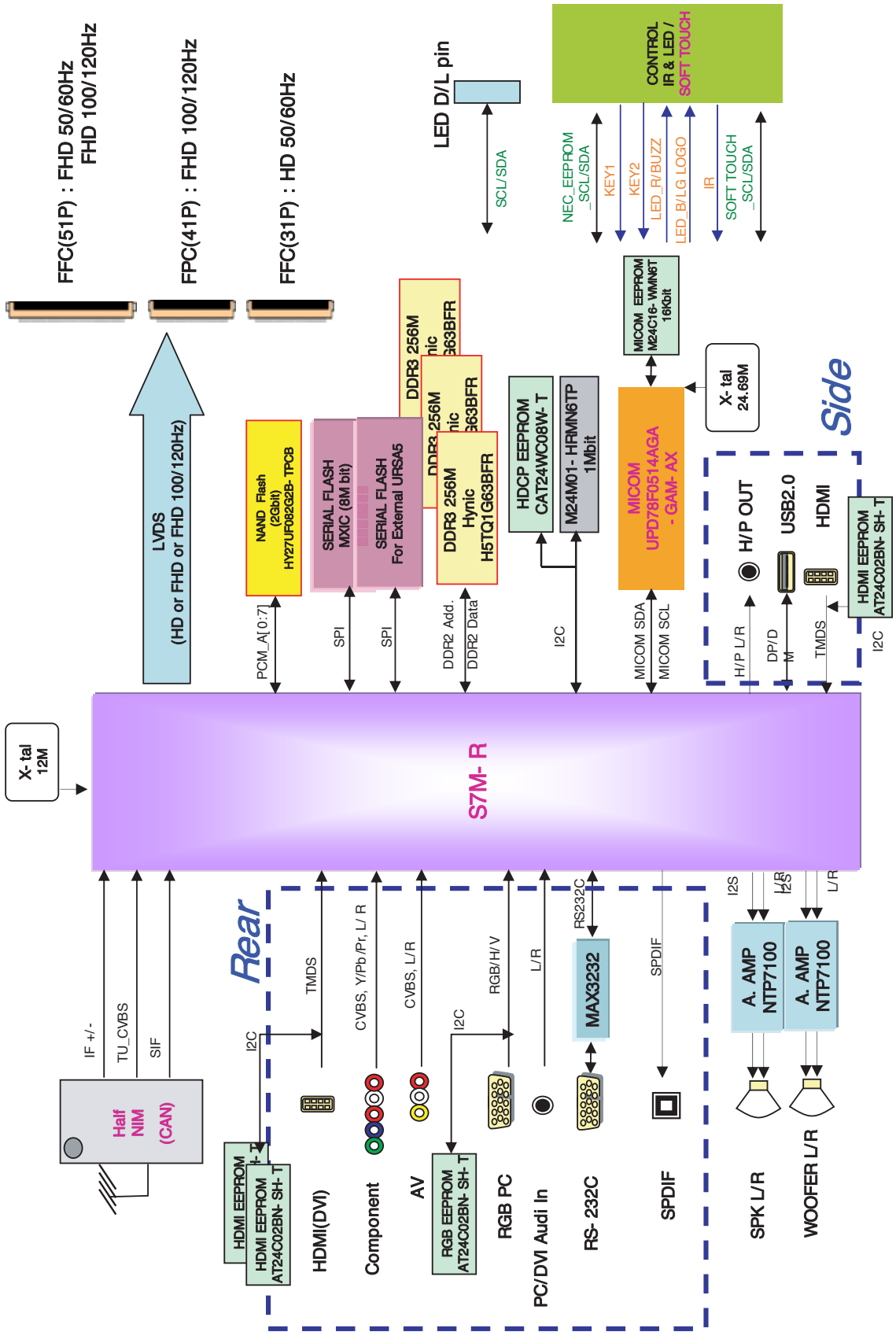
A. Serial number D/L is using of scan equipment.
B. Setting of scan equipment operated by Manufacturing Technology Group.
C. Serial number D/L must be conformed when it is produced in production line, because serial number D/L is mandatory by D-book 4.0.



* Manual Download (Model Name and Serial Number)
  If the TV set is downloaded by OTA or Service man, sometimes model name or serial number is initialized.(Not always)
  There is impossible to download by bar code scan, so It need Manual download.
  1) Press the ‘instart’ key of Adjustment remote control.
  2) Go to the menu ‘6.Model Number D/L’ like below photo.
  3) Input the Factory model name(ex 32LV2510-TB) or Serial number like photo.
  4) Check the model name Instart menu. -> Factory name displayed. (ex 32LV2510-TB)
  5) Check the Product/Service info..(Menu key -> Red key -> Select product/Service info) -> Buyer model displayed. (ex 32LV2510-TB)



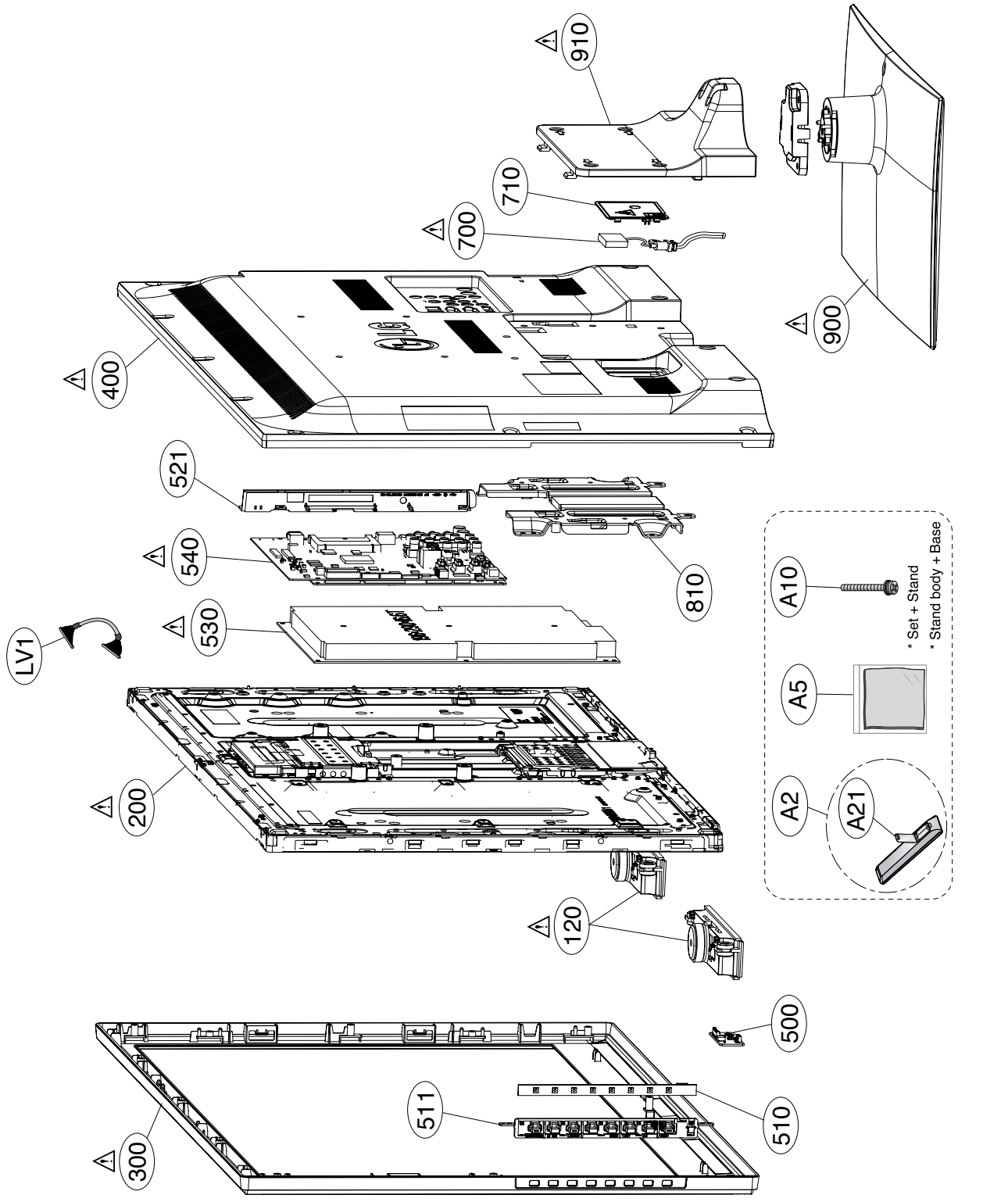
BLOCK DIAGRAM



EXPLODED VIEW

IMPORTANT SAFETY NOTICE

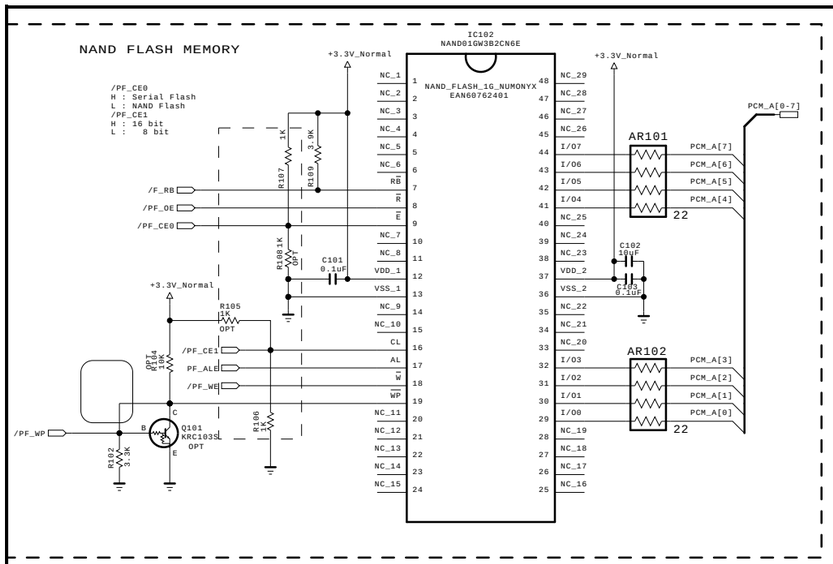
Many electrical and mechanical parts in this chassis have special safety-related characteristics. These parts are identified by ⚠ in the Schematic Diagram and EXPLODED VIEW.
It is essential that these special safety parts should be replaced with the same components as recommended in this manual to prevent X-RADIATION, Shock, Fire, or other Hazards.
Do not modify the original design without permission of manufacturer.



S7M-PLUS_DivX_MS10

LGE107DC-RP [S7M+ DIVX/MS10]

NAND FLASH MEMORY

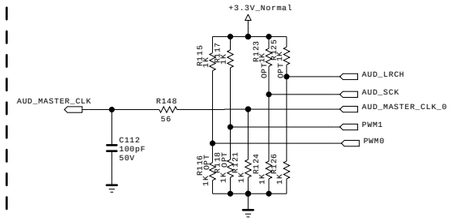


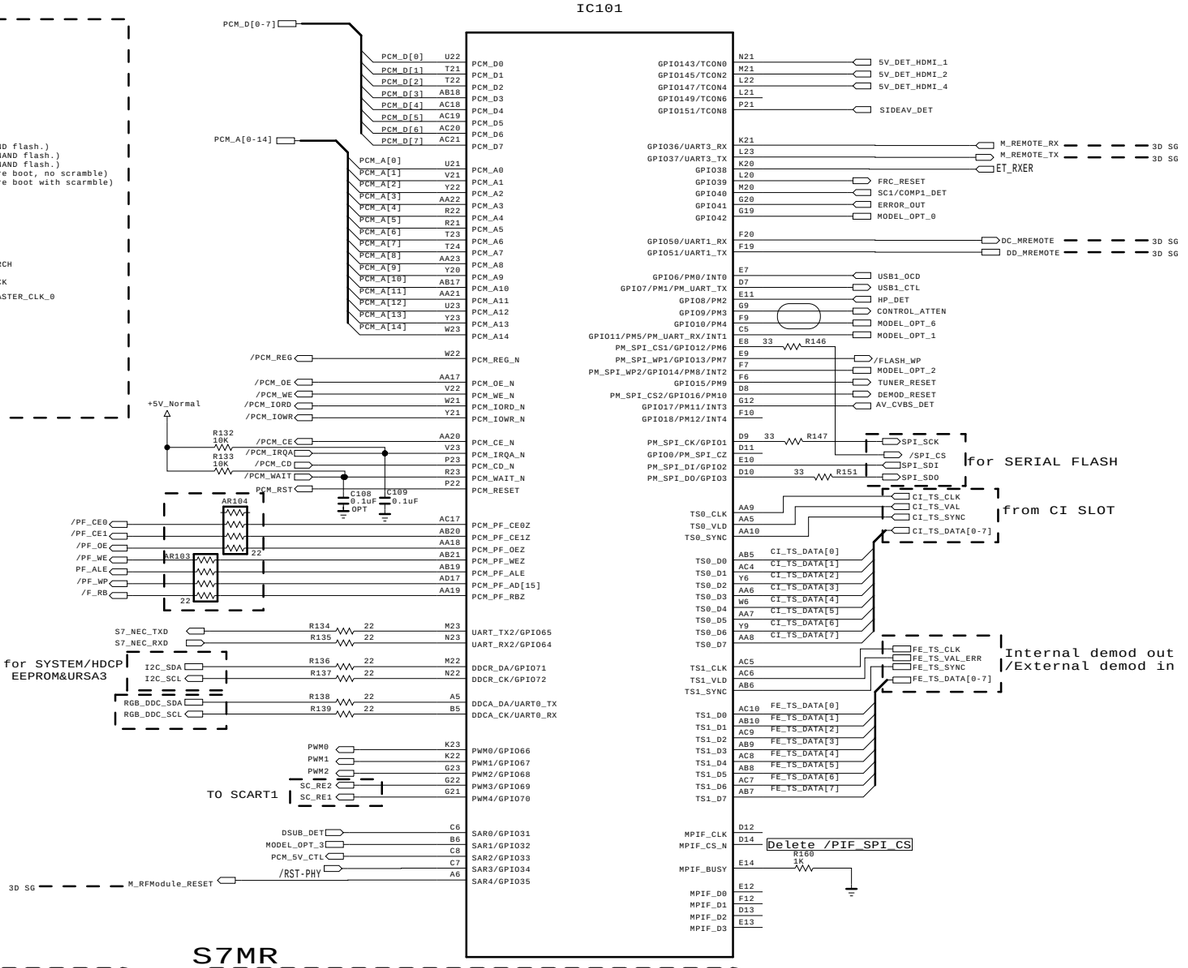
<T3 CHIP Config(AUD_LRCH)>

Boot from SPI flash : 1'b0
Boot from NOR flash : 1'b1

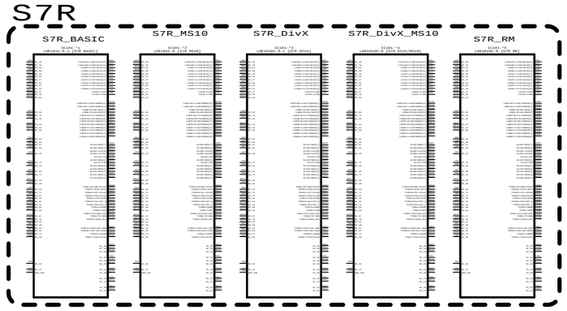
<T3 CHIP Config>
(AUD_SCK, AUD_MASTER_CLK, PWM1, PWM0)

MIPS_no_EJ_NOR8 : 4'h3 (MIPS as host. No EJ PAD. Byte mode NAND flash.)
MIPS_EJ1_NOR8 : 4'h4 (MIPS as host. EJ use PAD1. Byte mode NAND flash.)
MIPS_EJ2_NOR8 : 4'h5 (MIPS as host. EJ use PAD2. Byte mode NAND flash.)
B51_Secure_no_scramble : 4'hb (8051 as host. Internal SPI flash secure boot, no scramble)
B51_Sesure_scramble : 4'hc (8051 as host. Internal SPI flash secure boot with scarmble)

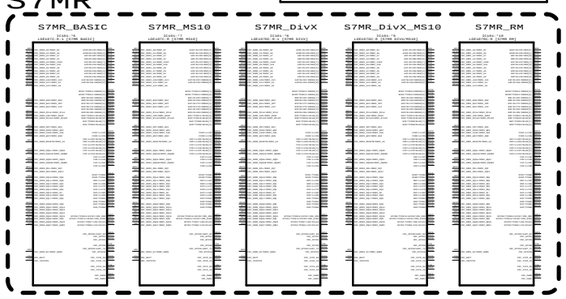




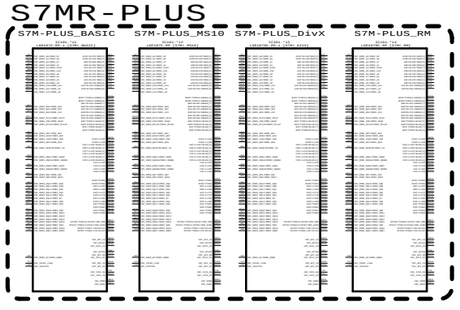
S7R

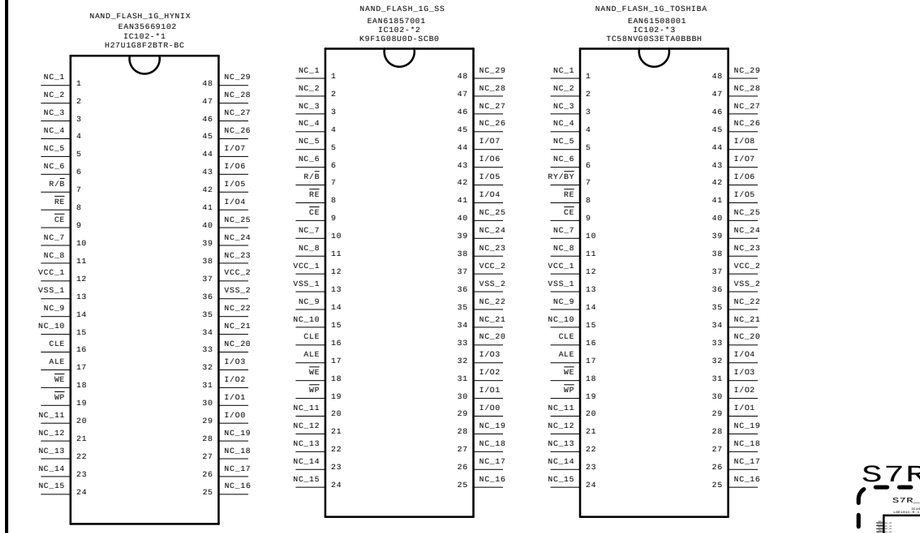


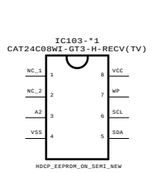
S7MR

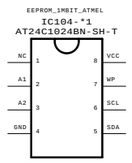


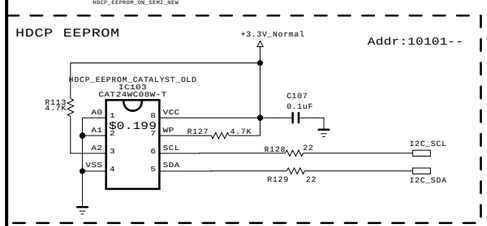
S7MR-PLUS

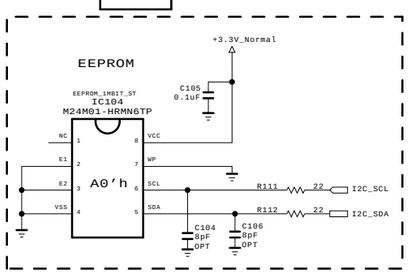


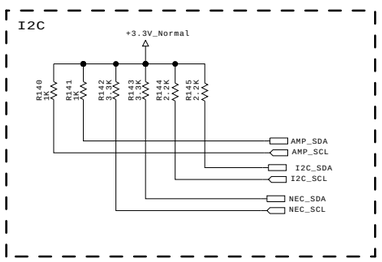


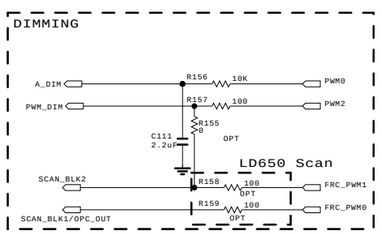


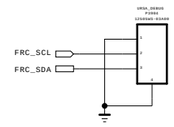












THE ⚠ SYMBOL MARK OF THIS SCHEMETIC DIAGRAM INCORPORATES SPECIAL FEATURES IMPORTANT FOR PROTECTION FROM X-RADIATION. FILRE AND ELECTRICAL SHOCK HAZARDS, WHEN SERVICING IF IS ESSENTIAL THAT ONLY MANUFATURES SPECFIED PARTS BE USED FOR THE CRITICAL COMPONENTS IN THE ⚠ SYMBOL MARK OF THE SCHEMETIC.

SECRET
LGElectronics

LG ELECTRONICS

MODEL	GP3_Saturn7M	DATE	Ver. 0.1
BLOCK	FLASH/EEPROM/GPIO	SHEET	1

MODEL OPTION

PIN NAME	PIN NO.	LOW	HIGH
MODEL_OPT_0	G19	NO FRC	FRC_HW_OPT
MODEL_OPT_4	E18	50/60Hz LVDS	100/120Hz LVDS
MODEL_OPT_1	C5	PHM_OFF	PHM_ON
MODEL_OPT_2	F7	NON_DVB_T2	DVB_T2
MODEL_OPT_3	B6	HD	FHD
MODEL_OPT_5	D18	Ready	default
MODEL_OPT_6	F9	LCD	OLED

NO_FRC : LOW LOW
U3_INTERNAL : HIGH LOW
U5_EXTERNALBOOT :HIGH HIGH
reserved for FRC : LOW HIGH

--> This option is only applied in EU.
In case of NON_EU, default value set LOW.

-->In case of GP2, This port was used for GIP/NON_GIP

--> MODEL_OPT_5, MODEL_OPT_6
: Only 3D_SG GPIO OUTPUT CONTROL

RSDS Power OPT

VDDC 1.26V

VDDC : 2026mA

S7M-PLUS_DivX_MS10 IC101 LGE107DC-RP [S7M+ DIVX/MS10]

Normal Power 3.3V

AVDD_MEMPLL:24mA
AU33:31mA
FRC_AVDD:60mA
FRC_LPLL:13mA
FRC_MPLL:4mA
FRC_VDD33_DDR:50mA
VDD33_DVI:163mA
AVDD_DMPLL/AVDD_NODIE:7.362mA

Normal 2.5V

AVDD2P5/ADC2P5:162mA
AU25:10mA
AVDD25_PGA:13mA

DDR3 1.5V

AVDD_DDR0:55mA
AVDD_DDR1:55mA
AVDD_DDR_FRC:55mA

RSDS Power OPT

HDMI

DSUB

SCART1_RGB/COMP1

COMP2

CVBS In/OUT

Delete CHB_CVBS_IN

Close to MSTAR

ANALOG SIF Close to MSTAR

TU/DEMOD_I2C

B/T USB

SIDE USB

I2S_I/F

AUDIO IN

AUDIO OUT

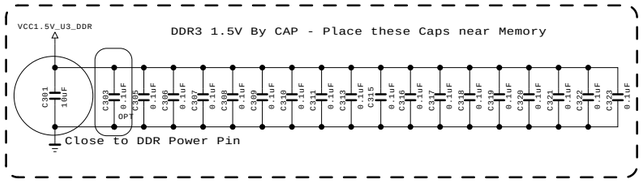
H/P OUT

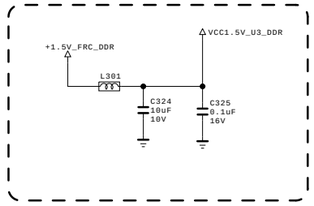
THE ⚠ SYMBOL MARK OF THIS SCHEMETIC DIAGRAM INCORPORATES SPECIAL FEATURES IMPORTANT FOR PROTECTION FROM X-RADIATION. FILRE AND ELECTRICAL SHOCK HAZARDS, WHEN SERVICING IF IS ESSENTIAL THAT ONLY MANUFATURES SPECFIED PARTS BE USED FOR THE CRITICAL COMPONENTS IN THE ⚠ SYMBOL MARK OF THE SCHEMETIC.

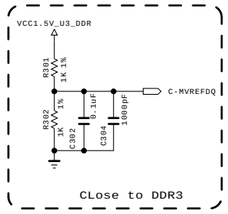
SECRET
LGElectronics

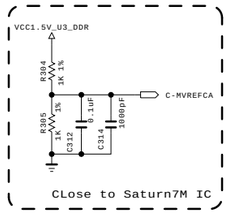
LG ELECTRONICS

MODEL	GP2R	DATE	20101023
BLOCK	MAIN2, HW OPT	SHEET	2 /



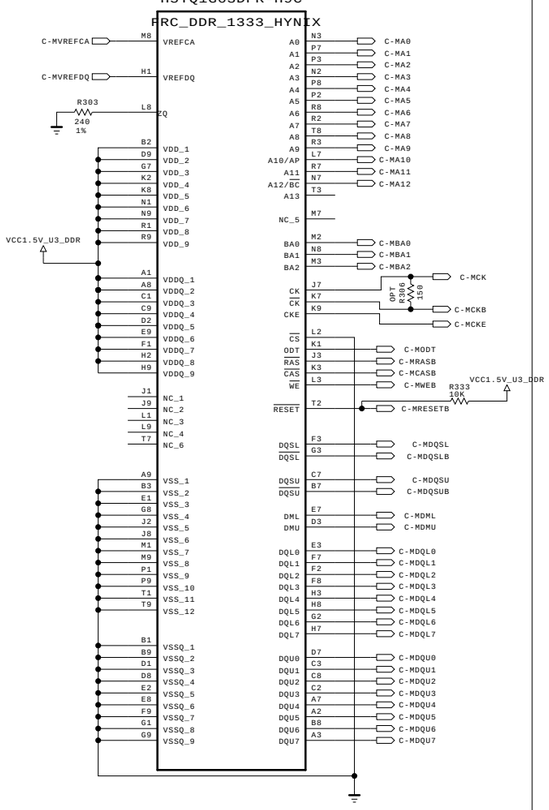


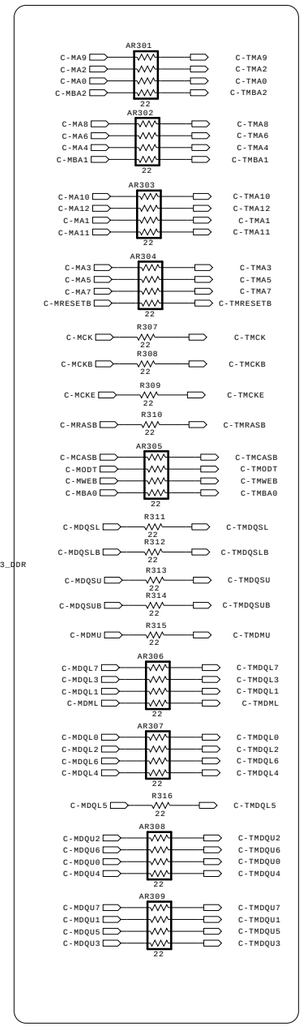




EAN61829001

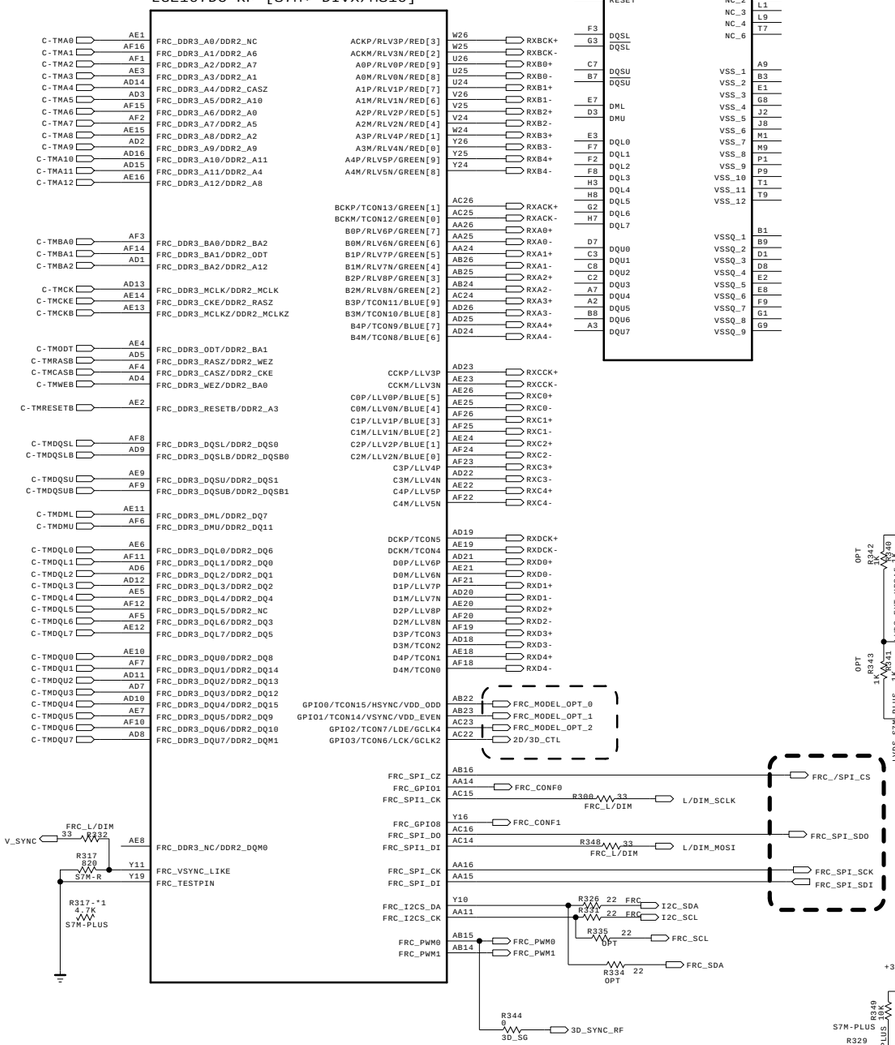
IC301 H5TQ1G63DFR-H9C





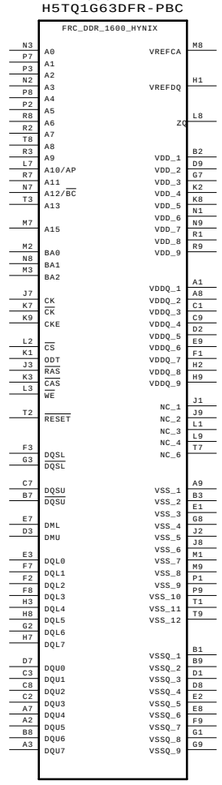
S7M-PLUS_DivX_MS10

IC101 LGE107DC-RP [S7M+ DIVX/MS10]



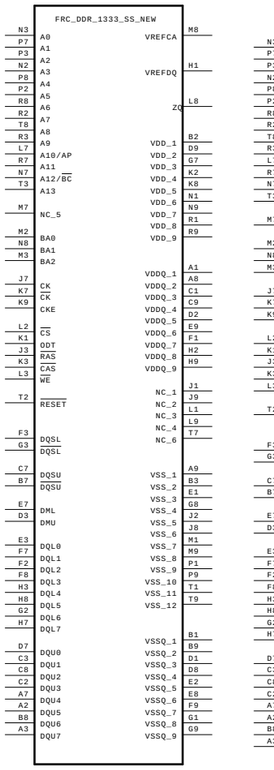
EAN61829001

IC301-*2 H5TQ1G63DFR-PBC



EAN61857101

IC301-*3 K4B1G1646G-BCH9



EAN61857201

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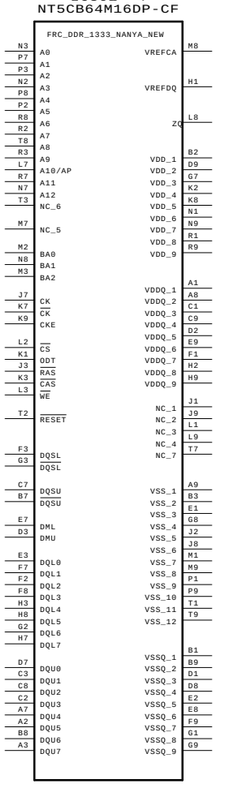

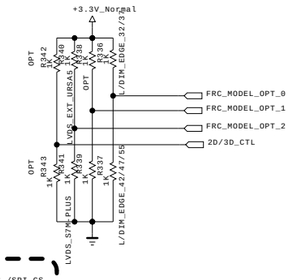

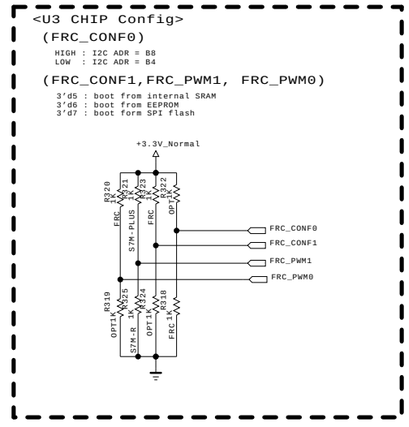

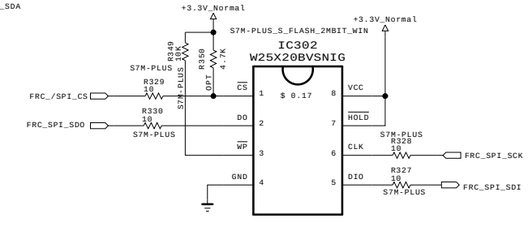

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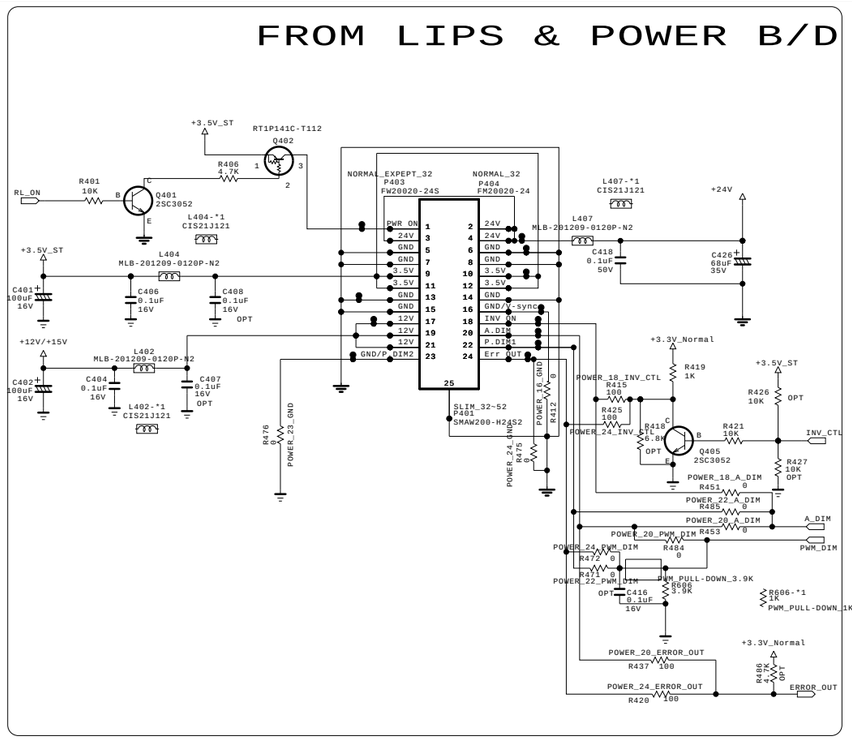
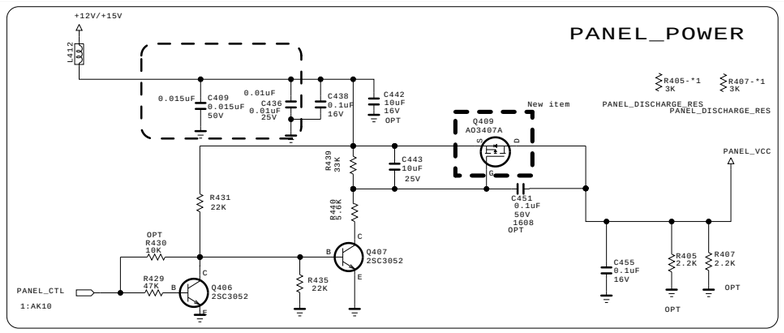
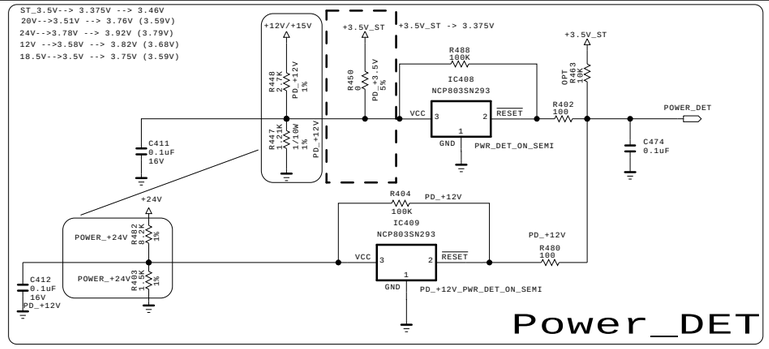
SECRET
LGElectronics

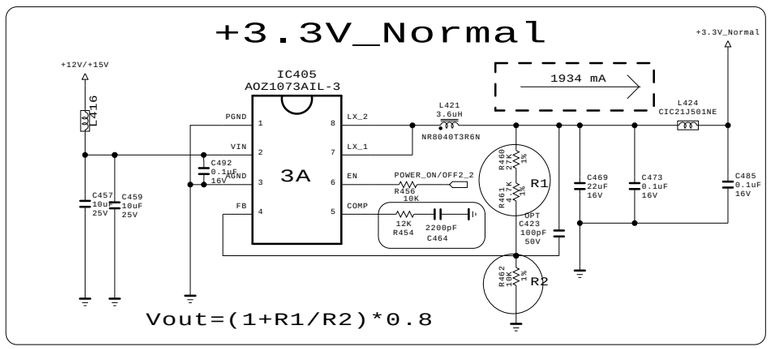
LG ELECTRONICS

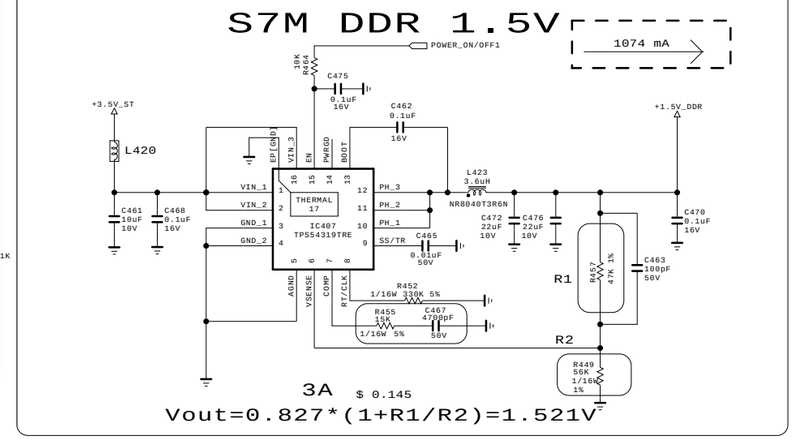
MODEL	GP2R	DATE	20101023
BLOCK	FRC_DDR	SHEET	3

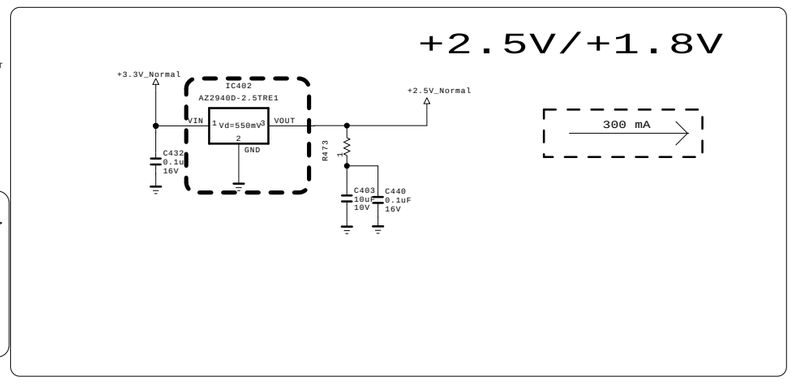


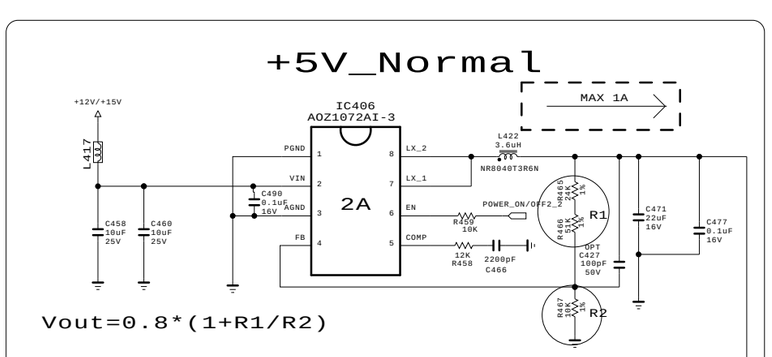


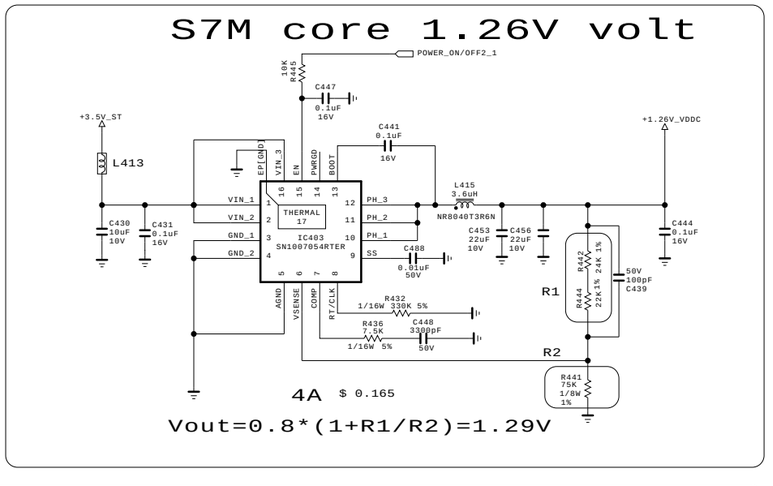


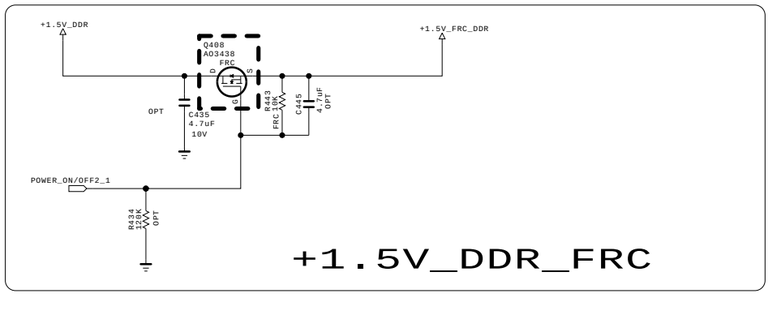












<MODULE PIN MAP>

PIN No	LGD(PSU) or LIPS	CMO10"Lamp (PSU)	AUO 10"Lamp (PSU)	SHARP (PSU)	IPS-@ (PSU)
16	GND	GND	GND	GND	GND
18	INV_ON	A-DIM	INV_ON	INV_ON	INV_ON
20	VBR-A	NC	Err_out	52/60:ERROR 26/32HD:NC	Err_out
22	PWM_DIM	PWM_DIM	NC	26/32/52:PWM 60:NC	NC
24	Err_out	INV_ON	PWM_DIM	26/32/52:GND 60:PWM	PWM_DIM
23	GND	GND	GND	GND	GND

TP5302 OLP
TP5303 V_SYNC
TP5304 SCAN_BLK2
TP5305 SCAN_BLK1/OPC_OUT
TP5306 OPC_OUT

<LED MODULE PIN MAP -> latest update 20100618>

PIN No	LGD LPB/ OS LPB	32LE5300-TA CMO10"LED (PSU)	32LE4500-TA AUO 10"LED (PSU)	32LE5300-TA LGD 10"LED (PSU)	
16	NC	NC	NC	NC	
18	INV_ON	INV_ON	INV_ON	INV_ON	
20	NC	err_out --> NC	err_out --> NC	NC	
22	PWM_DIM	NC	NC	PWM_DIM	
24	err_out --> NC	PWM_DIM	PWM_DIM	err_out --> NC	
23	NC	NC	NC	NC	

LGD edge led error-out use or not? checking is necessary...

<Module Inv to Main Pin Connection>

INV	<-->	MAIN
#11	<-->	#24
#12	<-->	#18
#13	<-->	#20
#14	<-->	#22

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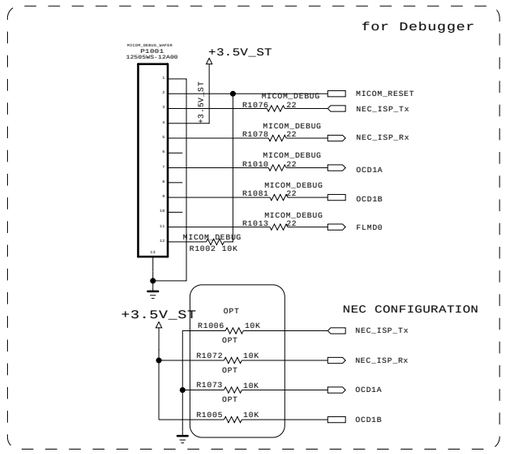
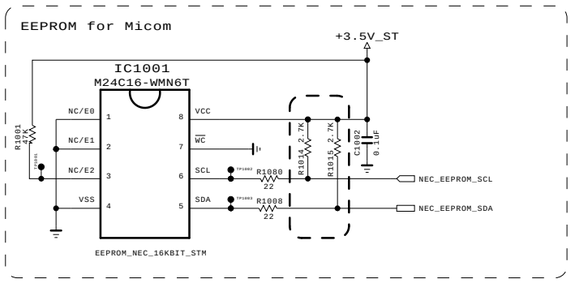
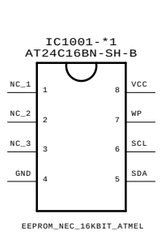
SECRET
LGElectronics

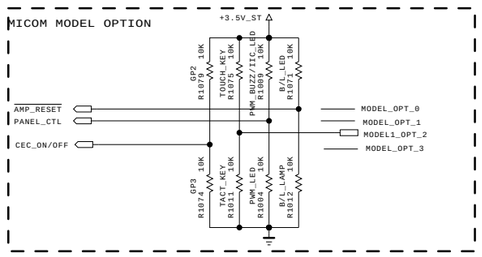
LG ELECTRONICS

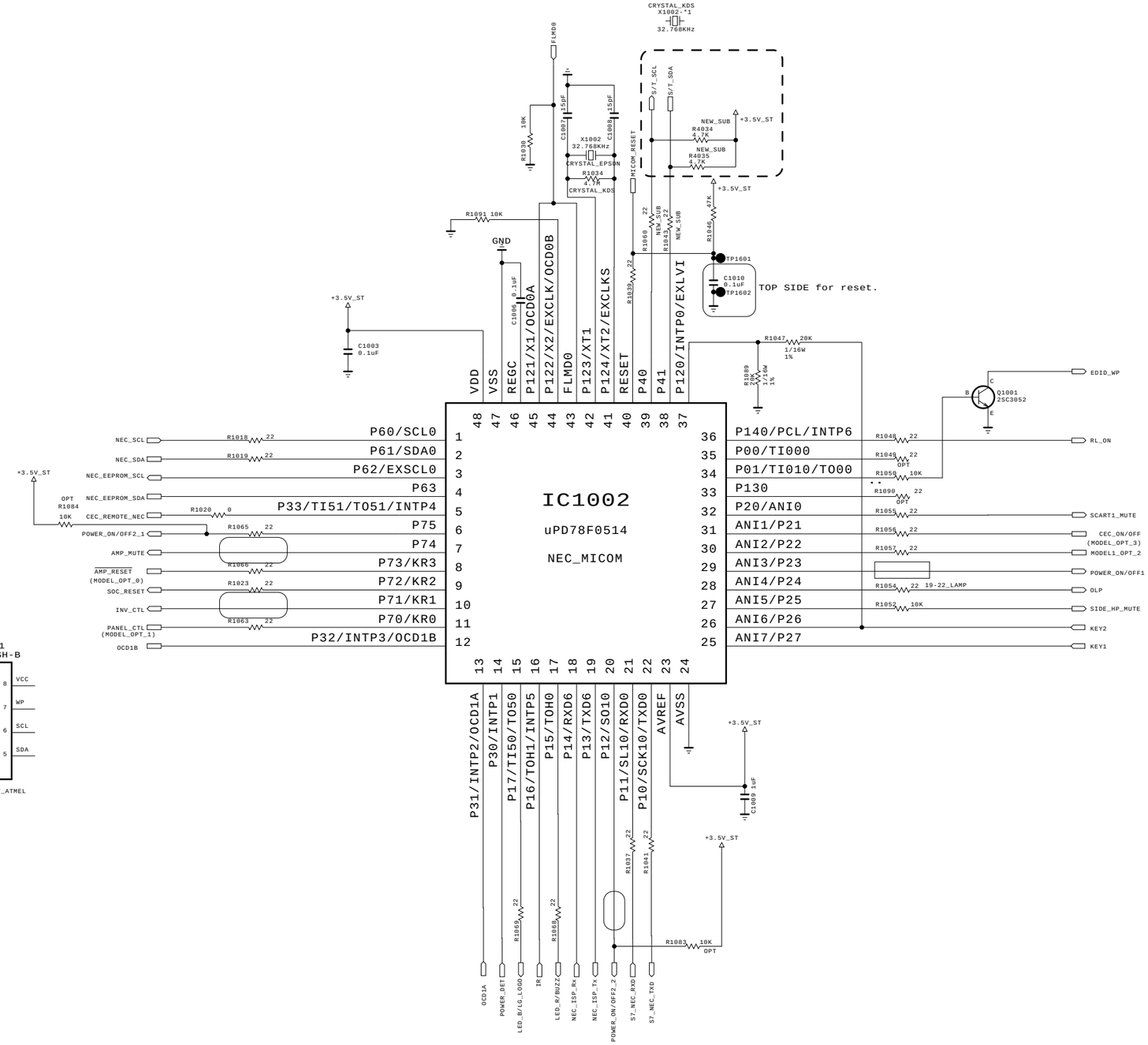
MODEL	GP2R	DATE	20101023
BLOCK	POWER_LARGE	SHEET	4











2011Y,GP2R, 101125 Update

MODEL OPTION

PIN NAME	PIN NO.	HIGH	LOW
MODEL_OPT_0	8	B/L_LED	B/L_LAMP
MODEL_OPT_1	11	PWM_BUZZ/IIC_LED	PWM_LED
MODEL_OPT_2	30	TOUCH_KEY	TACT_KEY
MODEL_OPT_3	31	GP2	GP3

PWM_BUZZ/IIC_LED :Using IIC for LED Breathing & PWM Buzz
PWM_LED : Using PWM Signal for LED Lighting

MODEL_OPT_0	MODEL_OPT_1	MODEL_OPT_2	MODEL_OPT_3	Description
LOW	LOW	LOW	LOW	LK330/LK430 for KR/US 10Y EYE-Q Sensor KEY & PWM LED & No Buzz & No LED Blink
LOW	LOW	LOW	HIGH	LK330/LK430/LK530 KEY & PWM LED & No Buzz & No LED Blink
LOW : LED HIGH : LAMP	HIGH	HIGH	LOW	LV25/LV35/LV45/LW45/LV55/LK45/LK55 S/T & IIC LED & NO BUZZ & LED Blink
	HIGH	LOW	LOW	TBD IIC LED(09Y IIC Protocol) & No BUZZ
	LOW	HIGH	LOW	TBD S/T & IIC LED & No Buzz & LED Blink

2010Y,GP2

MODEL OPTION

PIN NAME	PIN NO.	HIGH	LOW
MODEL_OPT_0	8	B/L_LED	B/L_LAMP
MODEL_OPT_1	11	PWM_BUZZ/IIC_LED	PWM_LED
MODEL_OPT_2	30	TOUCH_KEY	TACT_KEY
MODEL_OPT_3	31	GPIO_LED	NON_GPIO_LED

PWM_BUZZ/IIC_LED : For model that use LED Lighting used IIC
PWM_LED : For model that use LED Lighting used PWM Signal

MODEL_OPT_0	MODEL_OPT_1	MODEL_OPT_2	MODEL_OPT_3	
LOW	LOW	LOW	LOW	LD350/450/550 PWM LED & No Buzz & No LED Blink
HIGH	LOW	HIGH	LOW	19/22/26LE5300/5300 IIC LED & PWM IIC BUZZ
HIGH	HIGH	HIGH	LOW	32/37/42/47/55LE5300 IIC LED & PWM BUZZ
LOW	HIGH	LOW	LOW	LD420 IIC LED(09Y IIC Protocol) & No BUZZ
HIGH	LOW	LOW	HIGH	LE7300 GPIO LED & NO BUZZ

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SECRET
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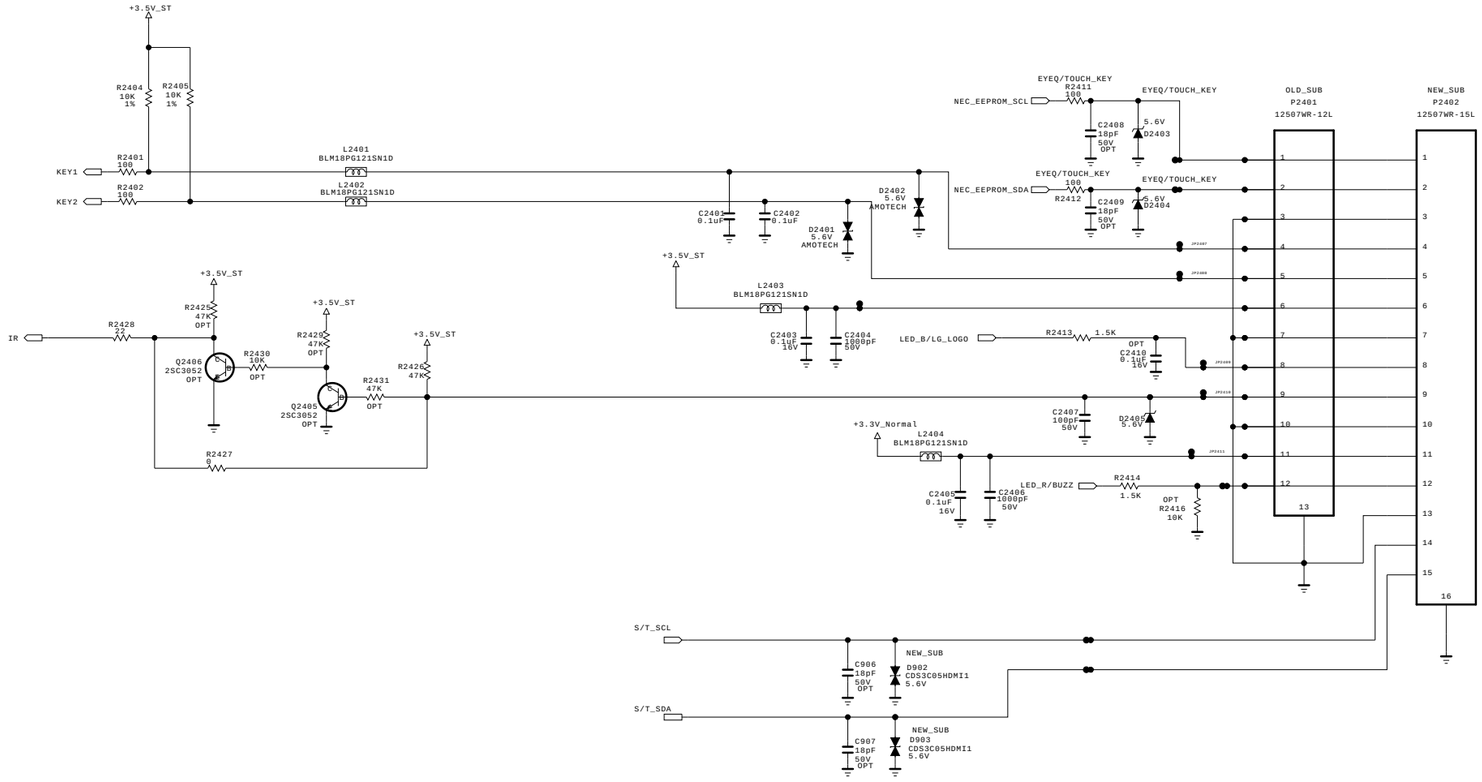
LG ELECTRONICS

MODEL	GP2R	DATE	20101125
BLOCK	MICOM Rev.4	SHEET	5

CONTROL
IR & LED



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SECRET
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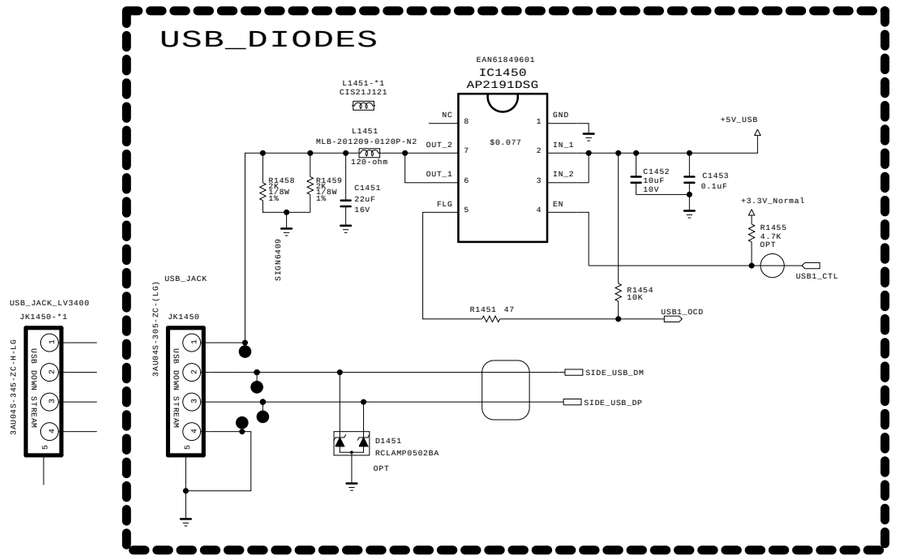
LG ELECTRONICS

MODEL	GP2R	DATE	20101023
BLOCK	IR/CONTROL-L	SHEET	6



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SECRET
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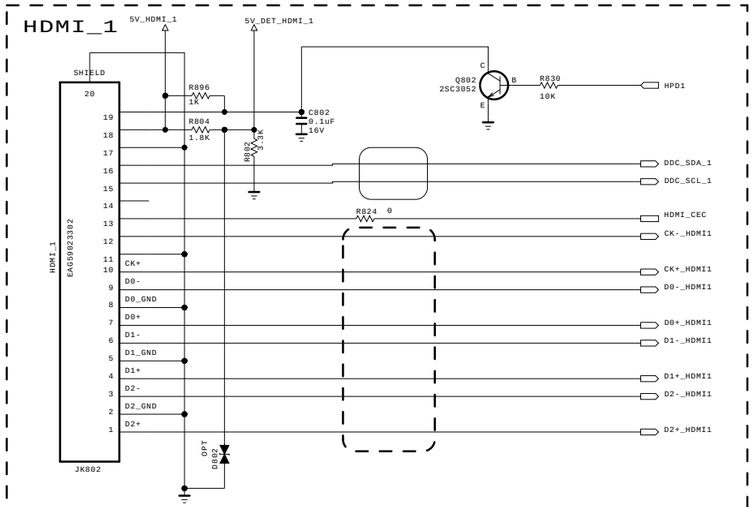
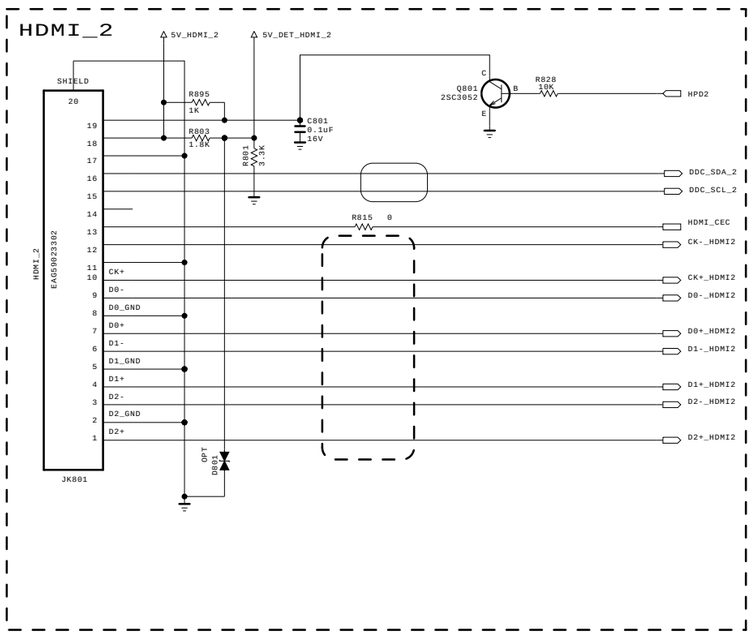
LG ELECTRONICS

MODEL	GP2R	DATE	20101023
BLOCK	USB_OCP_DIODE	SHEET	7 /

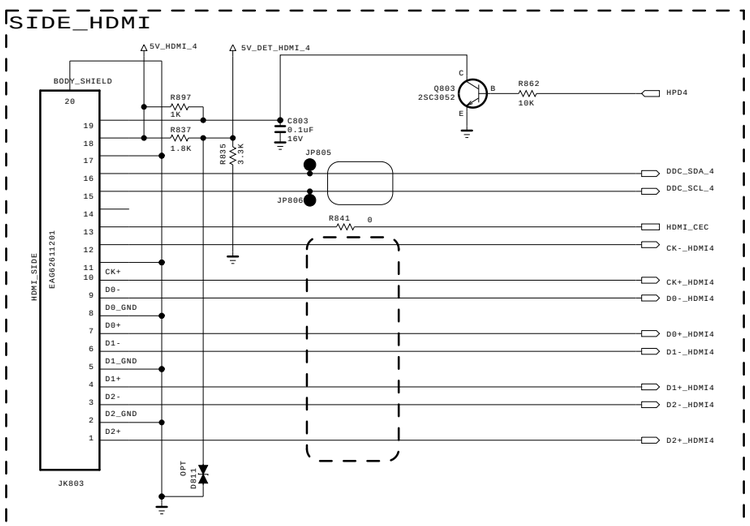
HDMI_1



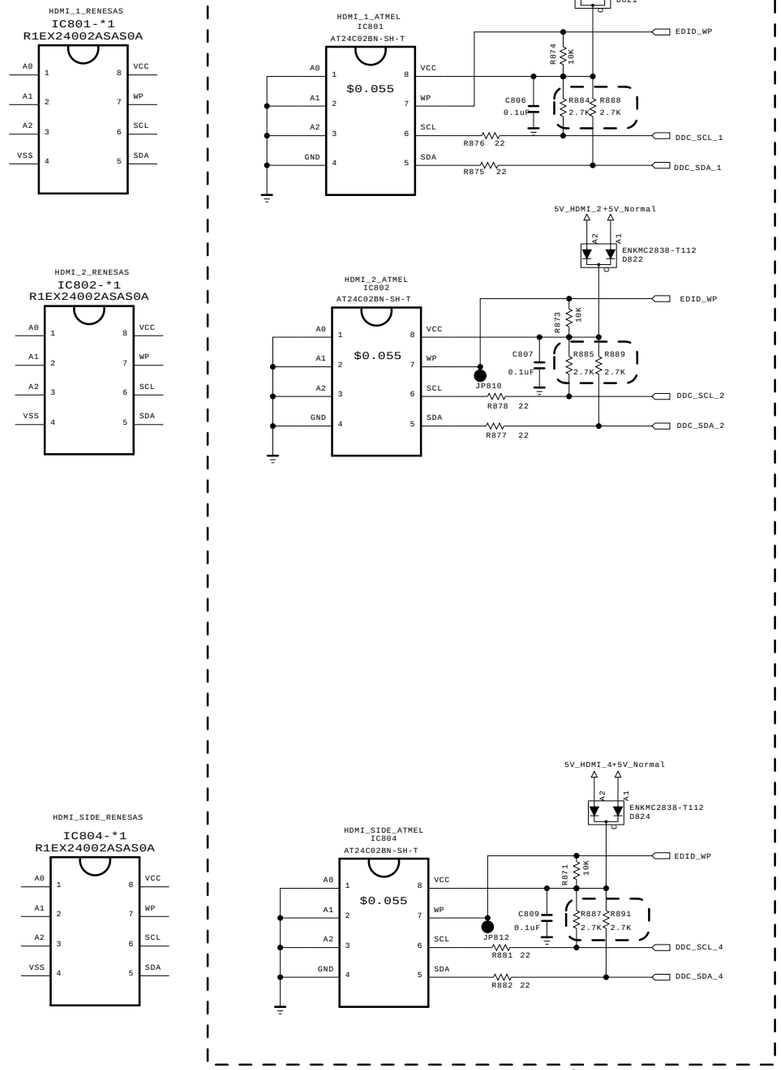
HDMI_2



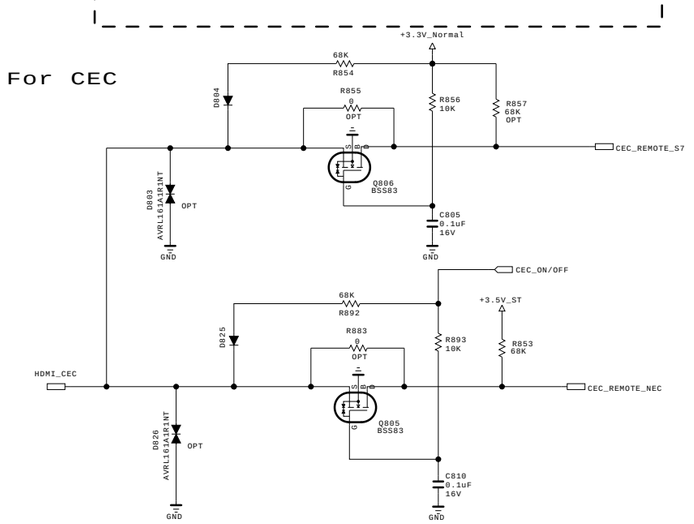
SIDE_HDMI



HDMI EEPROM



For CEC



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LG ELECTRONICS

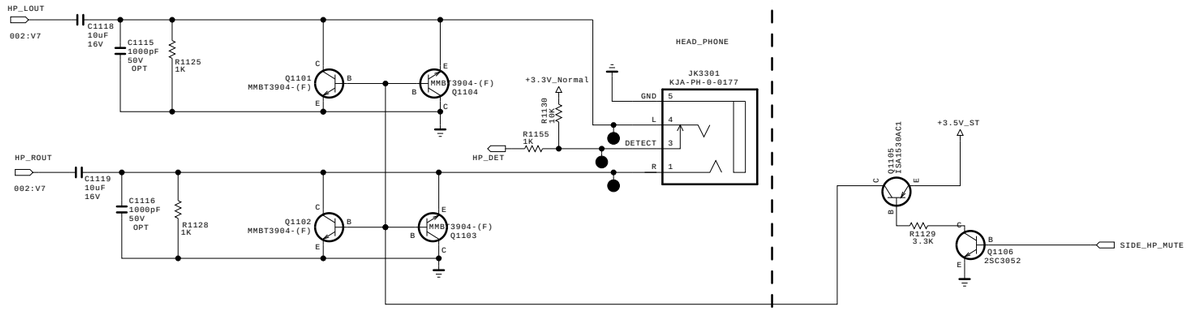
MODEL	GP2R	DATE	20101023
BLOCK	HDMI	SHEET	8

LGE Internal Use Only

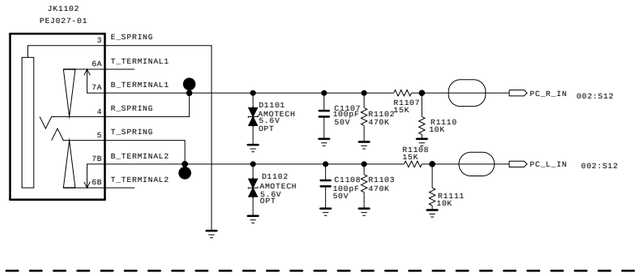
RGB/SPDIF/PC/HP

New Item Development

EARPHONE BLOCK

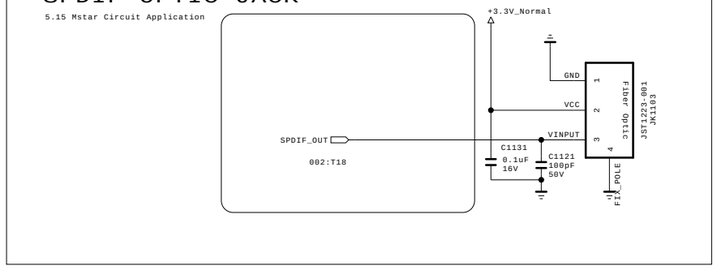


PC AUDIO

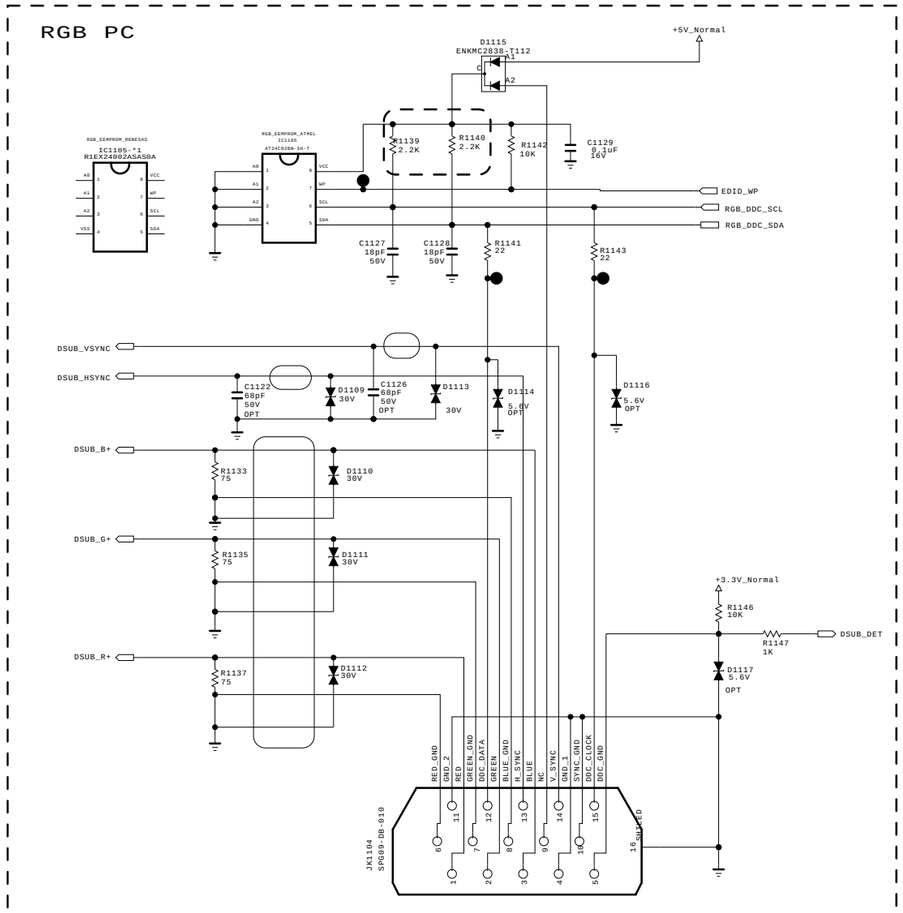


SPDIF OPTIC JACK

5.15 Mstar Circuit Application



RGB PC



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SECRET
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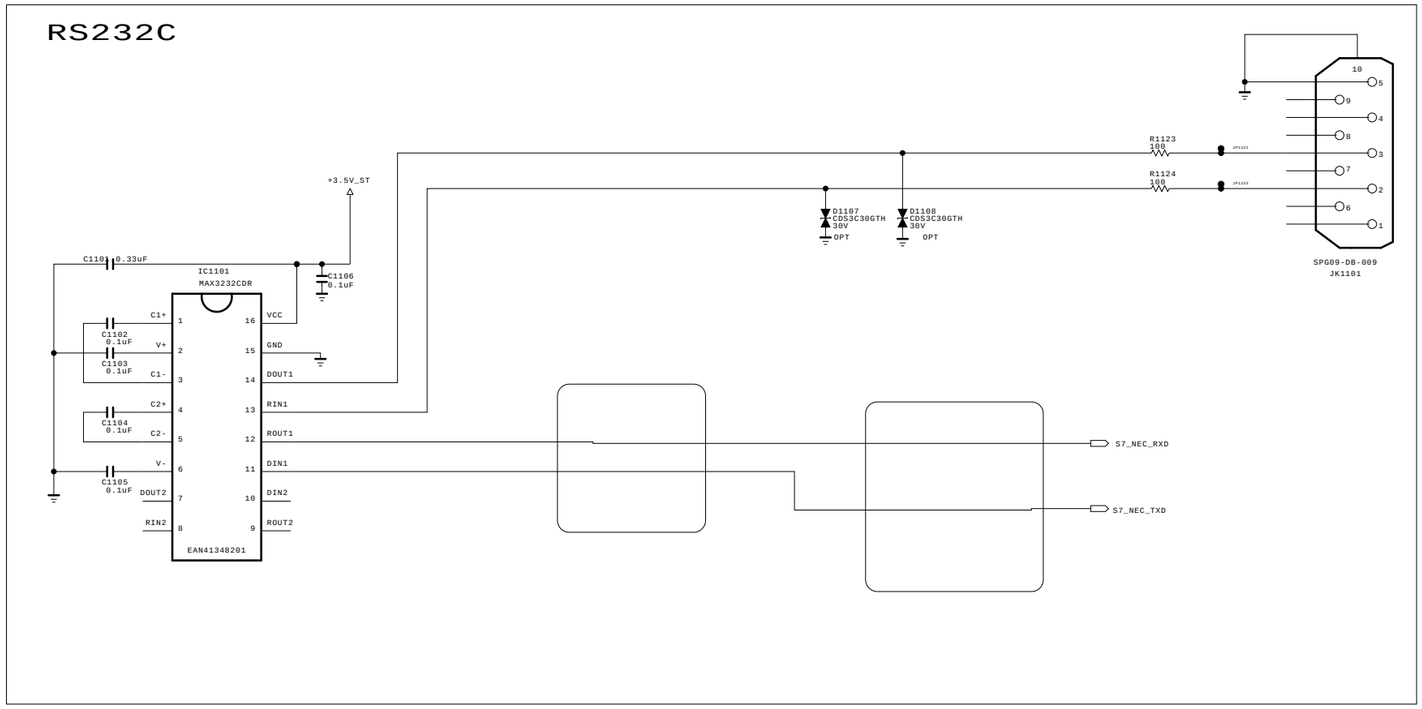
LG ELECTRONICS

MODEL	GP2R	DATE	20101023
BLOCK	RGB/SPDIF/HP	SHEET	9

RS232C



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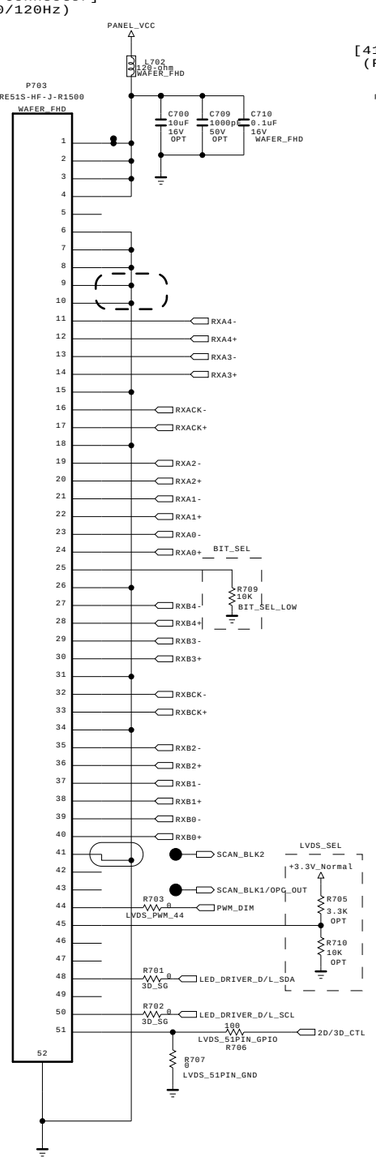
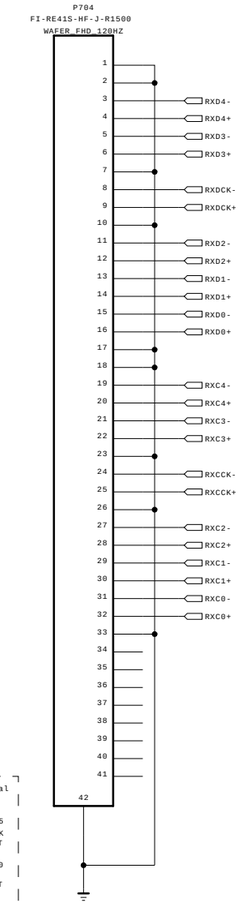
LG ELECTRONICS

MODEL	GP2R	DATE	20101023
BLOCK	RS232C_9PIN	SHEET	10

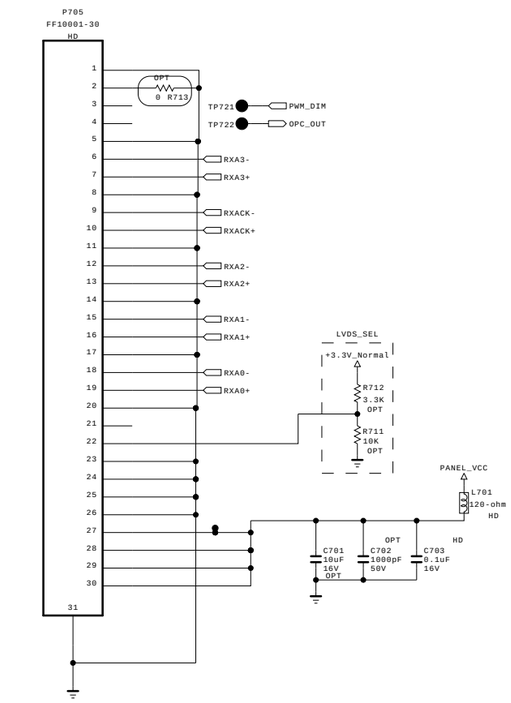
[51Pin LVDS Connector]
(For FHD 60/120Hz)



[41Pin LVDS Connector]
(For FHD 120Hz)



[30Pin LVDS Connector]
(For HD 60Hz_Normal)



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SECRET
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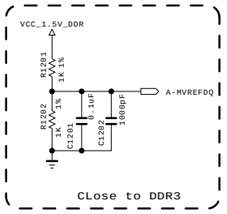
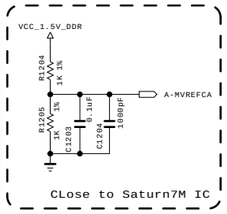
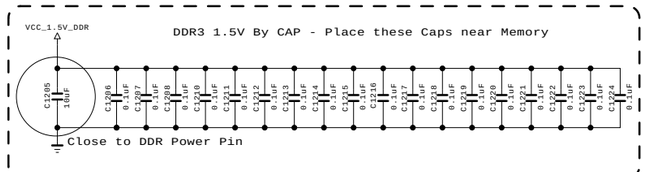
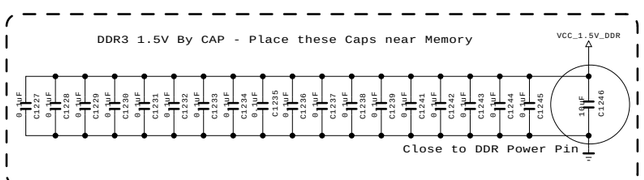
LG ELECTRONICS

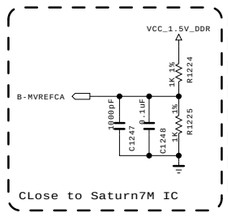
MODEL	GP2R	DATE	20101023
BLOCK	LVDS_LARGE	SHEET	11

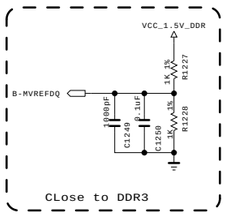


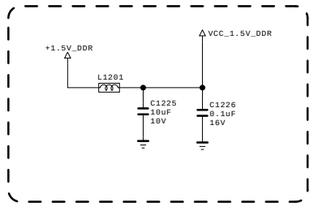


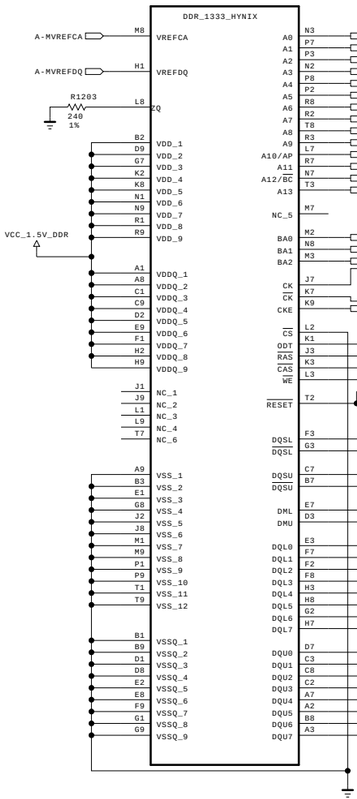


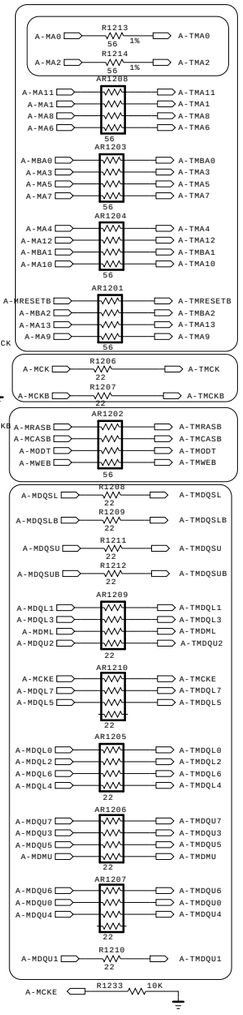


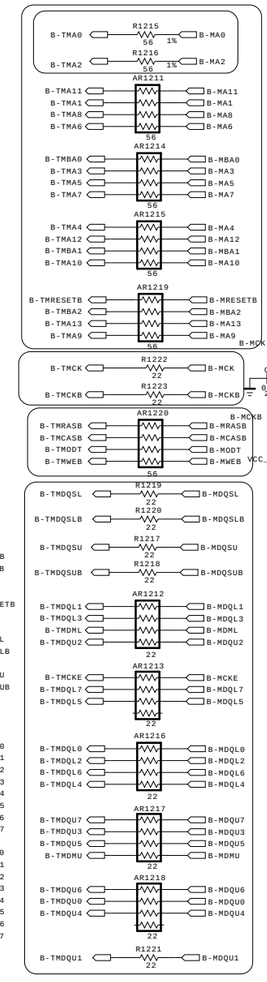


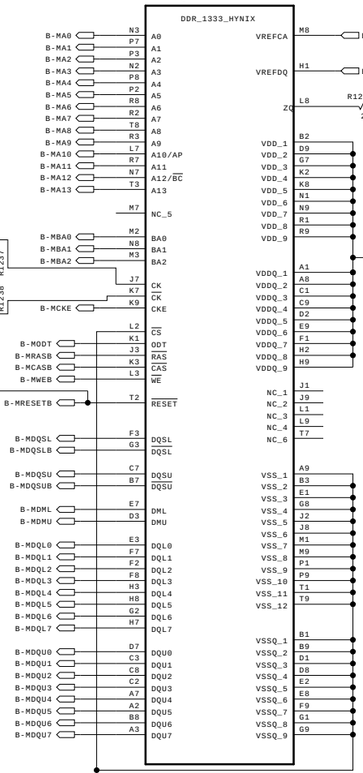


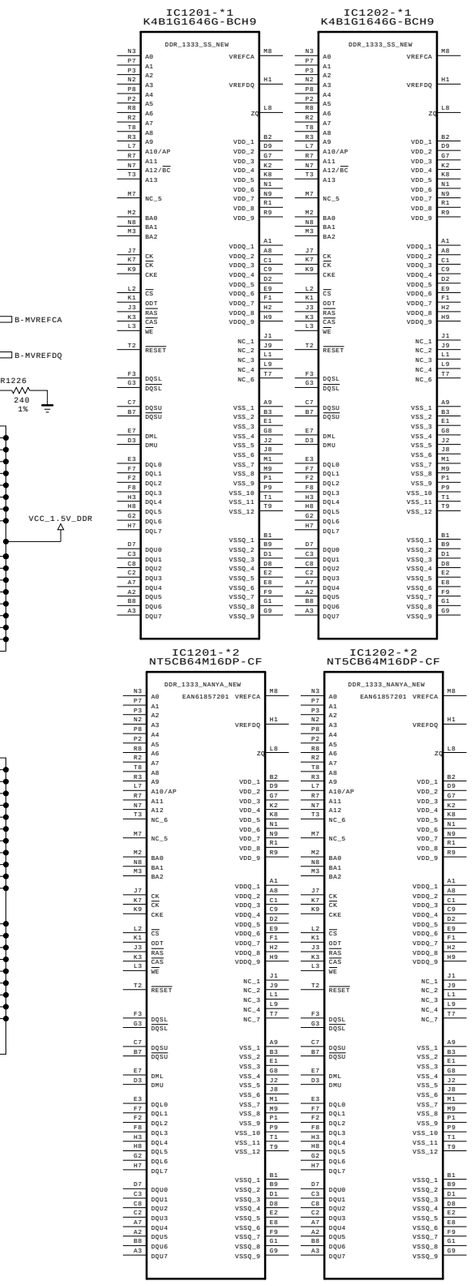












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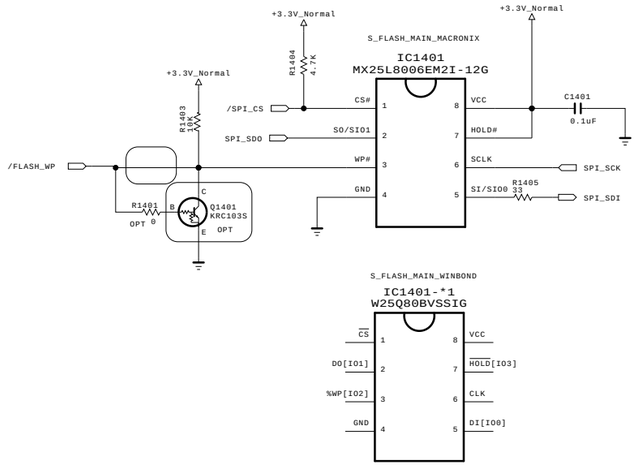
SECRET

LGElectronics

LG ELECTRONICS

MODEL	GP2R	DATE	20101023
BLOCK	DDR_256	SHEET	12 /



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SECRET
LGElectronics

LG ELECTRONICS

MODEL	GP2R	DATE	20101023
BLOCK	SFLASH_1MB	SHEET	13 /

GP2R_LARGE_TUNER

TU3702
TDTJ-S001D

DVB_1INPUT_H_LGIT

1	ANT_PWR[OPT]
2	BST_CNTL
3	+B
4	NC[RF_AGC]
5	AS
6	SCL
7	SDA
8	NC[IF_TP]
9	SIF
10	NC
11	VIDEO
12	GND
13	1.2V
14	3.3V
15	RESET
16	IF_AGC_CNTL
17	DIF_1
18	DIF_2
19	SHIELD

CN_2INPUT_H_LG3911

TU3701
TDFR-C036D

1	RF_S/W_CNTL
2	BST_CNTL
3	+B1[+5V]
4	NC[RF_AGC]
5	NC_1
6	SCLT
7	SDAT
8	NC_2
9	SIF
10	NC_3
11	VIDEO
12	GND
13	+B2[1.2V]
14	+B3[3.3V]
15	RESET
16	NC_4
17	SCL
18	SDA
19	ERR
20	SYNC
21	VALID
22	MCL
23	D0
24	D1
25	D2
26	D3
27	D4
28	D5
29	D6
30	D7
31	SHIELD

RF_SWITCH_CTL
Pull-up can't be applied because of MODEL_OPT_2

close to TUNER
OPT R3762 0 CONTROL_ATTEN

close to TUNER
R3705 0 RF_SW_OPT
C3701 0.1uF 16V

+5V_TU
C3703 100pF 50V
C3704 0.1uF 16V

OPTION : RF AGC
C3728 0.1uF 16V OPT
C3731 10uF 10V OPT
Q3704 2SC3052 OPT
R3754 10K OPT
FE_AGC_SPEED_CTL
IF_AGC_SEL

GPIO must be added.

R3707 0 OPT
C3706 0.1uF 16V

C3702 0.1uF 16V close to TUNER

+1.2V/+1.8V_TU
+3.3V_TU
CN C3739 10uF 6.3V
C3707 100pF 50V
C3708 0.1uF 16V
close to the tuner pin, add,09029

C3737 100pF 50V
C3738 0.1uF 16V
C3705 100uF 16V
FULL_NIM

R3732 100
R3733 180K
C3710 0.1uF 16V
TUNER_RESET

R3702 100 FULL_NIM
R3701 100 FULL_NIM
close to IF line

HALF_NIM R3760 0
R3761 0 HALF_NIM
Close to the tuner

IF_N_MSTAR
IF_P_MSTAR
1. should be guarded by ground
2. No via on both of them
3. Signal Width >= 12mils
Signal to Signal Width = 12mils
Ground Width >= 24mils

R3704 0 HALF_NIM
IF_AGC_MAIN
should be guarded by ground

+3.3V_TU
R3742 4.7K FULL_NIM
R3744 4.7K FULL_NIM
C3712 22pF 50V FULL_NIM
C3714 22pF 50V FULL_NIM

DEMOD_SCL
DEMOD_SDA

FULL_NIM R3724 0 FE_TS_SYNC
FULL_NIM R3730 0 FE_TS_VAL_ERR
FULL_NIM R3731 0 FE_TS_CLK
FULL_NIM_CHINA R3725 0 FE_TS_DATA[0]
FULL_NIM R3727 0 FE_TS_DATA[1]
FULL_NIM R3728 0 FE_TS_DATA[2]
FULL_NIM R3729 0 FE_TS_DATA[3]
FULL_NIM R3726 0 FE_TS_DATA[4]
FULL_NIM R3721 0 FE_TS_DATA[5]
FULL_NIM R3722 0 FE_TS_DATA[6]
FULL_NIM_CHINA R3723 0 FE_TS_DATA[7]
Close to the CI Slot

R3706 0 FULL_NIM_BR

+5V_TU
BOOSTER : CHINA OPT
L3701 BOOSTER_OPT BLM18PG121SN1D
R3734 BOOSTER_OPT 0
R3743 BOOSTER_OPT 10K
Q3701 ISA1530AC1 BOOSTER_OPT
R3737 2.2K
Q3702 2SC3052 BOOSTER_OPT
R3745 BOOSTER_OPT 10K
FE_BOOSTER_CTL
LNA2_CTL
C3709 0.01uF 25V BOOSTER_OPT
BOOSTER_OPT
The pull-up/down of LNA2_CTL is depended on MODLE_OPT_1.
GPIO must be added for FE_BOOSTER_CTL

TU_IIC_NON_ATSC_SANYO
R3740-*1 1K
+3.3V_TU
R3741-*1 1K
TU_IIC_ATSC_SANYO
R3740 1.2K
R3741 1.2K
TU_SCL
TU_SDA

TU_I2C_NON_FILTER
R3735 33 TU_I2C_NON_FILTER
R3736 33 TU_I2C_NON_FILTER
C3713 18pF 50V
C3711 18pF 50V
C3742 20pF 50V
C3743 20pF 50V
TU_I2C_FILTER

C3711-*1 20pF 50V TU_I2C_FILTER
C3713-*1 20pF 50V TU_I2C_FILTER
TU_I2C_FILTER R3735-*1 COIL
TU_I2C_FILTER R3736-*1 COIL

+5V_TU
R3755 470
R3758 0
TU_SIF
R3753 4.7K
Q3705 ISA1530AC1

+5V_TU
R3751 220
R3752 220
TU_CVBS
R3749 0
R3750 1K OPT
Q3703 ISA1530AC1

DEMOD_RESET
This was being applied to the only china demod, so this has to be deleted in both main and ISDB sheet.

HALF_NIM_1.2V_BCD
IC3703
AZ1117BH-ADJTRE1
+3.3V_TU
INPUT
ADJ/GND
OUTPUT
R2 HALF_NIM R3767 10
+1.2V/+1.8V_TU
HALF_NIM R3768 1.2K R1
R3703 150 OPT
IC3703-*1 AP1117EG-13
IN OUT ADJ/GND
HALF_NIM_1.2V_DIODES
Please, check multi Item! 10/12
HALF_NIM R3766 1 1/10W
C3740 0.1uF 16V HALF_NIM
C3741 10uF 10V HALF_NIM

IC3701
AP2132MP-2.5TRG1
+5V_TU
FULL_NIM_BCD
R3771 10K FULL_NIM_BCD
R3770 10K FULL_NIM_SEMTEK
R3769 10K FULL_NIM_BCD
PG EN VIN VCTRL GND ADJ VOUT NC
THERMAL PAD 9
+1.2V/+1.8V_TU
380mA
R3748-*1 10K
FULL_NIM_SEMTEK
R3748 5.1K R1
R3747 9.1K 1005 R2
Vo=0.8*(1+R1/R2)
R3764 0 1/10W FULL_NIM
C3729 0.1uF 16V FULL_NIM
C3730 10uF 10V FULL_NIM
C3717 0.1uF 16V
+5V_Normal
FULL_NIM_BCD L3704

IC3701-*1
SC4215ISTRT
NC_1 FULL_NIM_SEMTEK EN VIN NC_2 GND ADJ VO NC_3

TUNER MULTI-OPTION
TU3702-*1 TDVJ-H101F
TU3702-*3 UDA5SAL
TU3702-*2 TDTR-T036F
TU3702-*4 TDTJ-S101D
GP2R_AU_2INPUT_H_LGIT
NTSC_2INPUT_H_LGIT

TU3701-*2 TDFR-B035F
TU3701-*4 TDFR-C236D

+5V_TUNER
+5V_TU
200mA
Size change L3702
MLB-201209-0120P-N2
C3719 22uF 10V
C3724 0.1uF 16V
C3722 22uF 16V
C3726 0.1uF 16V
location movement,0929
+3.3V_TU
60mA
Size change L3703
MLB-201209-0120P-N2
+3.3V_Normal
C3723 22uF 10V
C3725 0.1uF 16V
C3715 22uF 16V
C3727 0.1uF 16V
Add,0929

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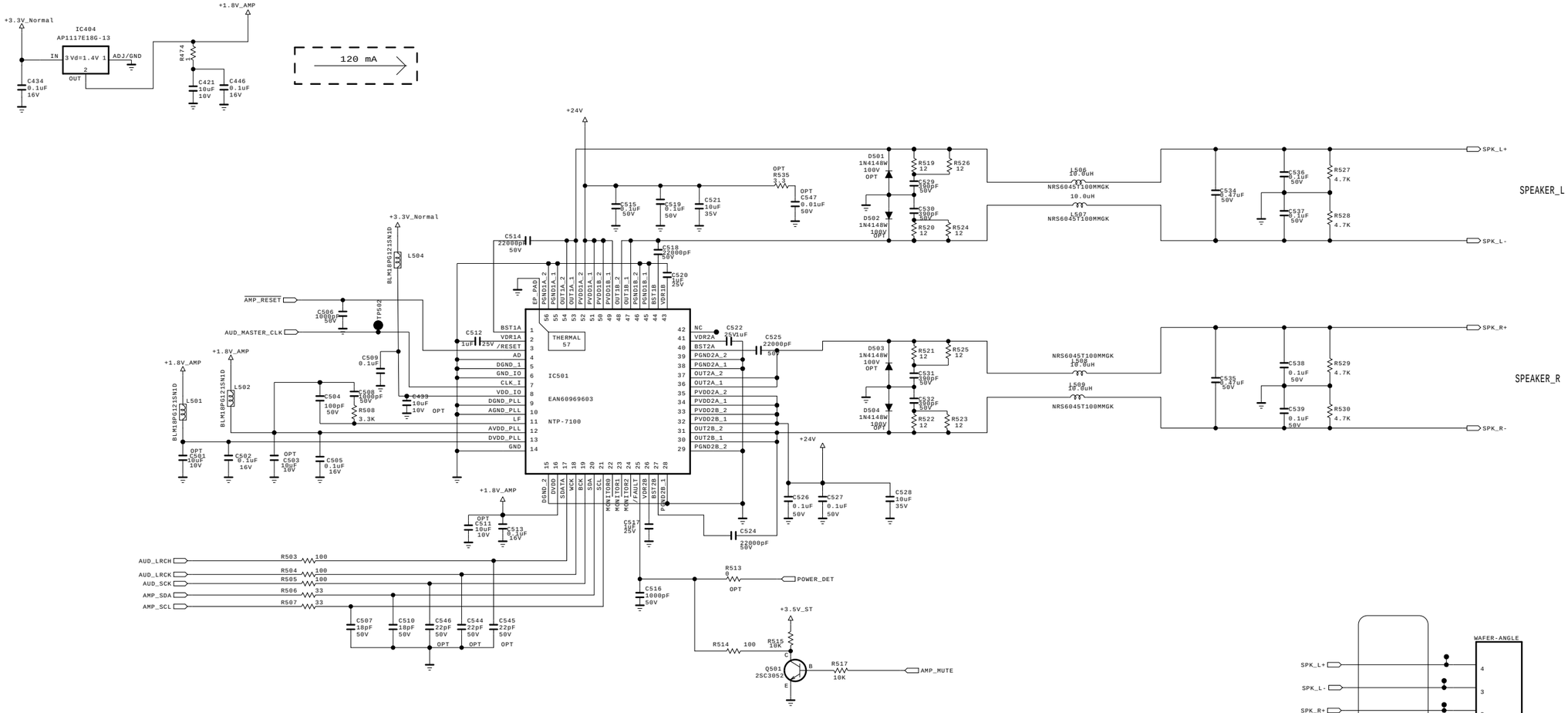
SECRET
LGElectronics

LG ELECTRONICS

MODEL	GP2R	DATE	20101023
BLOCK	TUNER_L	SHEET	14



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SECRET

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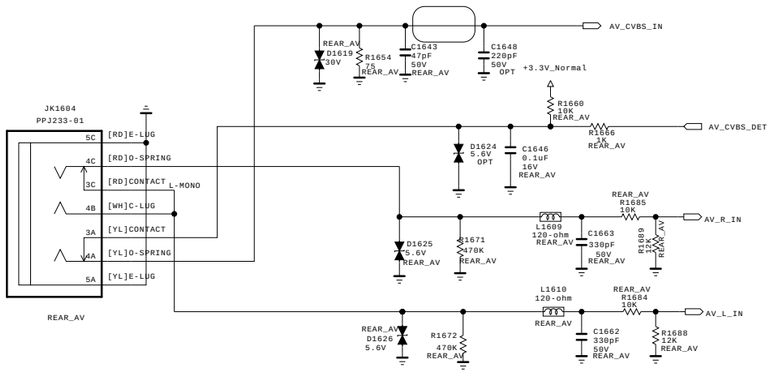
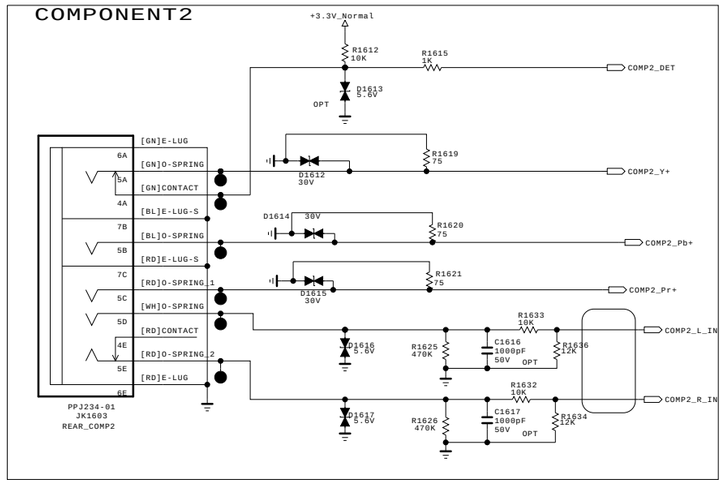
LG ELECTRONICS

MODEL	GP2R	DATE	20101023
BLOCK	AMP_NTP	SHEET	16 /

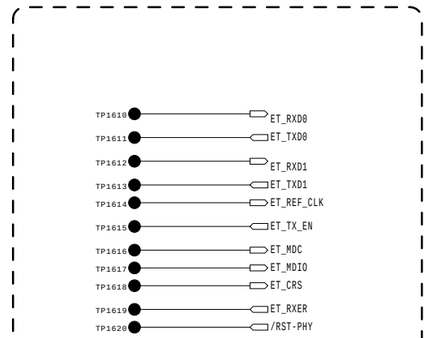
Rear AV



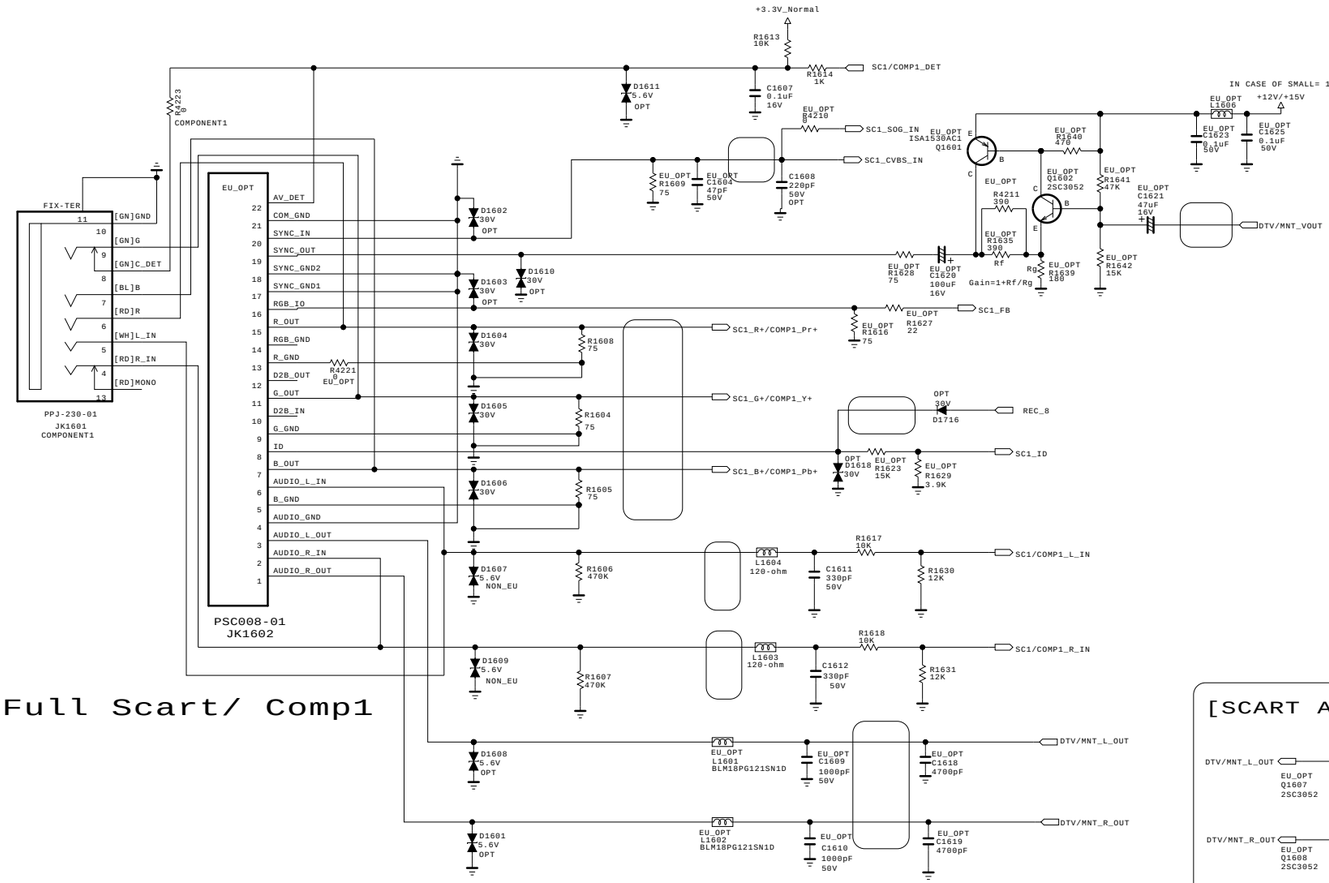
COMPONENT2



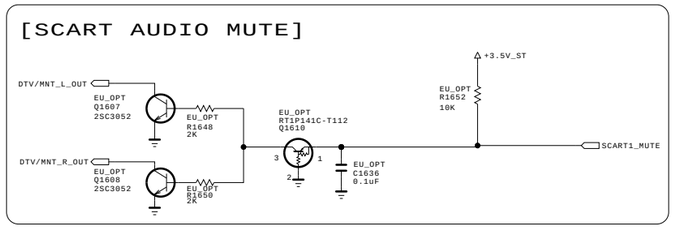
ETHERNET FOR DVB_T2

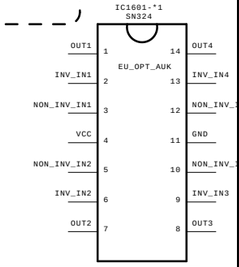


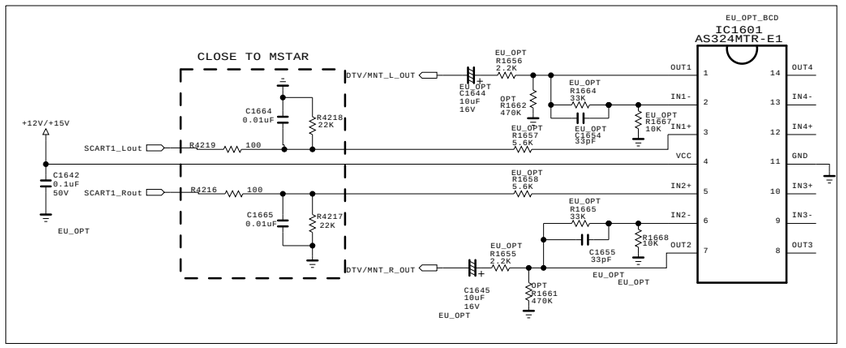
Full Scart/ Comp1



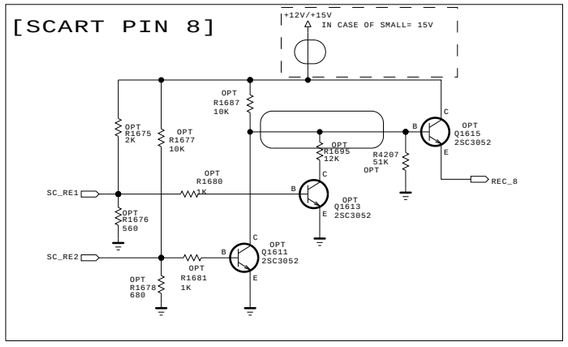
[SCART AUDIO MUTE]







[SCART PIN 8]



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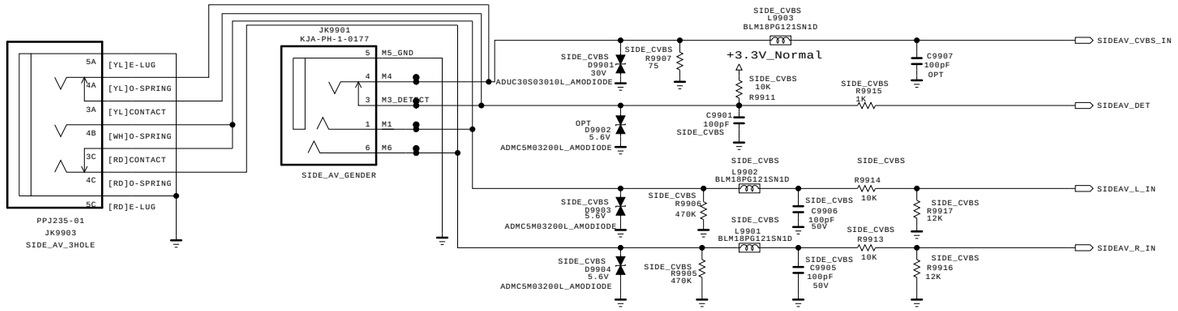
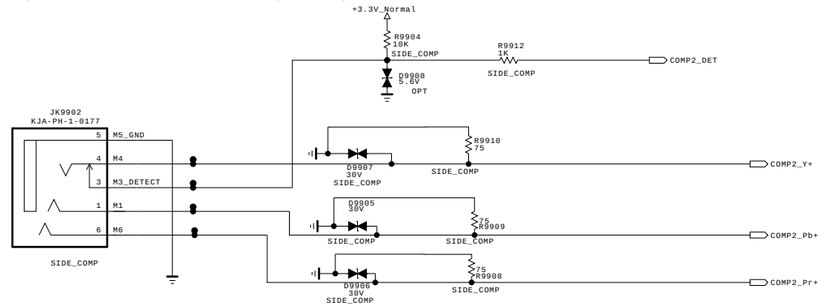
LG ELECTRONICS

MODEL	GP2R	DATE	20101023
BLOCK	REAR_JACK	SHEET	17 /

SIDE CVBS PHONE JACK
(New Item Development)



SIDE COMPONENT PHONE JACK
(New Item Developmen)



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LG ELECTRONICS

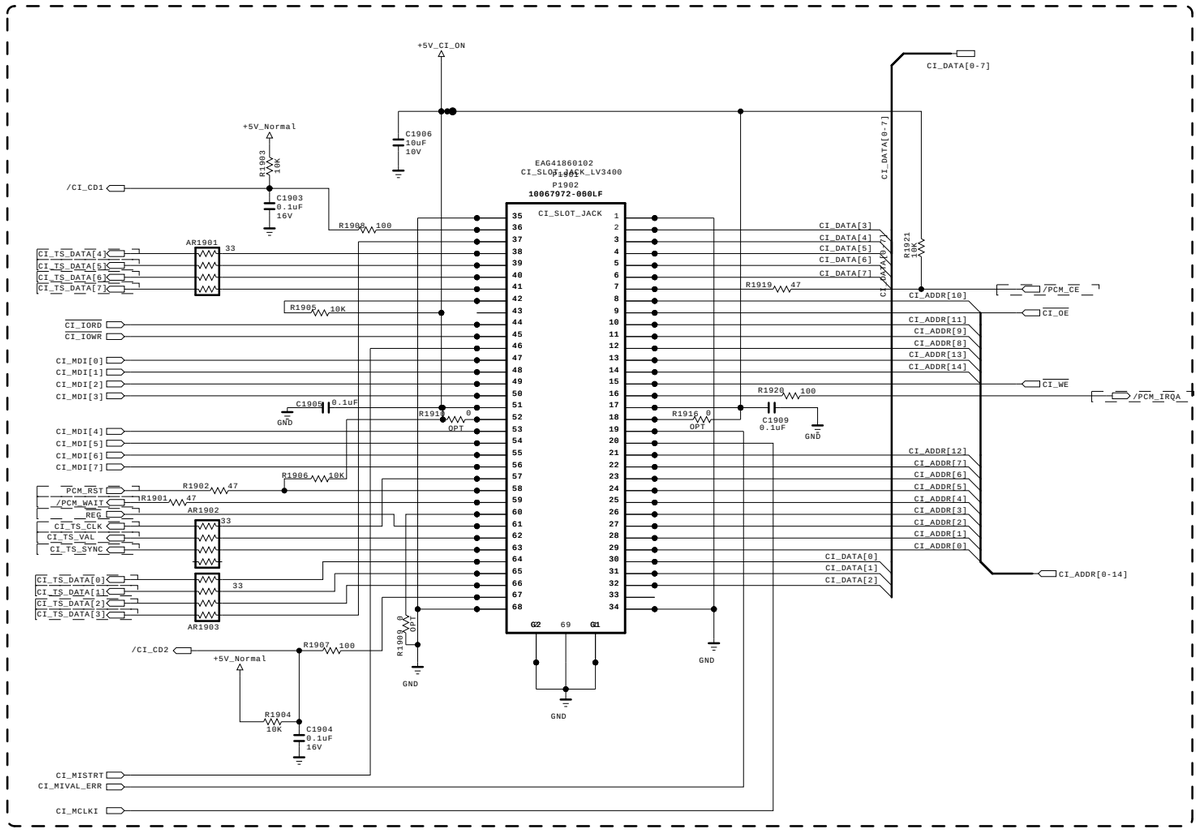
MODEL	GP2R	DATE	20101023
BLOCK	SIDE_JACK	SHEET	18 /

LGE Internal Use Only

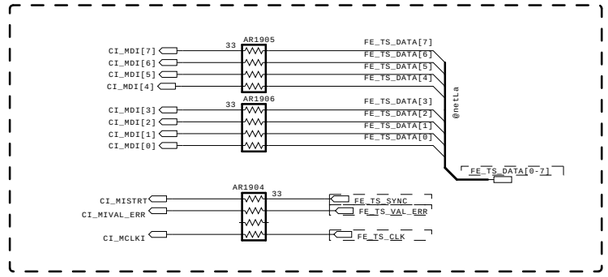
CI Region

* Option name of this page : CI_SLOT
(because of Hong Kong)

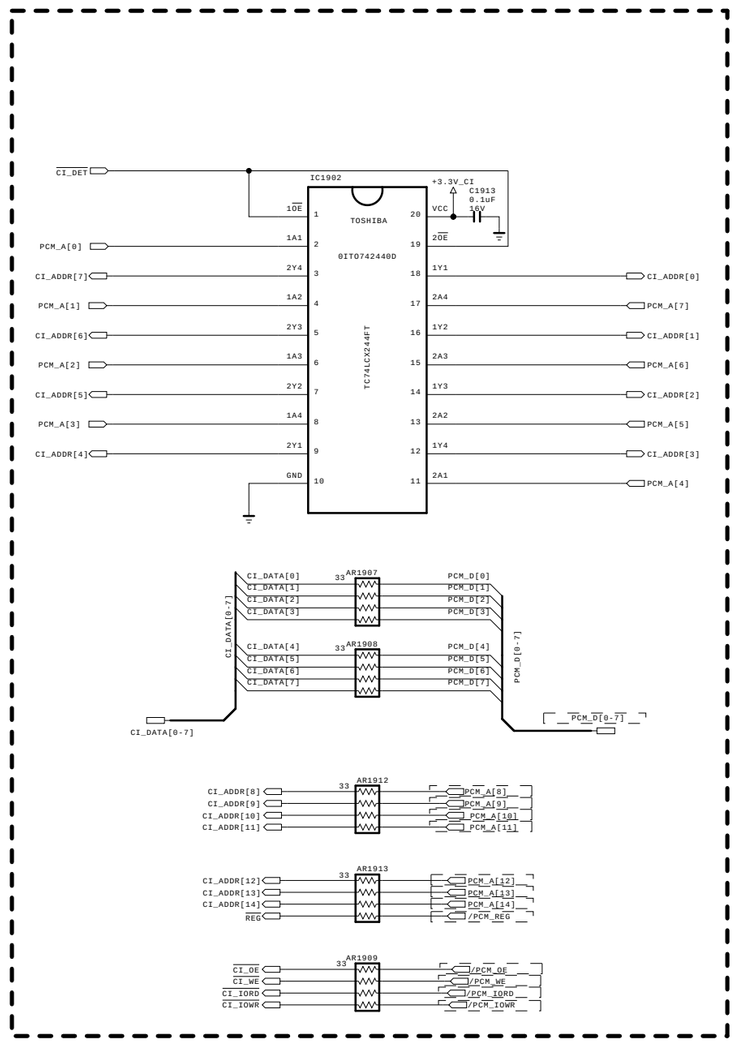
CI SLOT

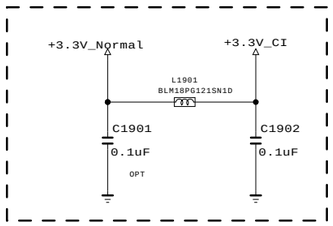


CI TS INPUT

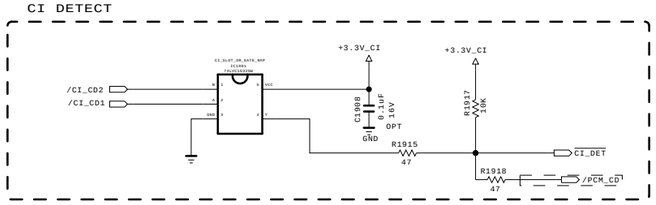


CI HOST I/F

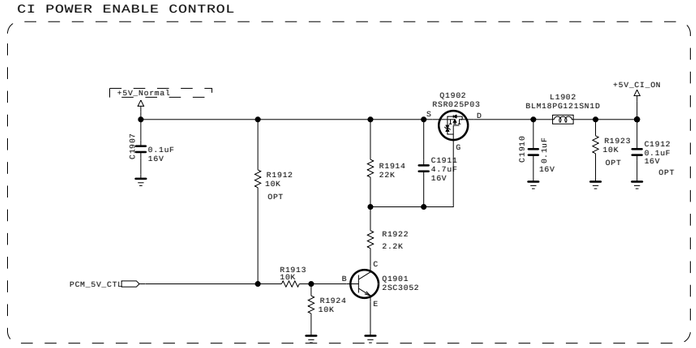




CI DETECT



CI POWER ENABLE CONTROL



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SECRET
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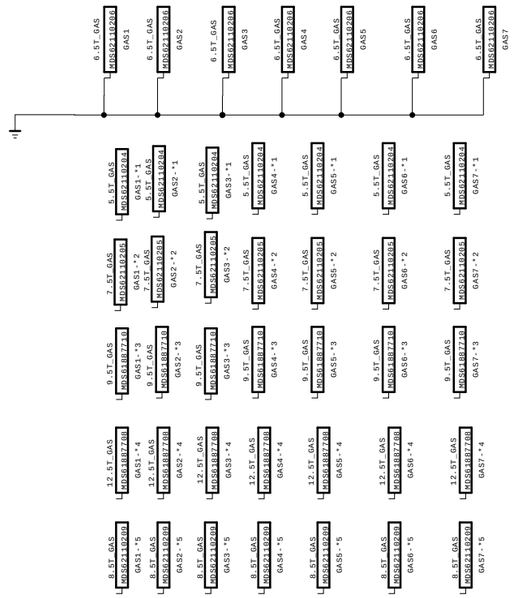
LG ELECTRONICS

MODEL	GP2R	DATE	20101023
BLOCK	PCMCI	SHEET	20 /

SMD GASKET



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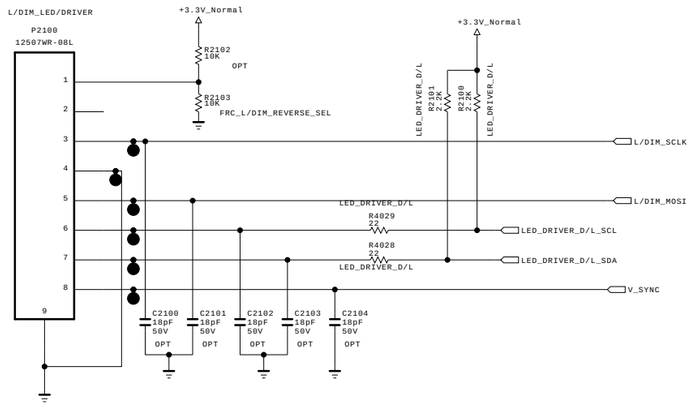
LG ELECTRONICS

MODEL	GP2R	DATE	20101023
BLOCK	SMD_GAS	SHEET	20 /



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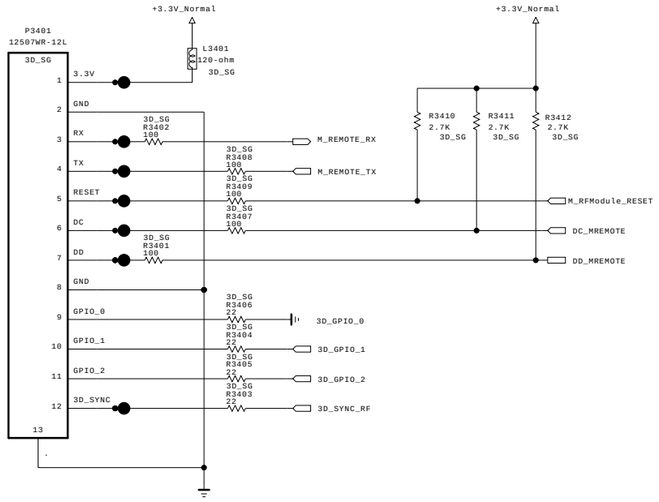
LG ELECTRONICS

MODEL	GP2R	DATE	20101023
BLOCK	L/DIM_LED	SHEET	21 /

TI solution RF-3D OPTION



ALL 3D-SG OPTION

FREQ.	GPOIO_0	GPOIO_1	GPOIO_2
3D Off	0	0	0
60Hz	0	0	1
59.94Hz	0	1	0
50Hz	0	1	1
RESERVED	1	0	0
RESERVED	1	0	1
RESERVED	1	1	0
RESERVED	1	1	1

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LG ELECTRONICS

MODEL		DATE	
BLOCK		SHEET	/

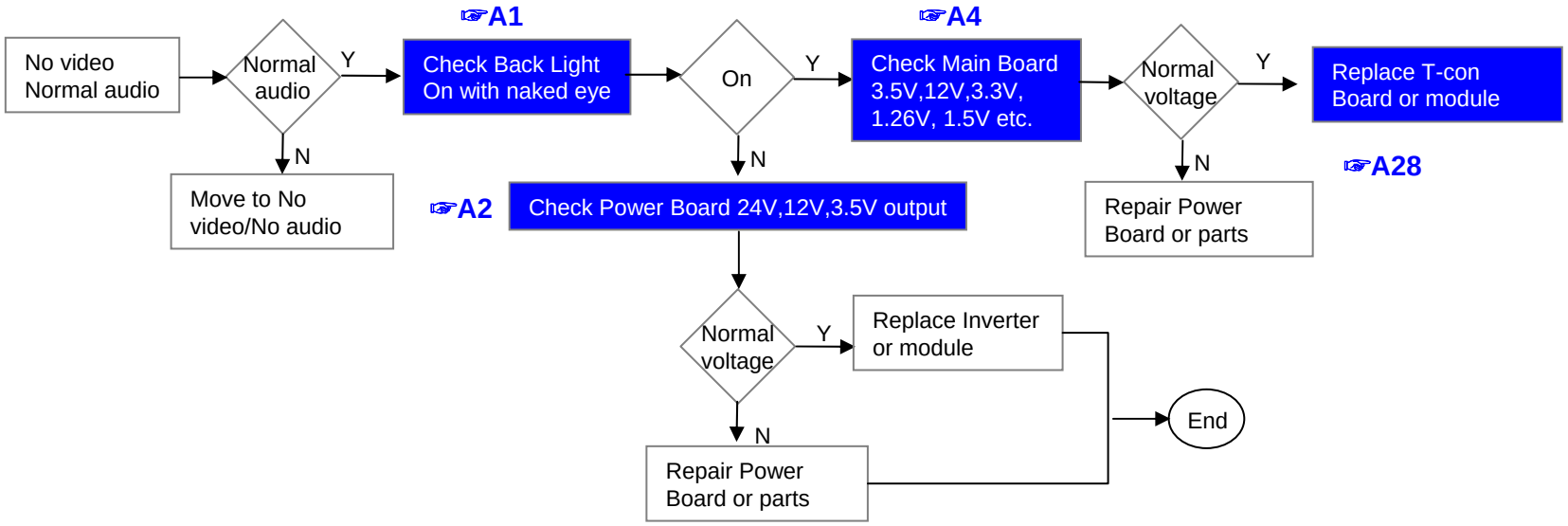

LG
Life's Good

1. Trouble Shooting

Contents of LCD TV Standard Repair Process

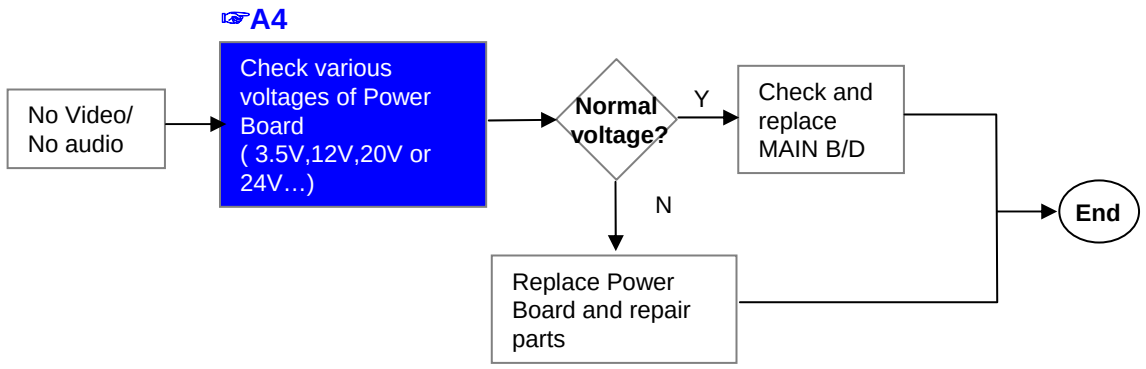
LCD TV	Error symptom	A. Video error	Established date		
		No video/ Normal audio	Revised date		1/13

First of all, Check whether all of cables between board is inserted properly or not.
(Main B/D↔ Power B/D, LVDS Cable,Speaker Cable,IR B/D Cable,,,)

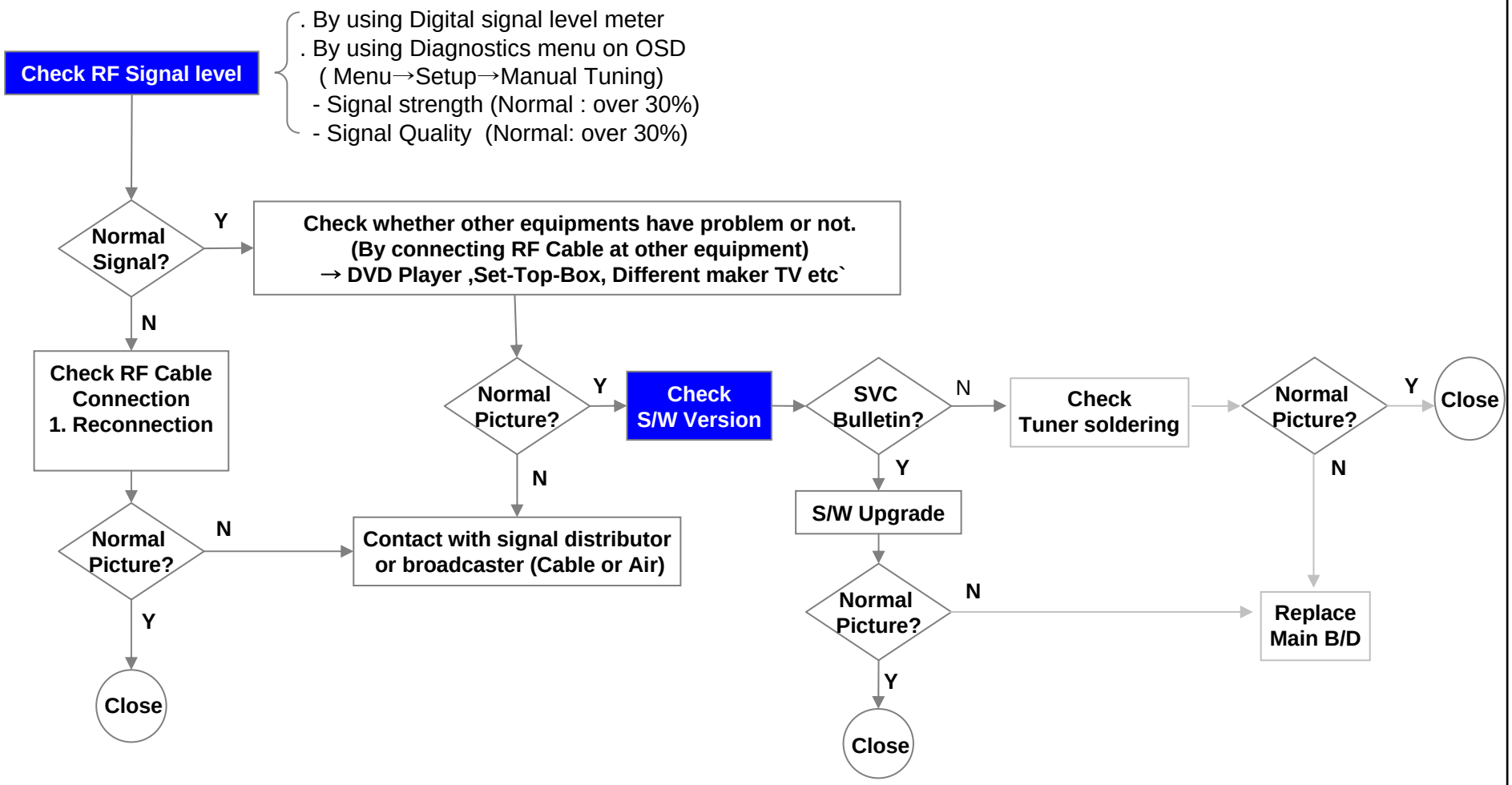


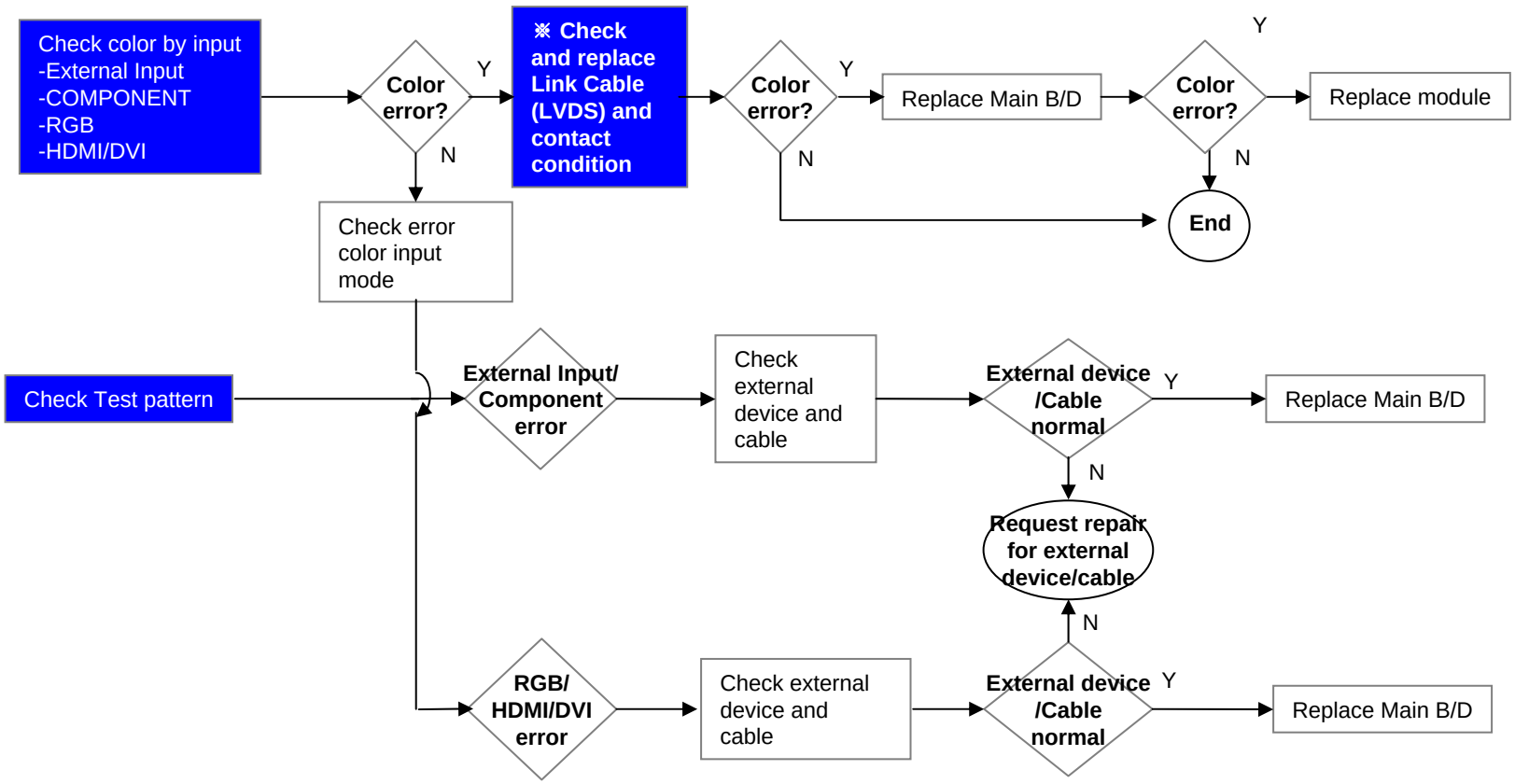
※Precaution ☞A7 & A3

LCD TV	Error symptom	A. Video error	Established date		
		No video/ No audio	Revised date		2/13



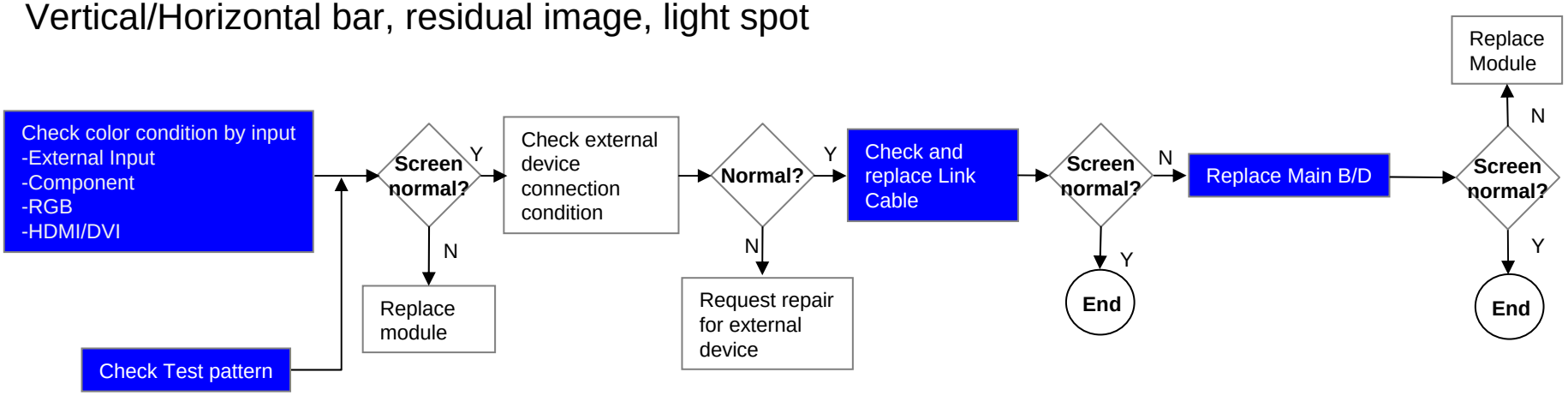
LCD TV	Error symptom	A. Picture Problem	Established date		
		Picture broken/ Freezing	Revised date		3/13



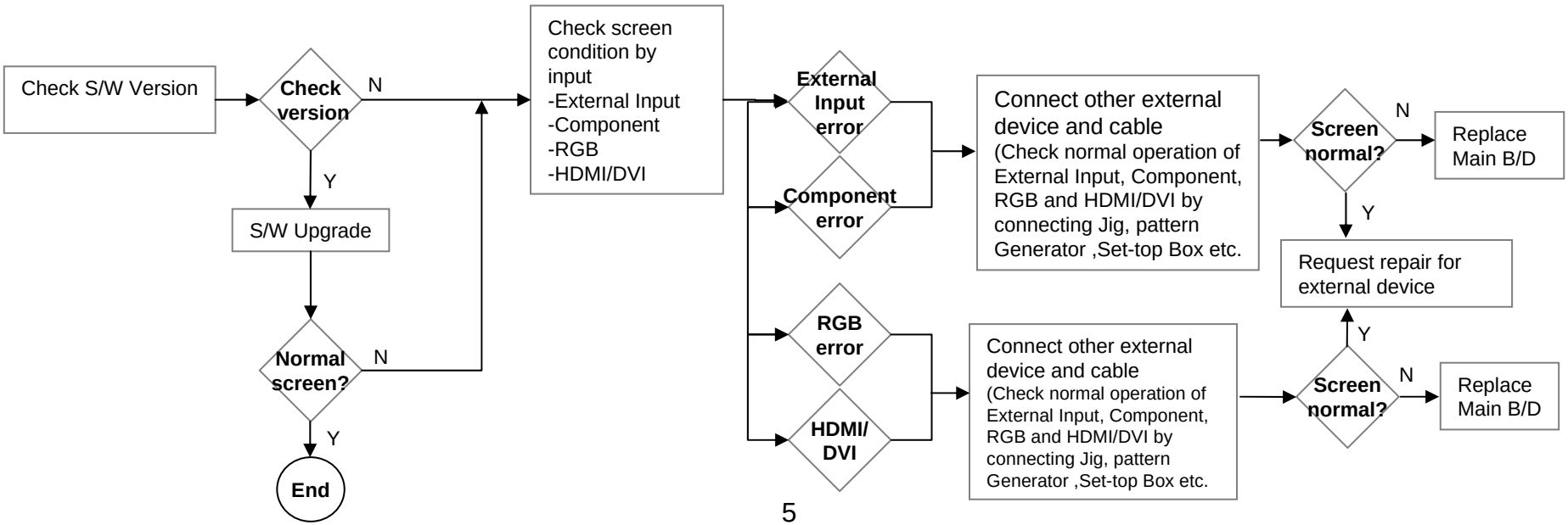


LCD TV	Error symptom	A. Video error	Established date		
		Vertical / Horizontal bar, residual image, light spot, external device color error	Revised date		5/13

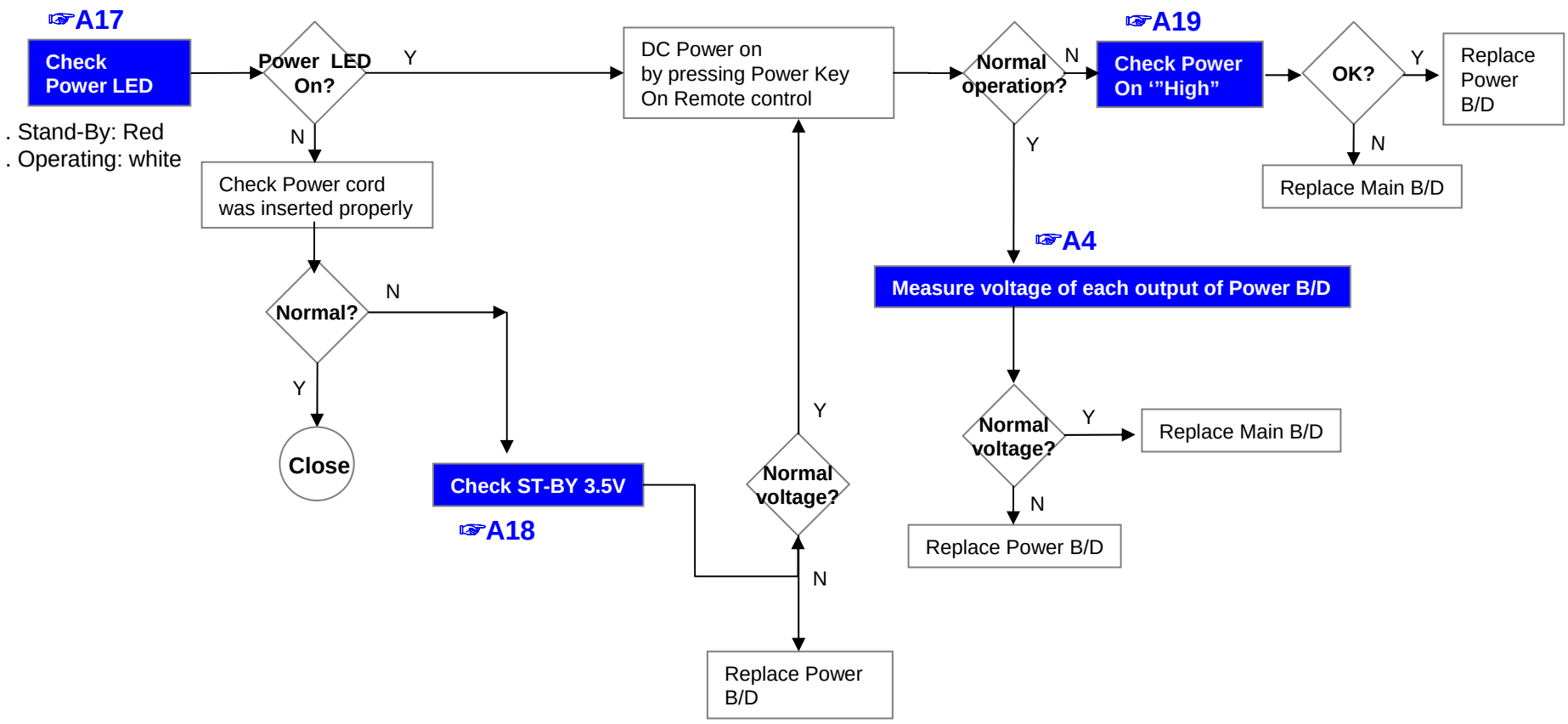
Vertical/Horizontal bar, residual image, light spot



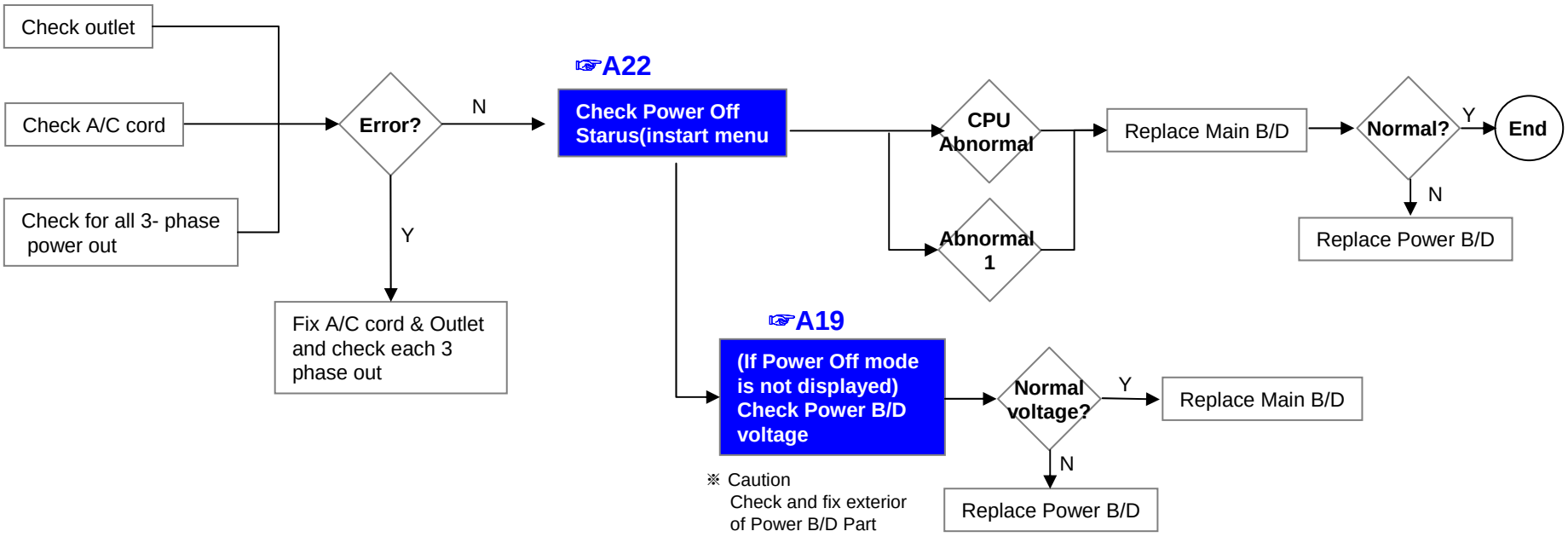
External device screen error-Color error



LCD TV	Error symptom	B. Power error	Established date		
		No power	Revised date		6/13



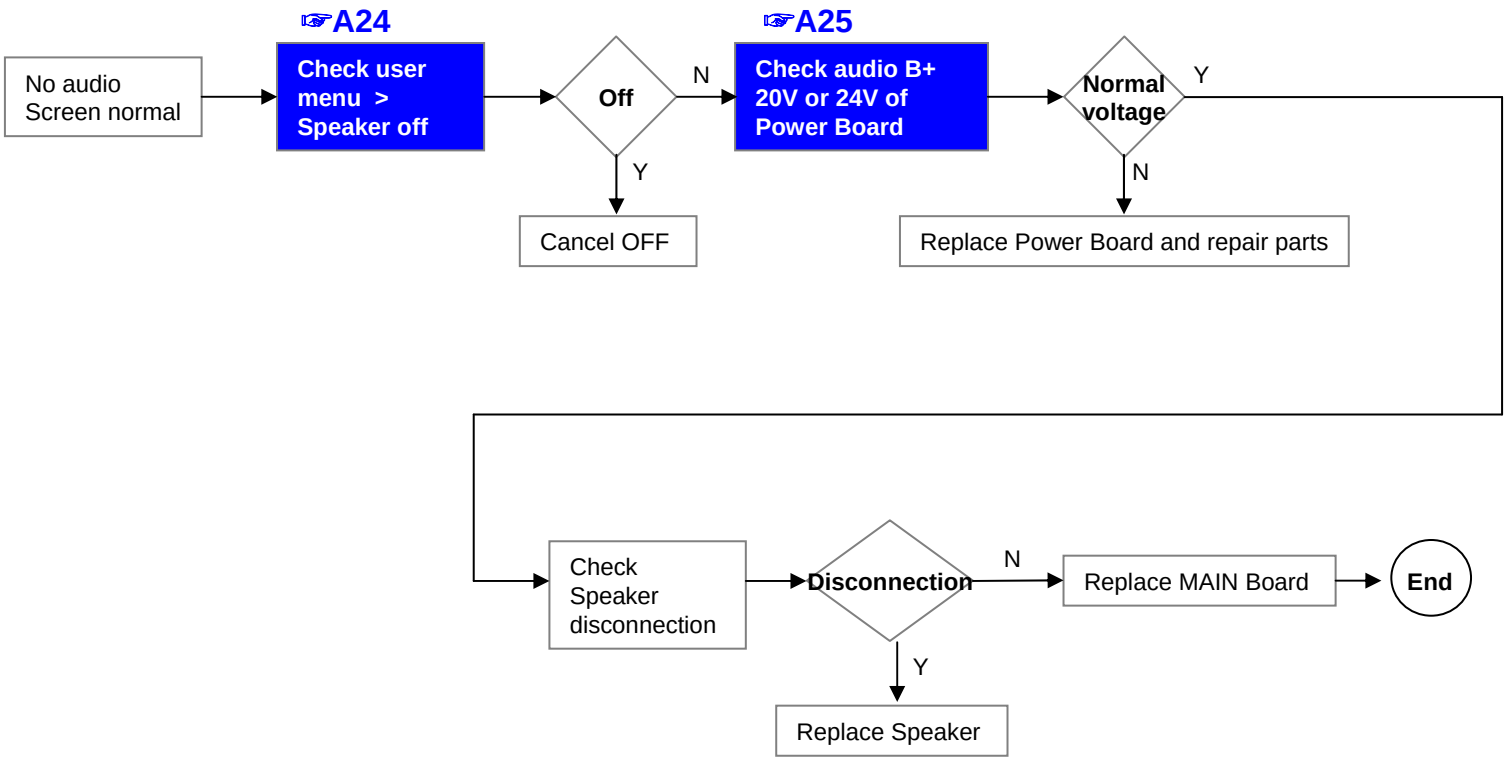
LCD TV	Error symptom	B. Power error	Established date		
		Off when on, off while viewing, power auto on/off	Revised date		7/13



*** Please refer to the all cases which can be displayed on power off mode.**

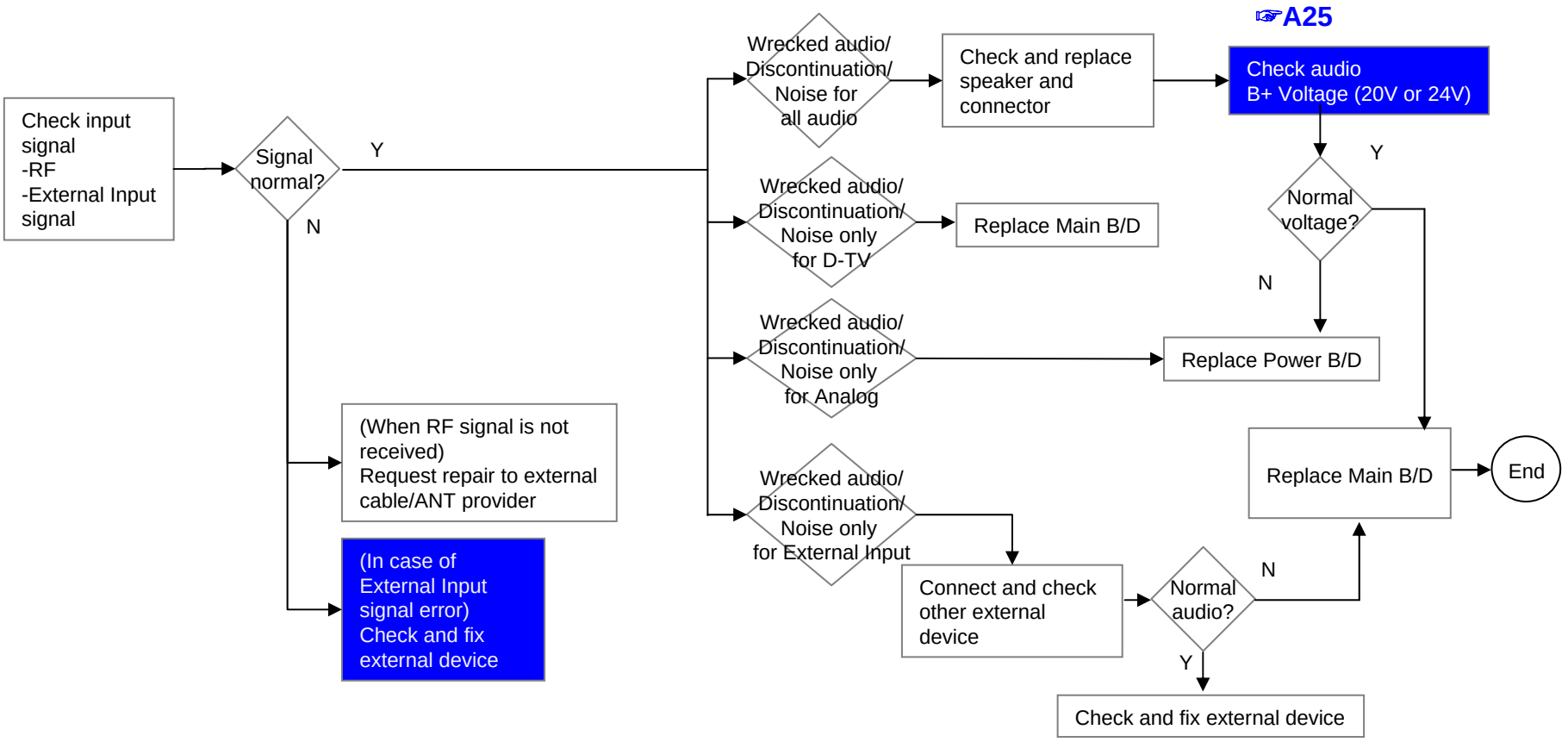
Status	Power off List	Explanation
Normal	"POWEROFF_REMOTEKEY"	Power off by REMOTE CONTROL
	"POWEROFF_OFFTIMER"	Power off by OFF TIMER
	"POWEROFF_SLEEPTIMER"	Power off by SLEEP TIMER
	"POWEROFF_INSTOP"	Power off by INSTOP KEY
	"POWEROFF_AUTOOFF"	Power off by AUTO OFF
	"POWEROFF_ONTIMER"	Power off by ON TIMER
	"POWEROFF_RS232C"	Power off by RS232C
	"POWEROFF_RESREC"	Power off by Reservated Record
	"POWEROFF_RECEND"	Power off by End of Recording
	"POWEROFF_SWDOWN"	Power off by S/W Download
	"POWEROFF_UNKNOWN"	Power off by unknown status except listed case
Abnormal	"POWEROFF_ABNORMAL1"	Power off by abnormal status except CPU trouble
	"POWEROFF_CPUABNORMAL"	Power off by CPU Abnormal

LCD TV	Error symptom	C. Audio error	Established date		
		No audio/ Normal video	Revised date		8/13



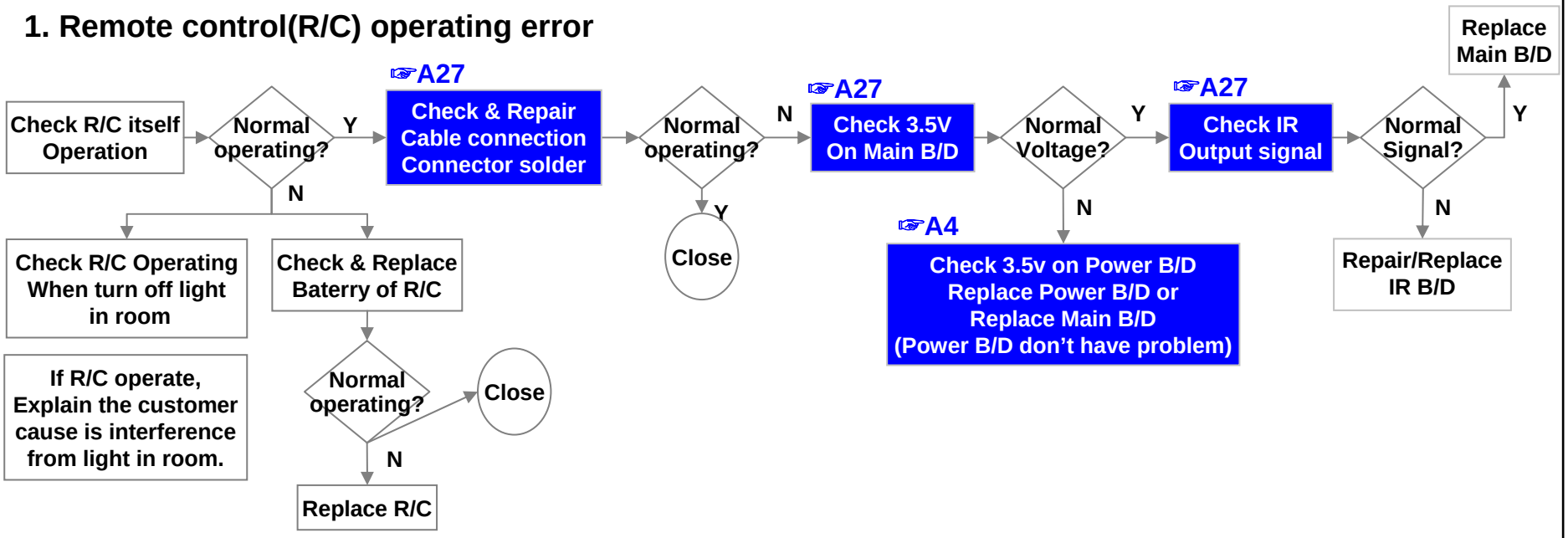
LCD TV	Error symptom	C. Audio error	Established date		
		Wrecked audio/ discontinuation/noise	Revised date		9/13

→ abnormal audio/discontinuation/noise is same after “Check input signal” compared to No audio

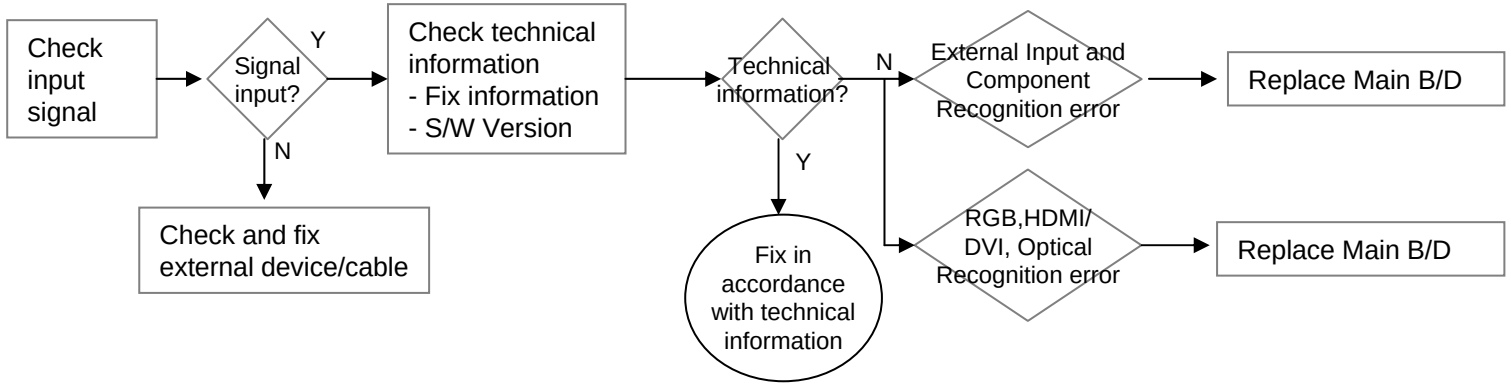


LCD TV	Error symptom	D. General Function Problem	Established date		
		Remote control & Local switch checking	Revised date		10/13

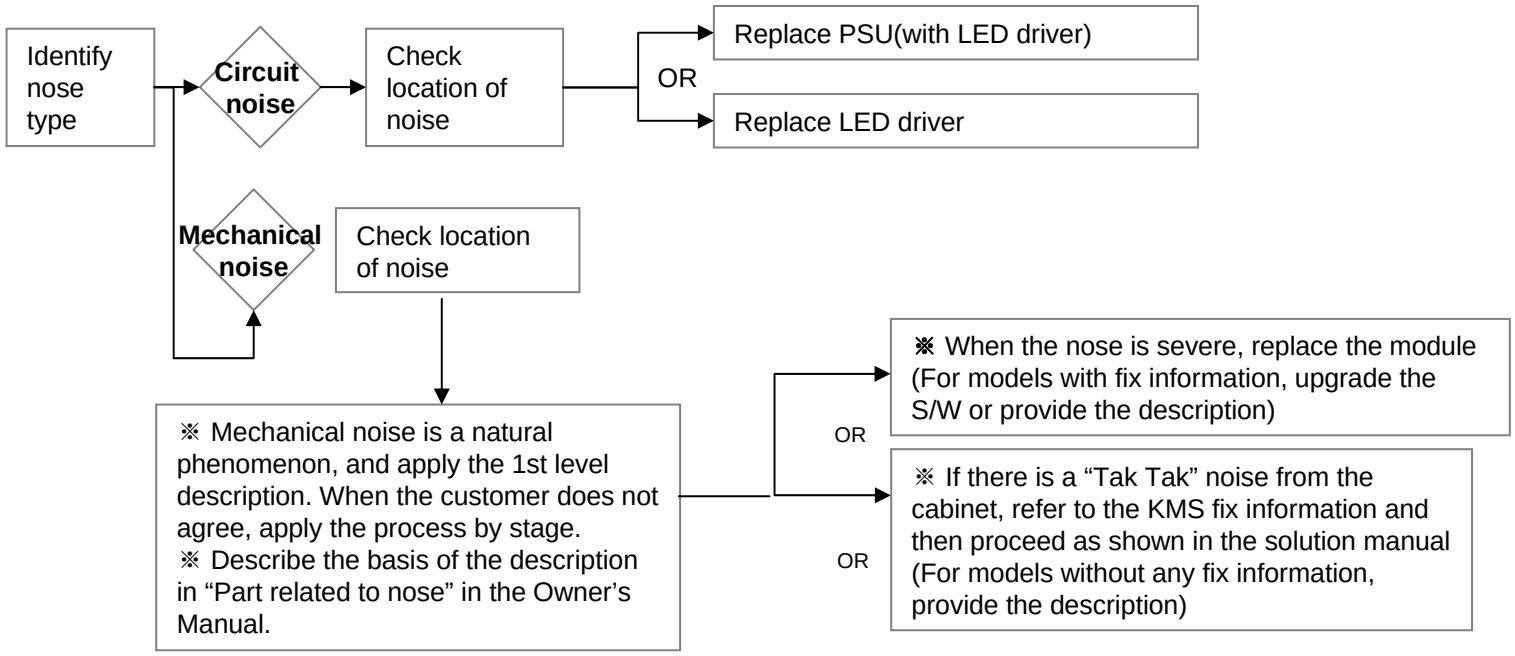
1. Remote control(R/C) operating error



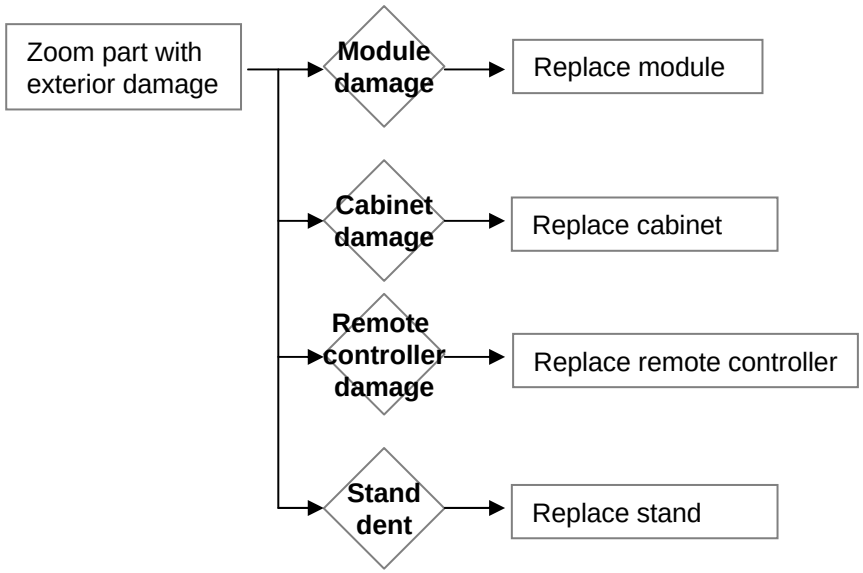
LCD TV	Error symptom	D. Function error	Established date		
		External device recognition error	Revised date		11/13



LCD TV	Error symptom	E. Noise	Established date		
		Circuit noise, mechanical noise	Revised date		12/13



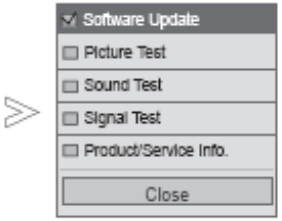
LCD TV	Error symptom	F. Exterior defect	Established date		
		Exterior defect	Revised date		13/13



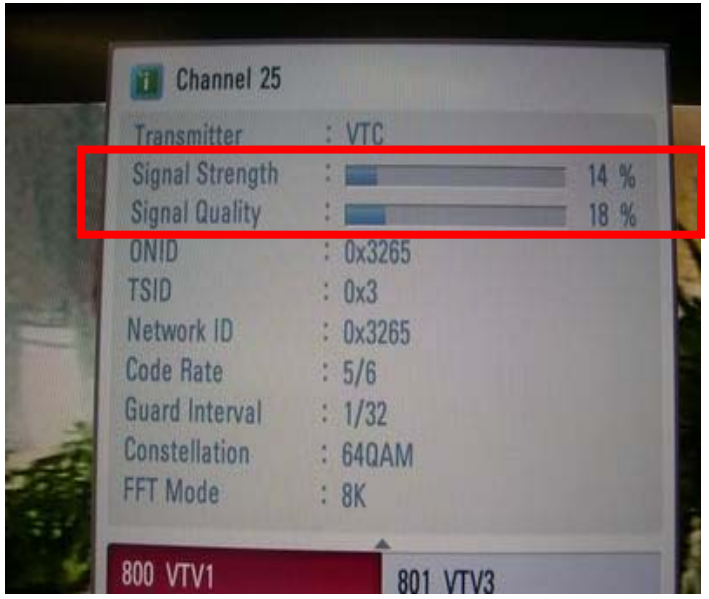
Standard Repair Process Detail Technical Manual

LCD TV	Error symptom	A. Video error_Video error, video lag/stop	Established date		
	Content	TUNER input signal strength checking method	Revised date		A6

<ALL MODELS>



MENU -→ red key(customer support -→ signal test -→ select channel



When the signal is strong, use the attenuator (-10dB, -15dB, -20dB etc.)

Standard Repair Process Detail Technical Manual

LCD TV	Error symptom	A. Video error_Video error, video lag/stop	Established date		
	Content	LCD-TV Version checking method	Revised date		A7

<ALL MODELS>

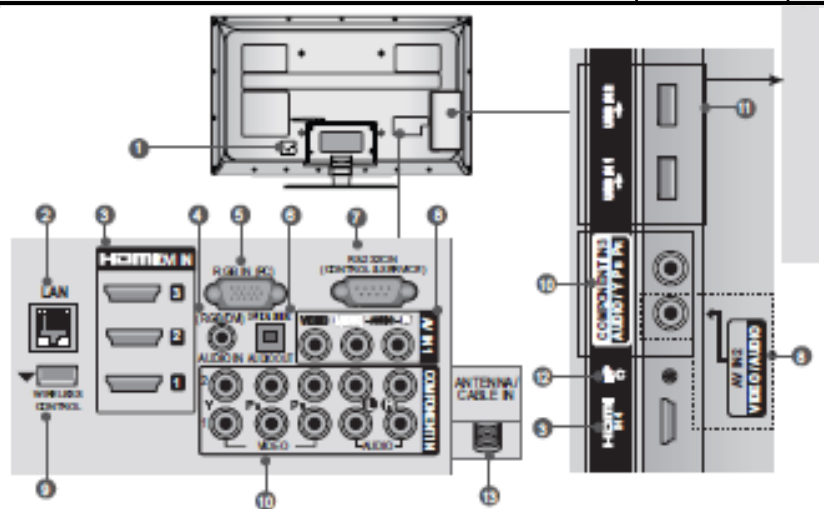
1. Checking method for remote controller for adjustment

Version

Press the IN-START with the remote controller for adjustment

Standard Repair Process Detail Technical Manual

LCD TV	Error symptom	A. Video error _Vertical/Horizontal bar, residual image, light spot	Established date		
	Content	LCD TV connection diagram (1)	Revised date		A8



❶ Power Cord Socket
This TV operates on an AC power. The voltage is indicated on the Specifications page. Never attempt to operate the TV on DC power.

❷ LAN
Network connection for Weather info, Photo Album, Movie Online, etc.
Also used for video, photo and music files on a local network.

❸ HDMI/DVI IN Input
Connect an HDMI signal to HDMI IN. Or DVI (VIDEO) signal to HDMI/DVI port with DVI to HDMI cable.

❹ RGB/DVI Audio Input
Connect the audio from a PC or DTV.

❺ RGB IN Input
Connect the output from a PC.

❻ OPTICAL DIGITAL AUDIO OUT
Connect digital audio to various types of equipment.
Connect to a Digital Audio Component.
Use an Optical audio cable.

❼ RS-232C IN (CONTROL & SERVICE) PORT
Connect to the RS-232C port on a PC.
This port is used for Service or Hotel mode.

❽ Audio/Video Input
Connect audio/video output from an external device to these jacks.

❾ WIRELESS Control
Connect the Wireless Dongle to the TV to control the external input devices connected to Media Box wirelessly.

❿ Component Input
Connect a component video/audio device to these jacks.

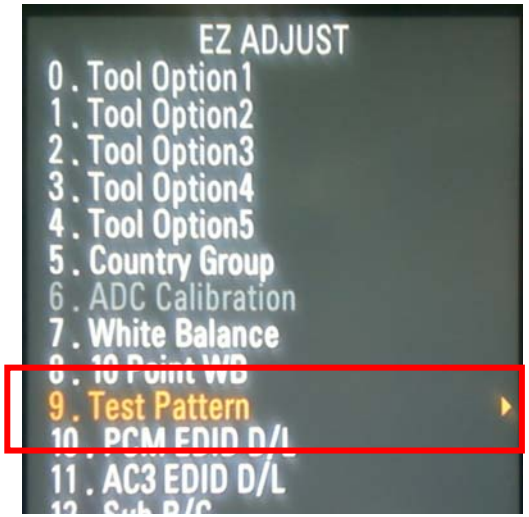
⓫ USB Input
Connect USB storage device to this jack.

⓬ Headphone Socket
Plug the headphone into the headphone socket.

⓭ Antenna / Cable Input
Connect antenna or cable to this jack.

Standard Repair Process Detail Technical Manual

LCD TV	Error symptom	A. Video error_Color error	Established date		
	Content	Adjustment Test pattern - ADJ Key	Revised date		A12

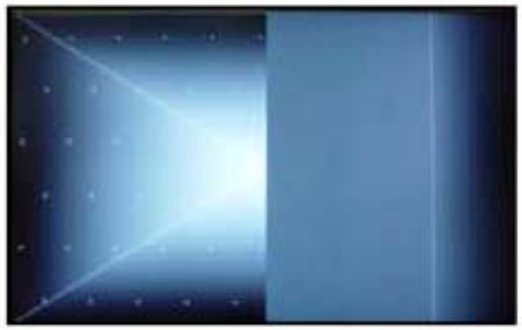


You can view 6 types of patterns using the ADJ Key

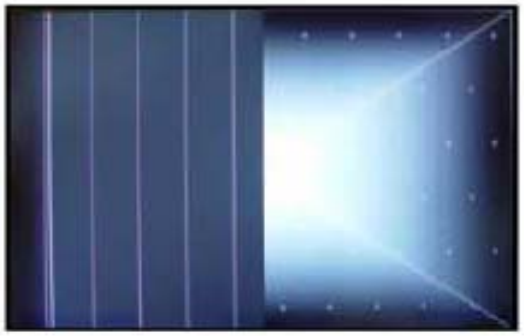
Checking item : 1. Defective pixel 2. Residual image 3. MODULE error (ADD-BAR,SCAN BAR..)
4.Video error (Classification of MODULE or Main-B/D!)

Appendix : Exchange T-Con Board (1)

Solder defect, CNT Broken

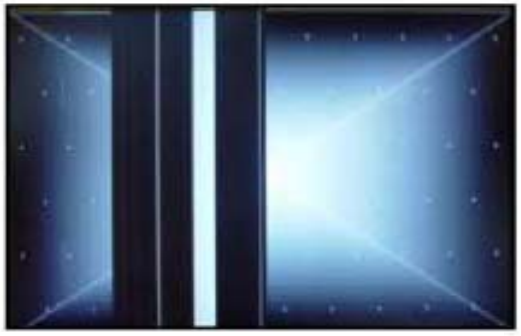


Solder defect, CNT Broken

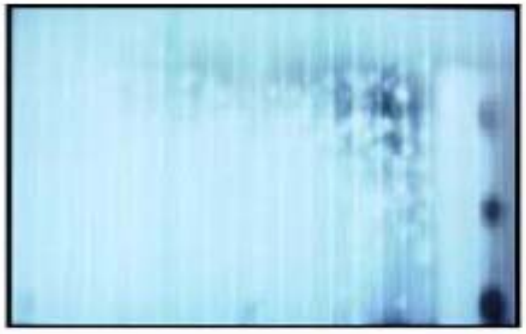


Solder defect, CNT Broken

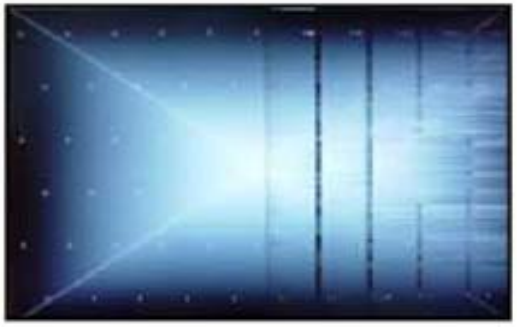
Solder defect, CNT Broken



Solder defect, CNT Broken



Abnormal Power Section

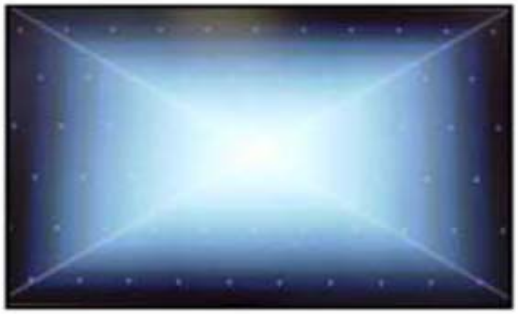


Solder defect, Short/Crack

Abnormal Power Section

Solder defect, Short/Crack

Appendix : Exchange T-Con Board (2)



Abnormal Power Section

Abnormal Power Section

Solder defect, Short/Crack

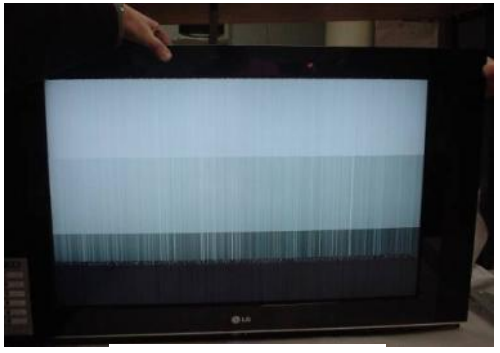
Solder defect, Short/Crack

Fuse Open, Abnormal power section

Abnormal Display

GRADATION

Noise



GRADATION

Appendix : Exchange PSU(LED driver)

No Light

Dim Light

Dim Light

Dim Light

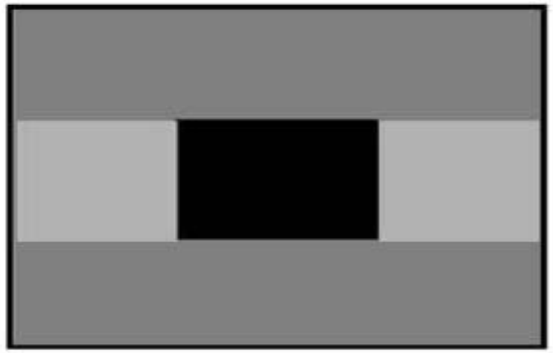
No picture/Sound Ok

Appendix : Exchange the Module (1)

Panel Mura, Light leakage

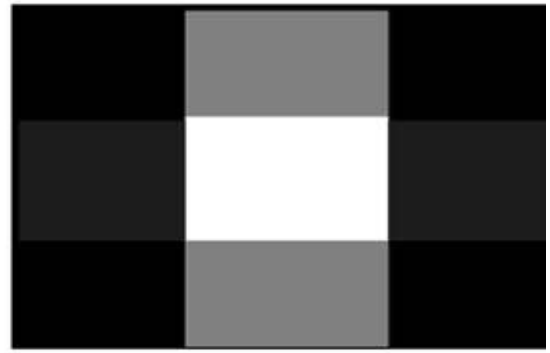
Panel Mura, Light leakage

Press damage



Crosstalk

Press damage



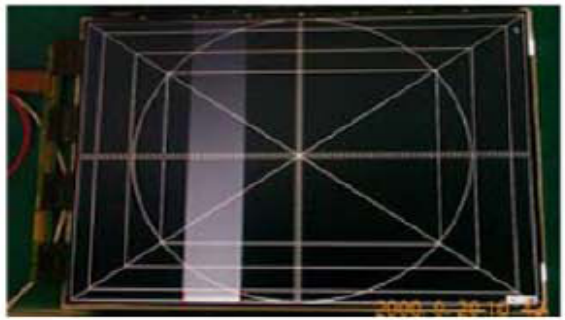
Crosstalk

Press damage

Un-repairable Cases

In this case please exchange the module.

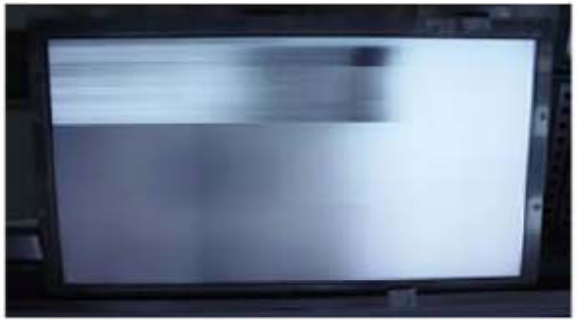
Appendix : Exchange the Module (2)



Vertical Block
Source TAB IC Defect

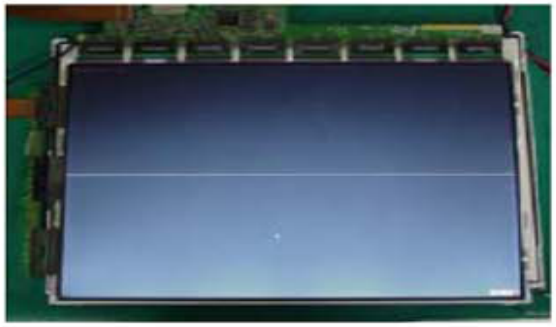
Vertical Line
Source TAB IC Defect

Vertical Block
Source TAB IC Defect



Horizontal Block
Gate TAB IC Defect

Horizontal Block
Gate TAB IC Defect



Horizontal line
Gate TAB IC Defect

Horizontal Block
Gate TAB IC Defect

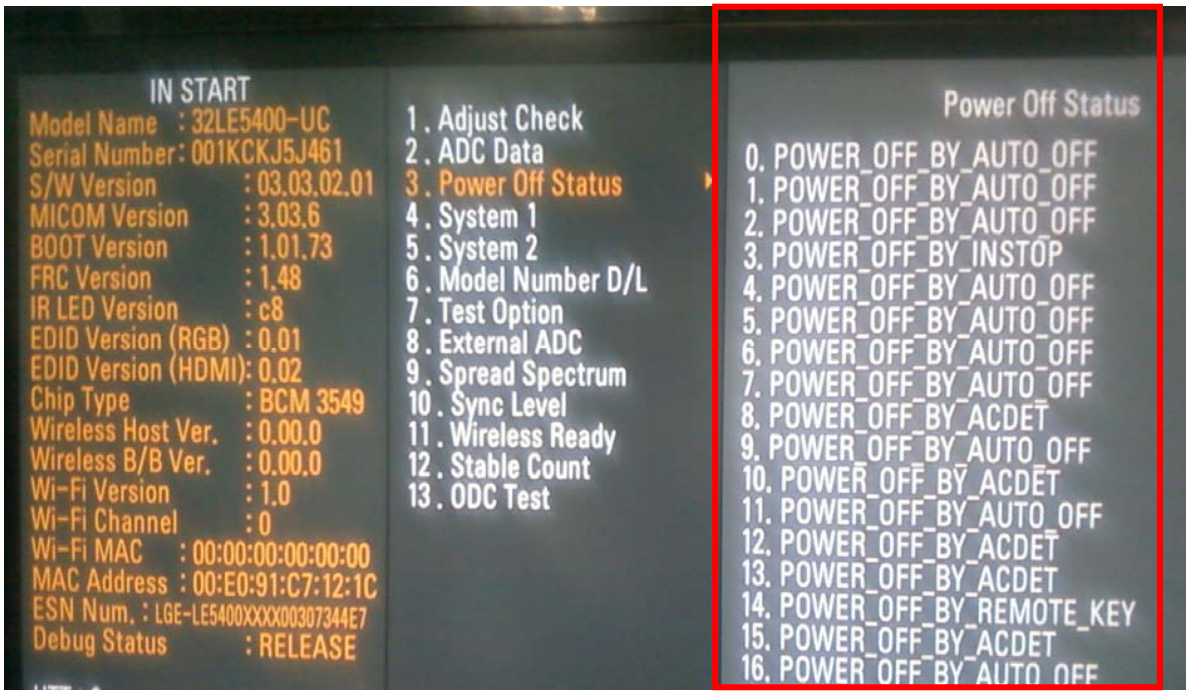
Un-repairable Cases

In this case please exchange the module.

Standard Repair Process Detail Technical Manual

LCD TV	Error symptom	B. Power error _Off when on, off whiling viewing	Established date		
	Content	POWER OFF MODE checking method	Revised date		A22

<ALL MODELS>



Entry method

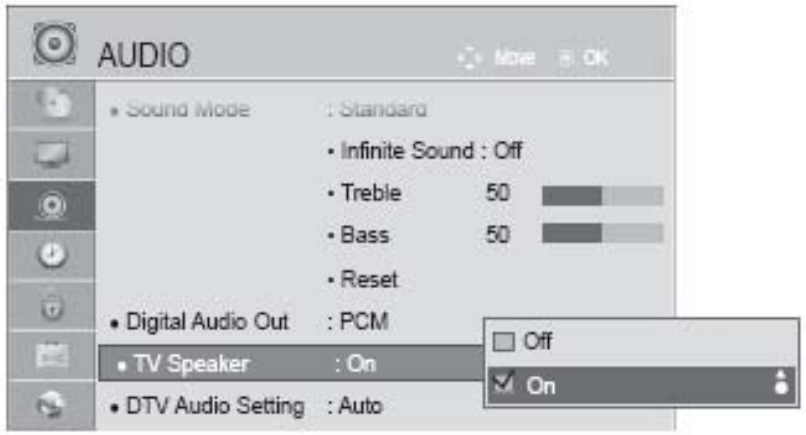
1. Press the IN-START button of the remote controller for adjustment

2. Check the entry into adjustment item 3

Standard Repair Process Detail Technical Manual

LCD TV	Error symptom	C. Audio error_No audio/Normal video	Established date		
	Content	Checking method in menu when there is no audio	Revised date		A24

<ALL MODELS>



Checking method

1. Press the MENU button on the remote controller
2. Select the AUDIO function of the Menu
3. Select TV Speaker from Off to On